



# Classroom

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Rev 7-14-23

## Tech History

### Part 1

### Computers

by

Dr Jeff Drobman

Dr Jeff Software

# Index

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## ❖ Intro

- ☐ CHM, Comm and Fax
- ☐ Titans & Landscape

## ❖ Computers

- ☐ Mainframes
- ☐ Minis
- ☐ PC's
- ☐ HPC & Supers
- ☐ QC\*

## ❖ Computer Architecture

- ☐ Modern CPU (AMD & Intel, ARM, IBM)
- ☐ CPU Performance
- ☐ Parallelism
- ☐ GPU\*

## ❖ Phones \*see slide set on “SoC’s” for phone chips

\*see separate slide sets

# Computer History Museum



<http://www.computerhistory.org/fellowawards/hall/>

Image Gallery



# CHM Timeline

## Decades of Silicon Valley Innovation\*



Tube

1930s - Radio Communications (Litton)

1940s - Defense Systems (Varian)

1950s - Magnetic Storage (IBM)



Transistor

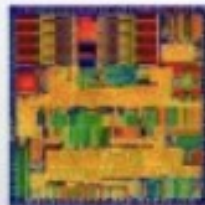
1960s - Semiconductors (Fairchild)

1970s - Personal Computing (Apple)

1980s - Networks (Xerox)

1990s - Internet (Cisco)

2000s - Mobile (Apple)



Microchip

\* in hardware





# Personal Communications

- 1684 ❖ Optical Telegraph (smoke, mirrors)
- 1792 ❖ Semaphores (flags)
- 1837 ❖ Telegraph, Electrical (w/Morse code)
- 1843 ❖ Fax
- 1870 ❖ Telephone
- ❖ Radio (shortwave)
- ❖ TV (broadcast)
- 1969 ❖ CATV (interactive)
- ❖ **Internet**
- ❖ **Email** (1971 private, 1991 public)
- ❖ Teletype (TTY)
- 1989 ❖ FAX
- ❖ **WWW** (Web 1.0 – over the Internet)
- ❖ Cell phones (analog voice + data)
- ❖ Messaging
  - **Texting** (SMS – *thumbing*)
  - **IM**
- 2000 ❖ Web 2.0 (smart apps)
- ❖ Smart phones – OS alerts, **apps**
- ❖ **Social media** websites

Wireline

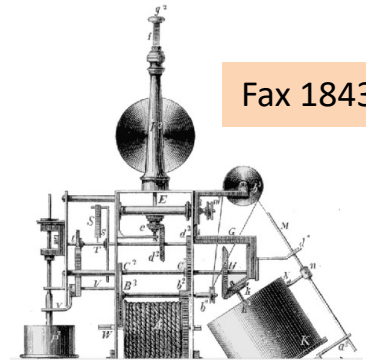
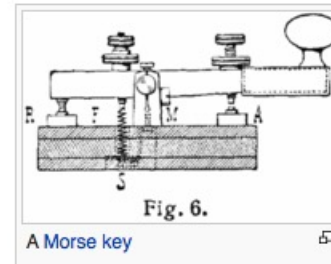
Wireless

Wireline

Wireline

Wireless

Morse system [edit]



The *Internet* itself is both –  
*Wireline* (fiber & copper)  
& *Wireless* (WiFi, cellular)

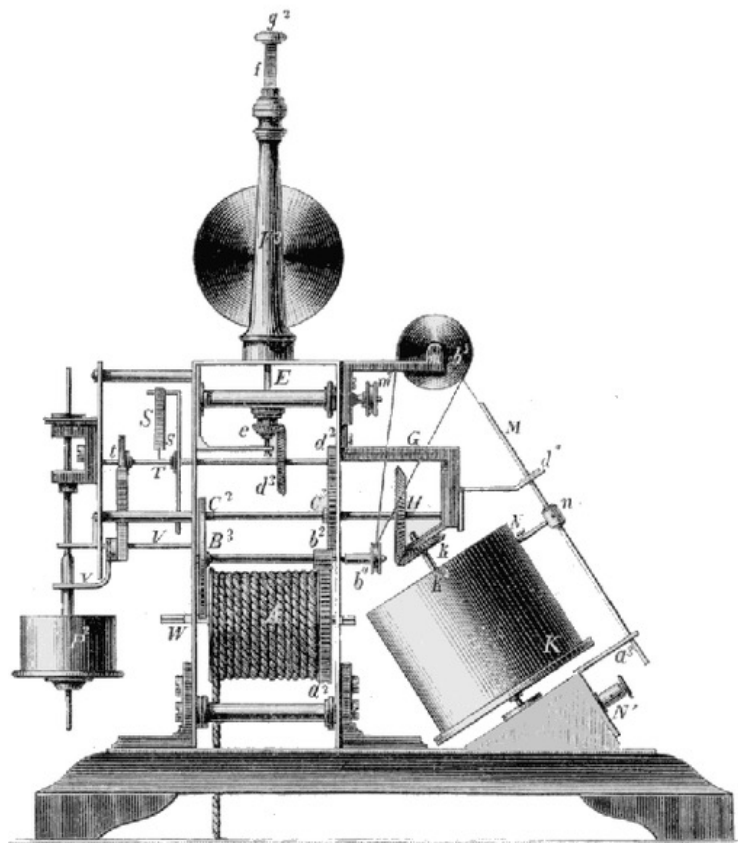


Latest trend:  
Media streaming services

# Fax Machine

Fax 1843

The first fax machine was invented in **1843** by Alexander Bain, a Scottish philosopher. Bain used two pendulums and the mechanisms from a clock to make his machine. The machine, called the Electric Printing Telegram printed messages line by line.



# Fax Machine

1843-1924

## FAST FAX FACTS

### The History of the Fax Machine

#### Mechanical Fax

Alexander Bain invents the 'Electric Printing Telegraph' machine in 1843 which is the world's first fax device.



1843

1880



#### Scanning PhotoTelegraph

The English inventor Shelford Bidwell invents the Scanning Phototelegraph machine, which is the first telefax machine capable of scanning and sending a two-dimensional image.

#### TelAutograph

In 1888 the TelAutograph machine was invented by Elisha Grey which allowed users to send signature images over long distances.



1888

1924



#### Wire Transmission

Scientists at the AT&T Corporation advance fax technology further by sending photos by telephone / wire transmission.

#### Wireless Transmission

The Radio Corporation of America (RCA) develops the TransOceanic Radio Facsimile and successfully transmits a photograph between New York and London.



1924

# Fax Machine

1924-1982

## FAST FAX FACTS

### The History of the Fax Machine

1924



#### Color Fax

The AT&T corporation invents a fax device which is capable of transmitting the world's first color facsimile.

6 mins

It took 6 mins to send a single page fax

00:06

1924

1960



#### Satellite Fax

The U.S Army sends the world's first photograph via satellite facsimile from America to Puerto Rico.

#### Telephone Transmission

The first commercialized version of the modern-day fax machine is introduced and patented by the Xerox Corporation using telephone transmission.



1964

1974

00:03

#### 3 mins

It took 3 mins to send a single page fax - How long does an eFax transmission take?

\$20,000

A fax machine cost \$20,000



1982

1982



#### Computer Based Fax Board

GammaLink introduced the first computer based fax

# Tech Companies

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**SOFTWARE**  
*INDIE APP DEVELOPER*

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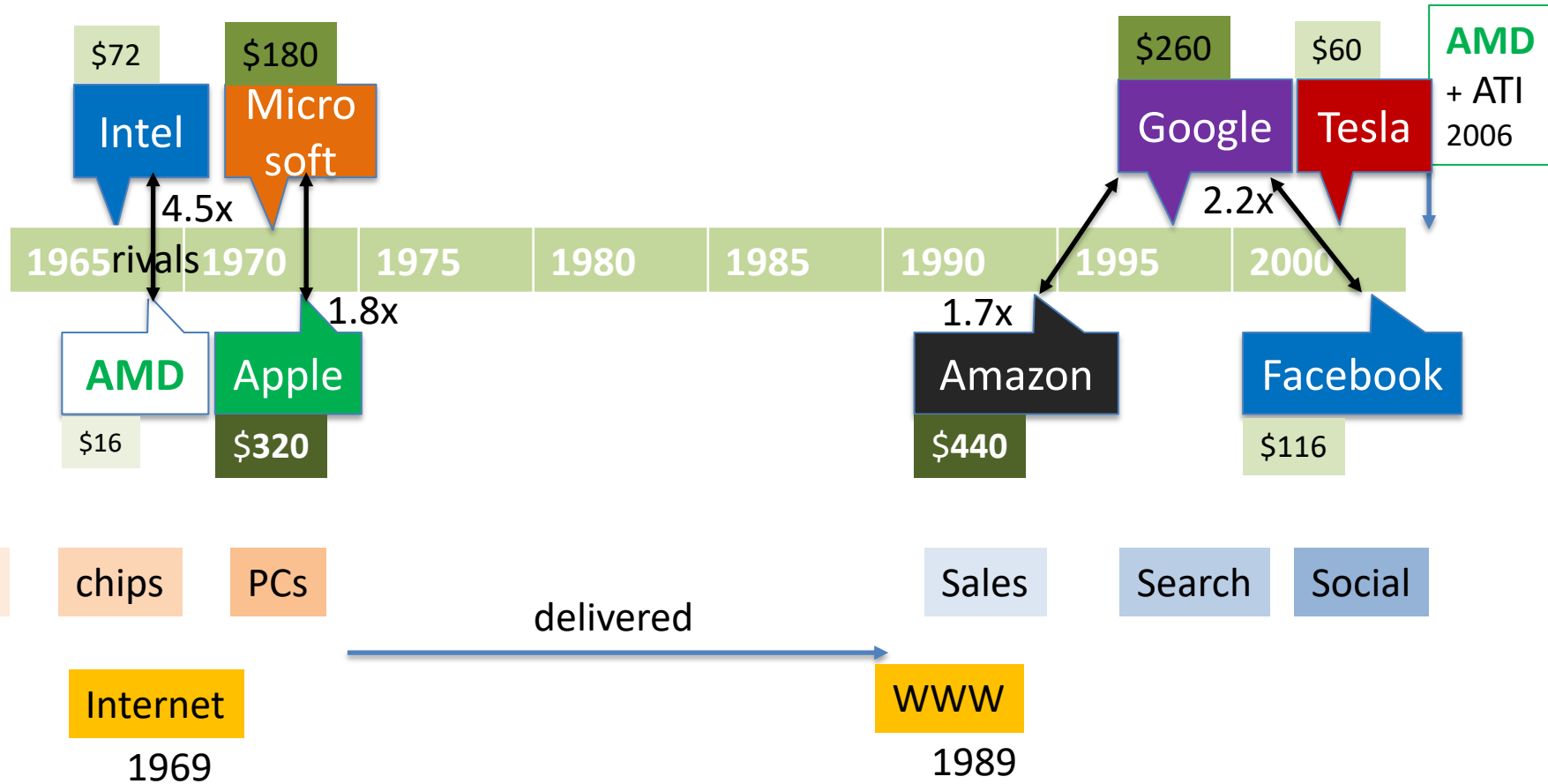
## Top Tech Titans

# Tech Titan Timeline

Revenue in \$B

Historical Perspective

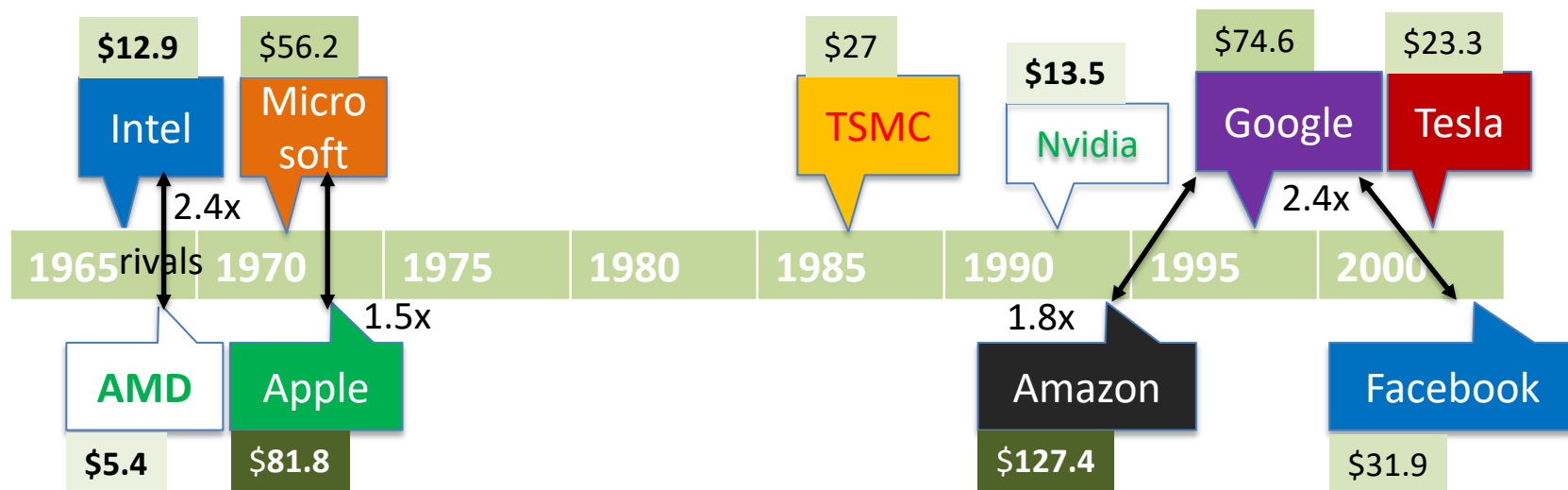
As of 2021





# Tech Titan Timeline

Qtr Revenue in \$B    Current Perspective    Q2 2023



## ❖ Other *Industrials*

- ❑ GM \$40.0 → 2x Tesla
- ❑ Ford \$39.1
- ❑ IBM \$16.7 → ~Intel
- ❑ QCOM \$9.3
- ❑ TI \$4.2
- ❑ NXPI \$3.3

## ❖ Other *Services*

- ❑ Netflix \$8.2
- ❑ Visa \$8.1
- ❑ PayPal \$7.4

# ISA/SoC Landscape

## CPU & GPU Cores

❖ **MIPS** Focus

❖ **ARM**

❑ **Apple**

❑ Qualcomm

❑ Samsung\*

❑ *Google*

Mobile

❖ **x86**

Laptop

❑ Intel\* 2/3

Desktop

❑ AMD 1/3

Server

❖ **ARM**

❑ Apple

❑ Nvidia

❑ Qualcomm

\*has own fab

❖ **iOT**

❑ Amazon

❑ Google

❖ **Cars**

❑ Tesla

❖ **Foundry (mfr)**

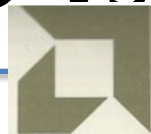
❑ TSMC

❑ Samsung

❑ GlobalFoundries (AMD)

❑ Intel (new)

# AMD vs Intel



Market Segment	AMD	Intel
Desktop	Ryzen 4K/Athlon 3K	Core i7/i9 (10 <sup>th</sup> gen)
Laptop	Ryzen 4000	Ice Lake
Gaming	Ryzen <i>Threadripper</i> +Radeon	Core Extreme
Server/Workstn	Epyc	Xeon

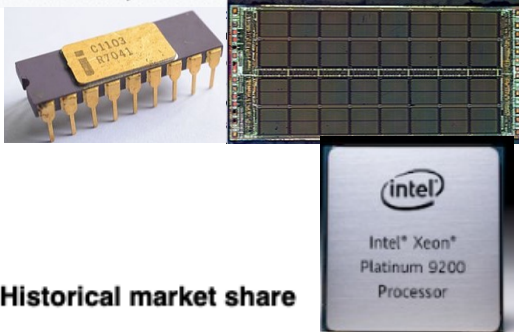
According to the company, the AMD Ryzen 4700 G series desktop processor offers up to 2.5x multi-threaded performance compared to the previous generation, up to 5% greater single-thread performance than the Intel Core i7-9700, up to 31% greater multithreaded performance than the Intel Core i7-9700, and **up to 202% better graphics performance than the Intel Core i7-9700.**



Intel's current logo, used since 2006



Intel's headquarters in Santa Clara, California



# Intel

\$70B



Intel logo used from 1968 to 2006



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f. 1968 Tech Titan 2019

<b>Founded</b>	July 18, 1968; 51 years ago
<b>Founders</b>	Gordon Moore Robert Noyce
<b>Revenue</b>	▲ US\$70.8 billion (2018)
<b>Operating income</b>	▲ US\$23.3 billion (2018)
<b>Net income</b>	▲ US\$21.0 billion (2018)

**Number of employees** 110,200 (2019)<sup>[2]</sup>

**Subsidiaries** Mobileye  
McAfee (49%)  
Here (15%)

## Products

Central processing units  
Microprocessors  
Integrated graphics processing units (iGPU)  
Systems-on-chip (SoCs)  
Motherboard chipsets  
Network interface controllers  
Modems  
Mobile phones  
Solid state drives  
Wi-Fi and Bluetooth Chipsets  
Flash memory  
Vehicle automation sensors



Andy Grove, Robert Noyce and Gordon Moore in 1978

## Historical market share

In the 1980s Intel was among the top ten sellers of [semiconductors](#) (10th in 1987) in the world. In 1992,<sup>[13]</sup> Intel became the biggest chip maker by revenue and has held the position ever since. Other top semiconductor companies include [TSMC](#), [Advanced Micro Devices](#), [Samsung](#), [Texas Instruments](#), [Toshiba](#) and [STMicroelectronics](#).

## Operating segments <sup>[edit]</sup>

- **Client Computing Group** – 55% of 2016 revenues – produces hardware components used in desktop and notebook computers.<sup>[10]</sup>
- **Data Center Group** – 29% of 2016 revenues – produces hardware components used in server, network, and storage platforms.<sup>[10]</sup>
- **Internet of Things Group** – 5% of 2016 revenues – offers platforms designed for retail, transportation, industrial, buildings and home use.<sup>[10]</sup>
- **Non-Volatile Memory Solutions Group** – 4% of 2016 revenues – manufactures [NAND flash memory](#) and [3D XPoint](#), branded as [Optane](#), products primarily used in [solid-state drives](#).<sup>[10]</sup>
- **Intel Security Group** – 4% of 2016 revenues – produces software, particularly security, and [antivirus](#) software.<sup>[10]</sup>
- **Programmable Solutions Group** – 3% of 2016 revenues – manufactures programmable semiconductors (primarily [FPGAs](#)).<sup>[10]</sup>



# AMD



Old AMD Headquarters  
(Sunnyvale, California)

Founder	Jerry Sanders +7
Headquarters	Santa Clara, California, U.S.
Area served	Worldwide
Key people	Lisa Su (President and CEO) John Edward Caldwell (Chairman)
Number of employees	10,100 <sup>[3]</sup> (2018)



AMD Sunnyvale groundbreaking, May 1969.

# AMD

## \$6.5B



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f. 1969 Tech Titan 2019

**Advanced Micro Devices, Inc. (AMD)** is an American **multinational semiconductor company** based in **Santa Clara, California** that develops **computer processors** and related technologies for business and **consumer markets**. While initially it manufactured its own processors, the company later outsourced its manufacturing, a practice known as **fabless**, after **GlobalFoundries** was spun off in 2009. AMD's main products include **microprocessors**, **motherboard chipsets**, **embedded processors** and **graphics processors** for **servers**, **workstations**, personal computers and **embedded system** applications.

AMD is the second-largest supplier and only significant rival to **Intel** in the market for **x86-based microprocessors**. Since acquiring **ATI** in 2006, AMD and its competitor **Nvidia** have maintained a **duopoly** in the discrete **graphics processing unit (GPU)** market.<sup>[4]</sup>



### AMD Accelerated Processing Unit



Release date 2011

### Architecture AMD64

<b>Cores</b>	2 to 4
<b>Transistors</b>	32 nm 1.178b (Llano) 32 nm 1.303b (Trinity) 32 nm 1.3b (Richland) 28 nm 2.41b (Kaveri) 14 nm 4.95b (Raven Ridge)

The **AMD Accelerated Processing Unit (APU)**, formerly known as *Fusion*, is the marketing term for a series of 64-bit **microprocessors** from **Advanced Micro Devices (AMD)**, designed to act as a **central processing unit (CPU)** and **graphics processing unit (GPU)** on a single **die**.

AMD announced the first generation APUs, *Llano* for high-performance and *Brazos* for low-power devices in January 2011. The second generation *Trinity* for high-performance and *Brazos-2* for low-power devices were announced in June 2012. The third generation *Kaveri* for high performance devices was launched in January 2014, while *Kabini* and *Temash* for low-power devices were announced in the summer of 2013.

The **Sony PlayStation 4** and **Microsoft Xbox One eighth generation video game consoles** both use semi-custom third generation low-power APUs.

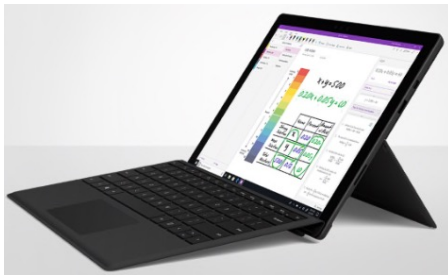
**Intel** CPUs with integrated **HD Graphics** also have a CPU and GPU on a single die, but they do not offer **HSA** features (see below).

Microsoft Corporation



Building 92 on the Microsoft Redmond campus  
in Redmond, Washington

Type Public  
Traded as NASDAQ: MSFT



# Microsoft

\$126B

f. 1975 Tech Titan 2019

**Industry** Computer software  
Computer hardware  
Consumer electronics  
Social networking service  
Cloud computing  
Video games  
Internet  
Corporate venture capital

**Founded** April 4, 1975; 44 years ago in  
Albuquerque, New Mexico,  
U.S.

**Founders** Bill Gates  
Paul Allen

**Headquarters** One Microsoft Way, Redmond,  
Washington, U.S.

**Number of employees** 144,106<sup>[2]</sup> (2019)

**Revenue** US\$125.8 billion<sup>[1]</sup> (2019)

**Operating income** US\$43.0 billion<sup>[1]</sup> (2019)

**Net income** US\$39.2 billion<sup>[1]</sup> (2019)

**Products** Windows · Office · Servers ·  
Skype · Visual Studio ·  
Dynamics · Xbox · Surface ·  
Mobile · List of software

**Services** Azure · Bing · LinkedIn · MSDN  
· Office 365 · OneDrive ·  
Outlook.com · TechNet · Pay ·  
Microsoft Store · Windows  
Update · Xbox Live



**Be brilliant with Office 365**

## Windows 10 Enterprise

Download the free 90-day  
evaluation for IT professionals.

[DOWNLOAD NOW >](#)

## Get Visual Studio 2019

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productive, modern, and innovative  
IDE.





# Apple

\$266B



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**Founded** April 1, 1976; 43 years ago

**Founders** Steve Jobs  
Steve Wozniak  
Ronald Wayne

**Number of employees** 132,000<sup>[2]</sup> (2018)

## Products

Macintosh • iPod • iPhone • iPad  
• Apple Watch • Apple TV •  
HomePod • macOS • iOS •  
iPadOS • watchOS • tvOS • iLife  
• iWork • Final Cut Pro • Logic  
Pro • GarageBand • Shazam •  
Siri

## Services

App Store • Apple Arcade •  
Apple Card • Apple Music  
(Beats 1) • Apple News+ • Apple  
Pay (Cash) • Apple Store  
(Genius Bar) • Apple TV+ •  
iBooks Store • iCloud •  
iMessage • iTunes Store • Mac  
App Store

## Industry

Computer hardware  
Computer software  
Consumer electronics  
Cloud computing  
Digital distribution  
Fabless silicon design  
Semiconductors  
Financial technology  
Artificial intelligence

## Subsidiaries

Braeburn Capital • Beats  
Electronics • FileMaker Inc. •  
Apple Energy, LLC • Apple  
Sales International<sup>[3]</sup> • Apple  
Services<sup>[4]</sup> • Apple Worldwide  
Video<sup>[5]</sup> • Anobit • Beddit



Photos



iMovie



GarageBand



Pages



Numbers



Keynote



Safari

# Google

\$137B

Tech Titan 2019

Google Search

Google Ads

Google Images

Google Marketing  
Platform

YouTube

Google Ad Manager

AdMob

Google News

Google AdSense

Google Ad Grants

Google Finance

**Alphabet Inc.** is an American multinational conglomerate headquartered in Mountain View, California. It was created through a corporate restructuring of Google on October 2, 2015, and became the parent company of Google and several former Google subsidiaries. The two founders of Google

**Number of employees** 103,459 (Q1 2019)



Account



Search



My Business



Maps



YouTube



Play



Finance



Docs



Books



News



Gmail



Contacts



Blogger



Duo



Hangouts



Drive



Calendar



Translate



Keep



Jamboard



Classroom



Photos



Shopping



Collections

## Operating systems

1. **Android** – Linux-based
2. **Chrome OS** – Linux-based
3. **Wear OS** – version of Android
4. **Android Auto** – version of Android
5. **Google TV** – it was a version of Android
6. **Android TV** – version of Android
7. **Glass OS** – operating system for Google Glass
8. **Google Fuchsia** – un



Google's logo since 2015



Google's headquarters, the Googleplex

**Formerly** Google Inc. (1998–2017)

**Type** Subsidiary

**Industry** Internet  
Cloud computing  
Computer software  
Computer hardware  
Artificial intelligence  
Advertising

**Founded** September 4, 1998; 20 years ago in **Menlo Park, California**

**Founders** **Larry Page**  
**Sergey Brin**

**Headquarters** 1600 Amphitheatre Parkway,  
**Mountain View, California, U.S.**

**Revenue** ▲ **US\$136.82 billion** (2018)

**Operating income** ▲ **US\$26.32 billion** (2018)

**Net income** ▲ **US\$30.74 billion** (2018)



# Google

\$137B

More

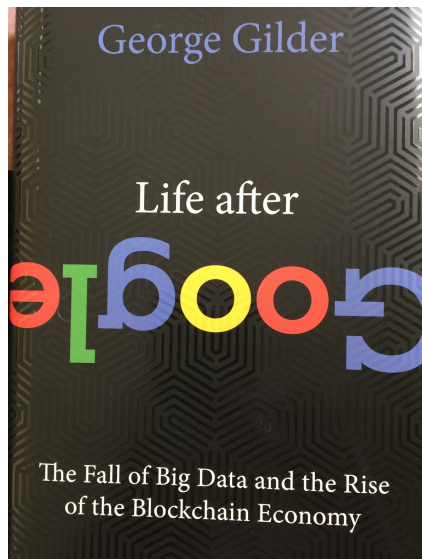
Tech Titan

2019



Then-CEO, now Chairman of Google  
Eric Schmidt with cofounders Sergey Brin and Larry Page (left to right) in 2008.

- ❖ Google started as research at Stanford by Brin and Page
  - Indexed 150 GB of Internet web pages → 15 TB (100x)
- ❖ Eric Schmidt brought “The Network” from Sun Micro to Google
- ❖ Google just built 30-acre Data Center in Oregon (at The Dalles)
  - 75,000 servers
  - 3x 10M cu. ft. warehouses
  - Connects to nearby trans-Pacific optical cable (PC-1 at 8.4 Tbps)
- ❖ Google now at “Peta/Exa scale” ( $10^{15/18}$ ): exabytes, petaflops
- ❖ Google handles each day
  - Scores of TB of Gmail, Facebook pages, Twitter, etc.
  - 1B ( $10^9$ ) YouTube videos
  - 3.5B searches → 1.5T per year
- ❖ In 2018, 1GB of hard disk costs only 2 cents (1ExB = \$20M)
- ❖ Google’s cloud will link to trillions of sensors around the world
  - iPhone 8 has 16 different sensors





# amazon



The Amazon Spheres, part of the Amazon headquarters campus in Seattle

# Amazon

\$233B



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Tech Titan 2019

**Founded** July 5, 1994; 25 years ago in Bellevue, Washington

**Founder** Jeff Bezos

**Headquarters** Seattle, Washington and Arlington, Virginia, United States

**Industry**

- Cloud computing
- E-commerce
- Artificial intelligence
- Consumer electronics
- Digital distribution

**Products** Amazon Echo • Amazon Fire • Amazon Fire TV • Amazon Fire OS • Amazon Kindle

**Services** Amazon.com • Amazon Alexa • Amazon Appstore • Amazon Music • Amazon Prime • Amazon Prime Video • Amazon

**Subsidiaries** A9.com • AbeBooks • Amazon Air • Alexa Internet • Amazon Books • Amazon Game Studios • Amazon Lab126 • Amazon Logistics, Inc. • Amazon Publishing • Amazon Robotics • Amazon.com Services • Amazon Studios • Audible • Body Labs • AWS • Book Depository • ComiXology • Goodreads • Graphiq • IMDb • Ring • Souq.com • Twitch Interactive • Whole Foods Market • Woot • Zappos

## Smart Speakers

**Revenue** ▲ US\$232.887 billion (2018)

**Operating income** ▲ US\$12.421 billion (2018)

**Net income** ▲ US\$10.073 billion (2018)

**Number of employees** ▲ 647,500 (2018)



Echo Dot

Add Alexa to any room

~~\$49.99~~ **\$29.99**

With Screens



**NEW** Echo Show 5

Compact smart display with Alexa

~~\$89.99~~ **\$64.99**

## Fire Tablets



**NEW** Fire 7, 16 GB

Our best-selling Fire tablet. All-new Kindle - now with a front-light

\$49.99

## Kindle E-Readers



**NEW** Kindle

\$89.99

## Doorbells



Ring Video Doorbell 2

See, hear and speak to anyone at your door

\$199.00



The "f" logo for its online platform

# Facebook

\$56B



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Tech Titan 2019

Facebook, Inc.



**Founded** February 4, 2004; 15 years ago in  
Cambridge, Massachusetts<sup>[2]</sup>

**Headquarters** 1 Hacker Way  
(aka 1601 Willow Road)  
Menlo Park, California, U.S.

**Employees** 39,651 (June 30, 2019)<sup>[6]</sup>

**Written in** C++, PHP (as HHVM),<sup>[8]</sup> D<sup>[9]</sup>

**Revenue** ▲ US\$ 55.838 billion (2018)<sup>[4]</sup>

**Operating income** ▲ US\$ 24.913 billion (2018)<sup>[4]</sup>

**Net income** ▲ US\$ 22.111 billion (2018)<sup>[4]</sup>

**Users** ▲ 2.3 billion monthly active users  
(December 2018)

Create Post



What's on your mind, Jeff?



Photo/Video



Tag Friends



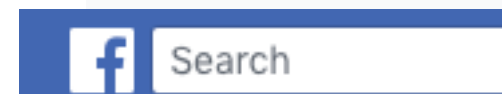
Feeling/Activ...

Products

Messenger

Watch

Portal



News Feed



Messenger



Watch



Marketplace

Explore



Pages



Groups



Oculus



Events



Fundraisers

Who should see this?



Public

Anyone on or off Facebook



Friends

Your friends on Facebook



Friends except...

Don't show to some friends

# Facebook

Server Farm



**FACEBOOK** says that since the company is the only entity gathering and monetizing personal data within its system, it does not engage in sales of user data to third parties. Above, a Facebook server room is seen in 2013.

JONATHAN NACKSTRAND AP/WIDEWORLD



# Bitcoin Mine



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INDIE APP DEVELOPER

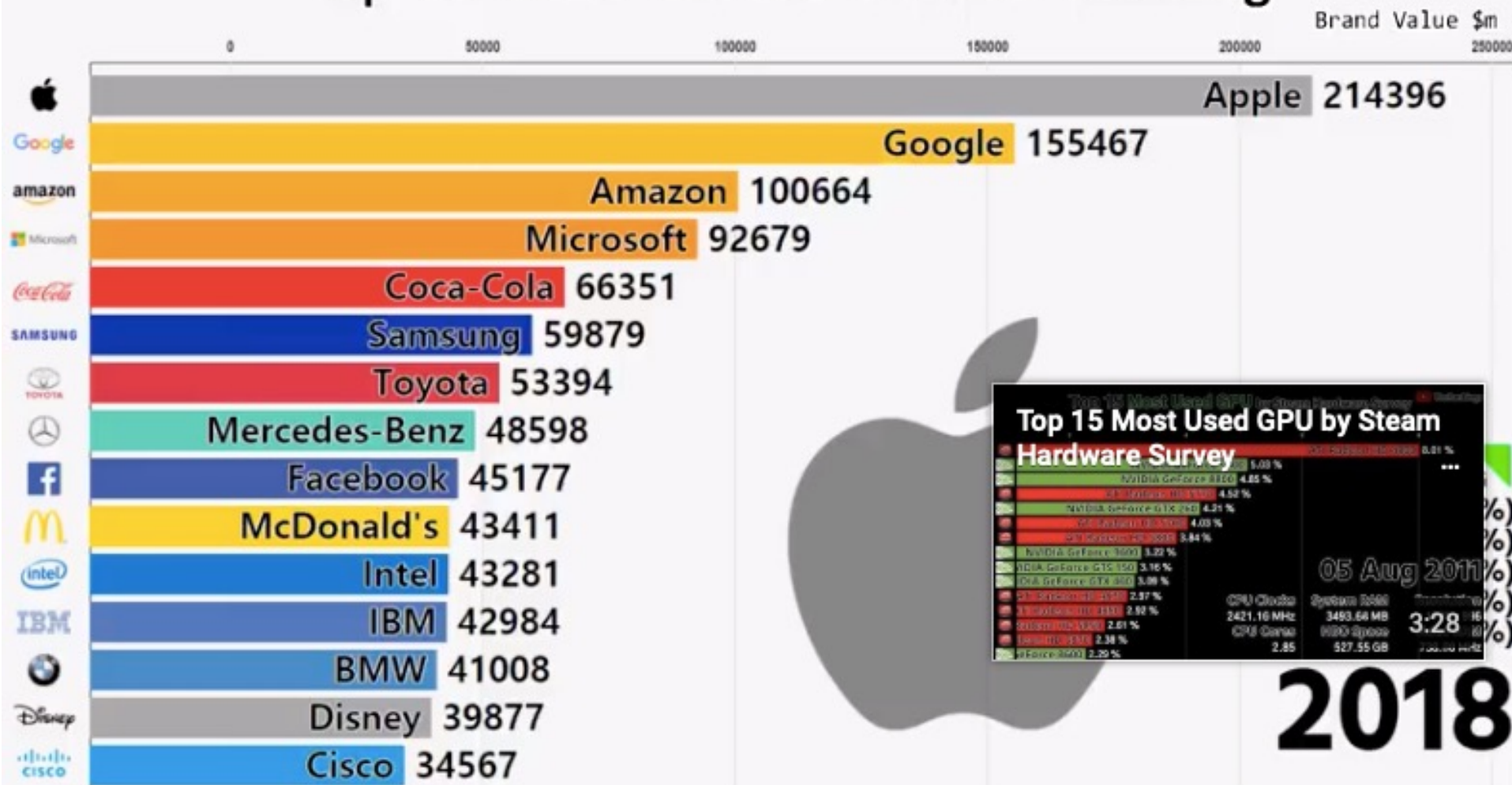
Jeff Drobman  
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Server Farm



# Corporate Brands

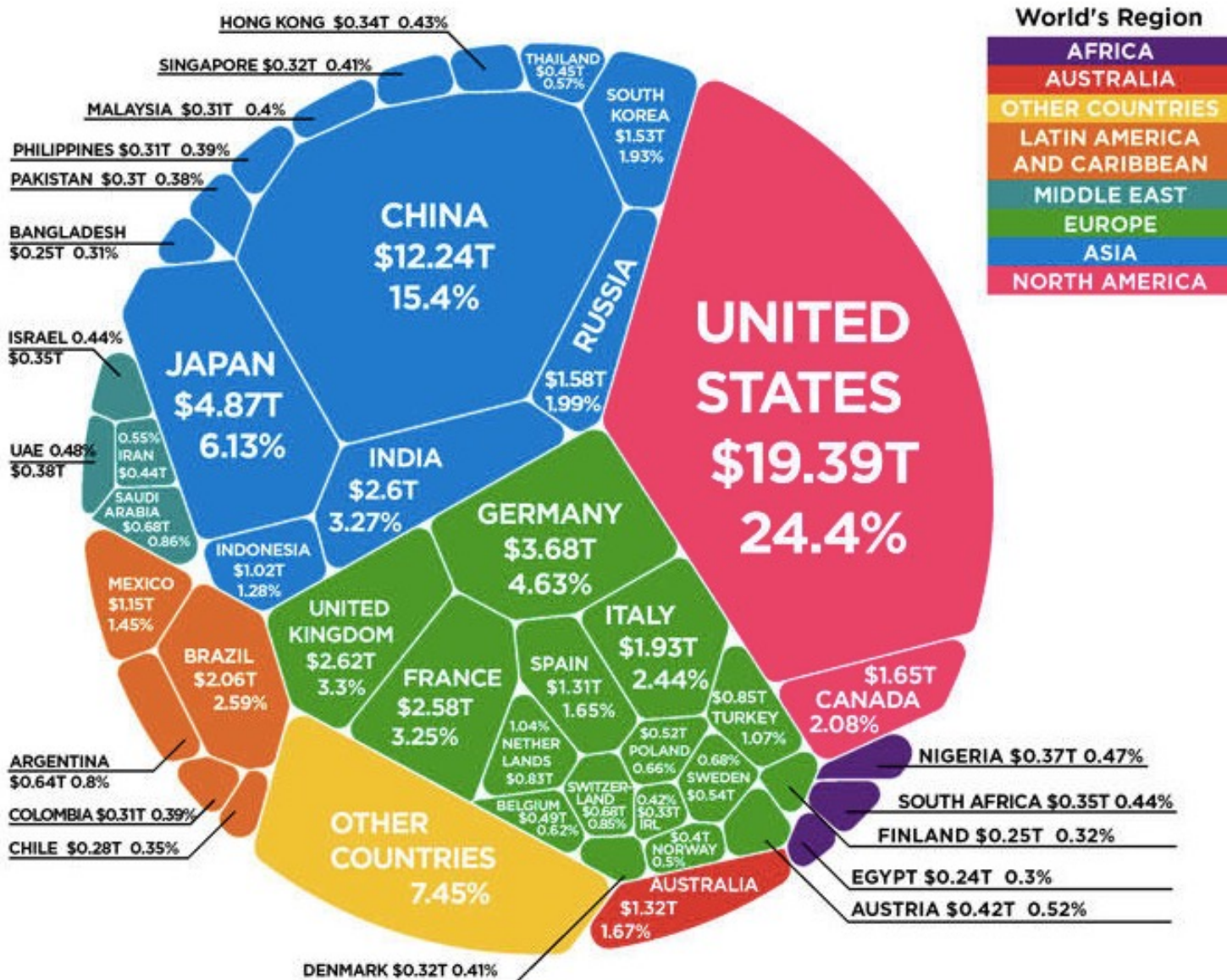
## Top 15 Best Global Brands Ranking



Top 15 Best Global Brands Ranking (2000-2018)



# World Economy

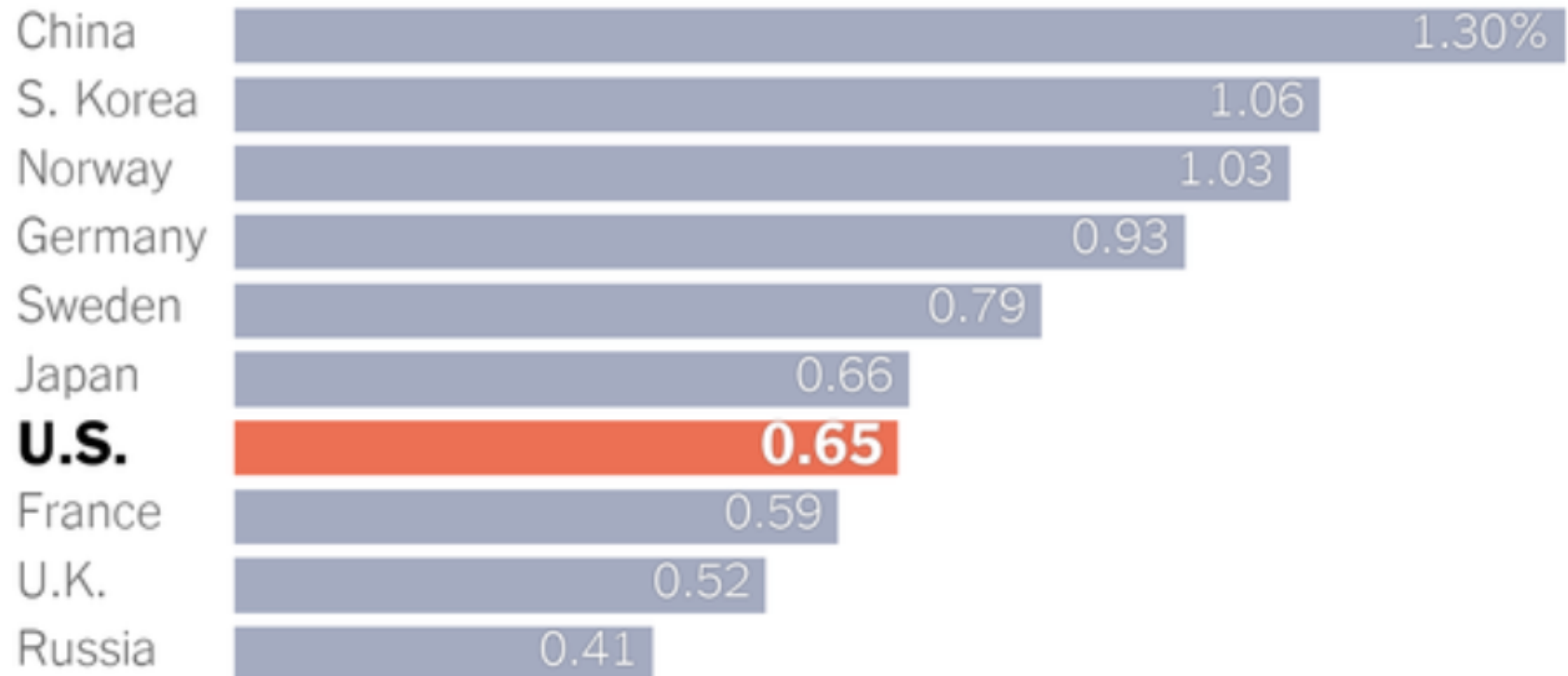


# WW R&D



## Government spending on research and development

As a share of a country's gross domestic product



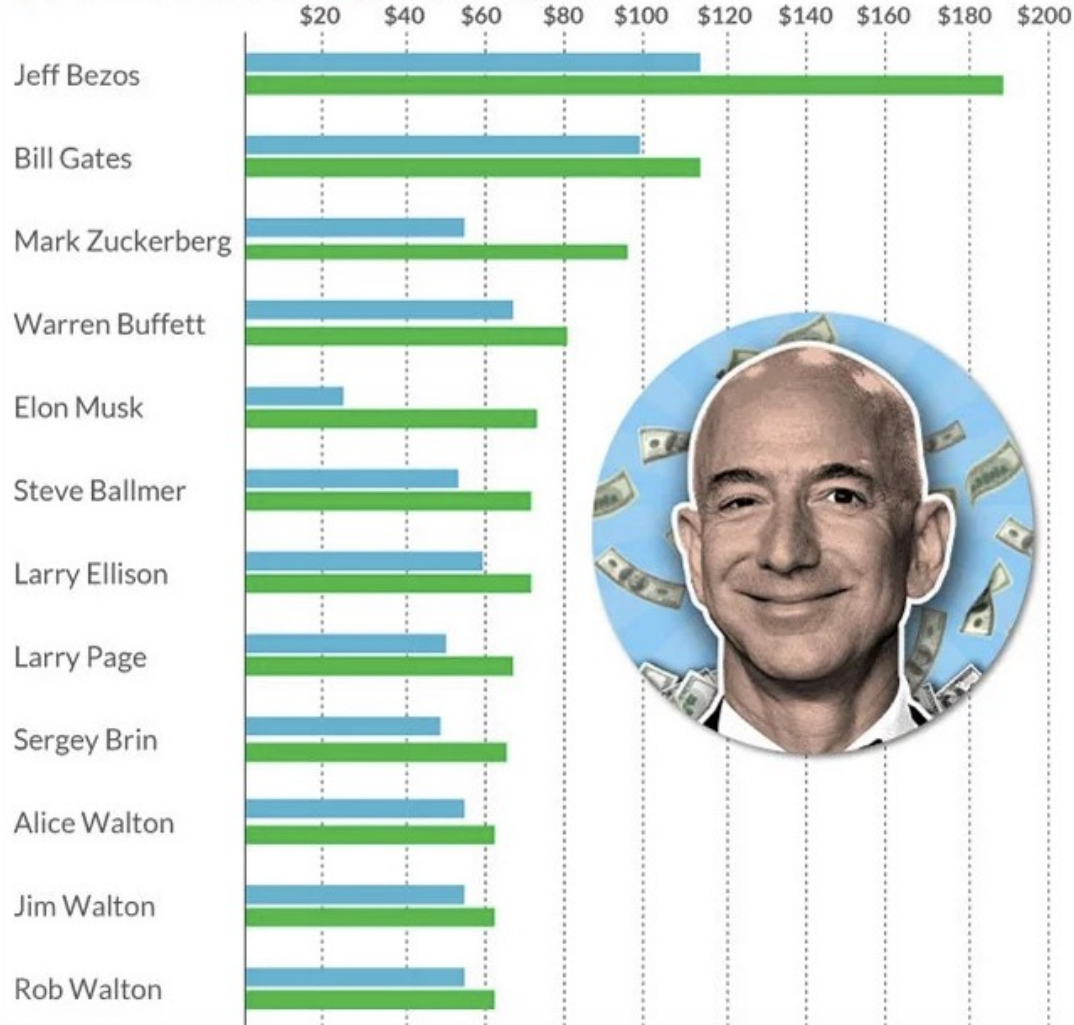
# Tech Titan Founders/CEOs

2020

## Oligarchic Dozen

The rich get richer... a lot richer

■ Net Worth March 18 ■ Net Worth Aug. 13 In billions



Source: Institute for Policy Studies



# Computers

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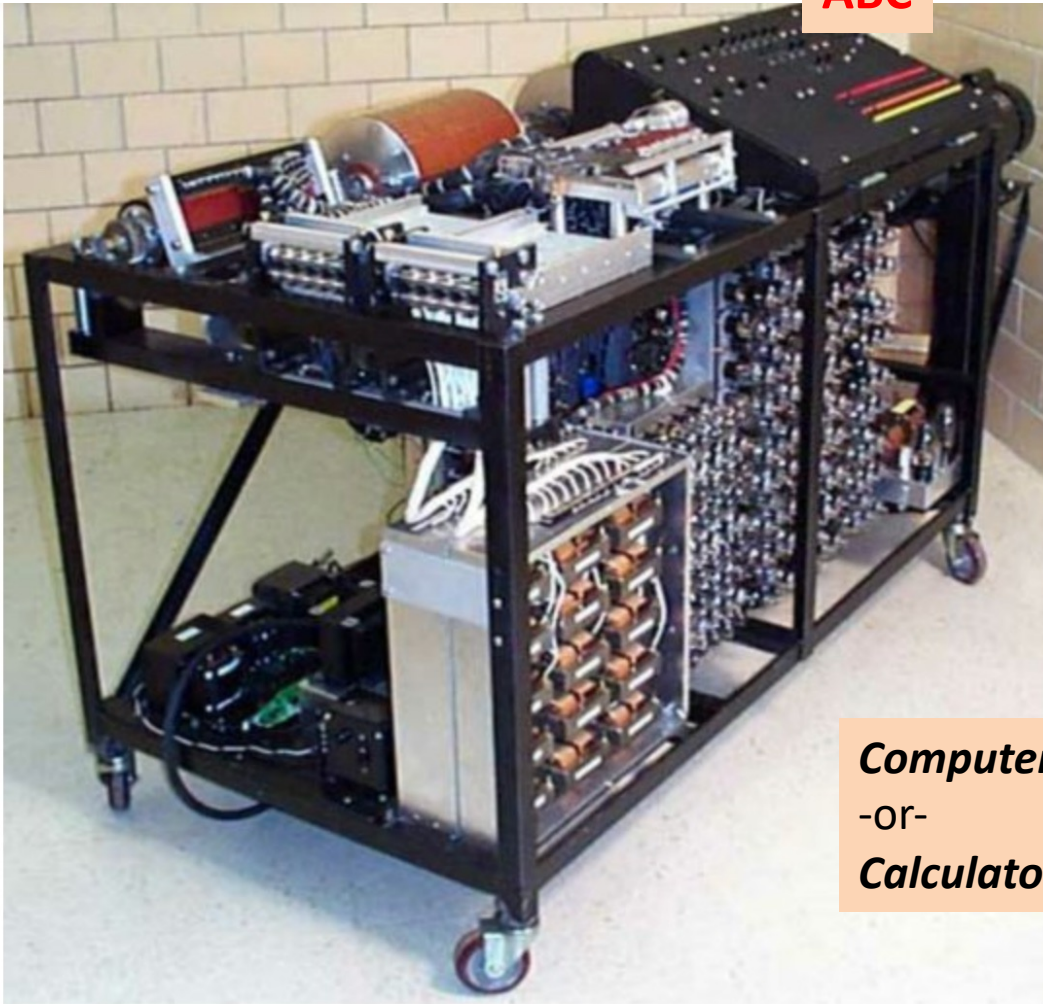
## Mainframes



Quora

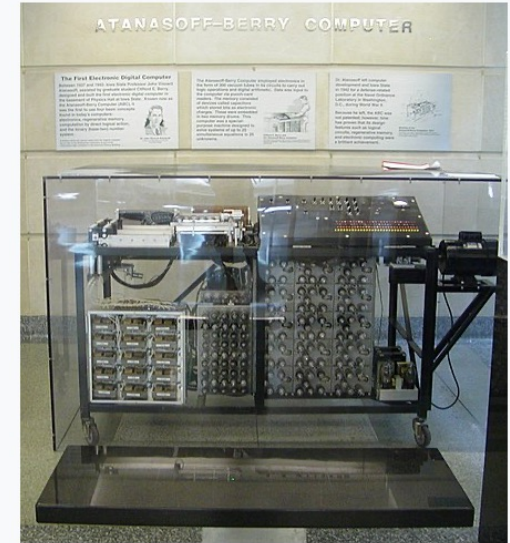
# 1<sup>st</sup> Computer?

ABC



*Computer  
-or-  
Calculator?*

## Atanasoff-Berry computer (ABC)



Atanasoff-Berry computer replica at Durham Center, Iowa State University

**Developer** John Vincent Atanasoff with help of graduate student Clifford Berry

**Release date** 1942; 81 years ago

**Units sold** 1

**CPU** More than 300 vacuum tubes @ 60 Hz

**Memory** 3000 bits

**Display** Decimal, via a front panel display

**Input** Decimal, via standard IBM 80-column punched cards

**Mass** 700 pounds (320 kg)

The ABC weighed over 700 pounds and used vacuum tubes. It had a rotating drum, a little bigger than a paint can, that had small capacitors on it. A capacitor is device that can store an electric charge, like a battery.

# 1<sup>st</sup> Computer?

Wikipedia

ABC

The **Atanasoff–Berry computer (ABC)** was the first automatic electronic [digital computer](#).<sup>[1]</sup> Limited by the technology of the day, and execution, the device has remained somewhat obscure. The ABC's priority is debated among historians of computer technology, because it was neither [programmable](#), nor [Turing-complete](#).<sup>[2]</sup> Conventionally, the ABC would be considered the first electronic ALU ([arithmetic logic unit](#)) – which is integrated into every modern processor's design.

Its unique contribution was to make computing faster by being the first to use [vacuum tubes](#) to do the arithmetic calculations. Prior to this, slower electro-mechanical methods were used by [Konrad Zuse's Z1 computer](#), and the simultaneously developed [Harvard Mark I](#). The first electronic, programmable, digital machine,<sup>[3]</sup> the [Colossus computer](#) from 1943 to 1945, used similar tube-based technology as ABC.

# First Computer?

Quora

ABC or ENIAC?




**Tom Crosley**, M.S. Computer Science, Illinois Institute of Technology  
Chicago - Illinois Tech



Answered Sep 18

## When was the first electronic computer ever produced?

Originally Answered: What was the first electronic computer?

The [Atanasoff–Berry computer \(ABC\)](#)  was the first automatic electronic digital computer. (It was not the first *general-purpose programmable* electronic computer; that honor goes to ENIAC as described in another answer.)

Conceived in 1937, the machine was built by Iowa State College (now Iowa State University, my undergraduate alma mater) mathematics and physics professor John Vincent Atanasoff with the help of graduate student Clifford Berry. It was first successfully tested in 1942.

The ABC computer was built for a specific purpose; the solution of systems of simultaneous linear equations. It could handle systems with up to twenty-nine equations.

**Quora**

# First Computer?

**ENIAC?**

The machine contained about 300 vacuum tubes. The memory of the Atanasoff–Berry Computer was a system called regenerative capacitor memory, a forerunner of DRAM but which used a drum.

**Eckert & Mauchly**

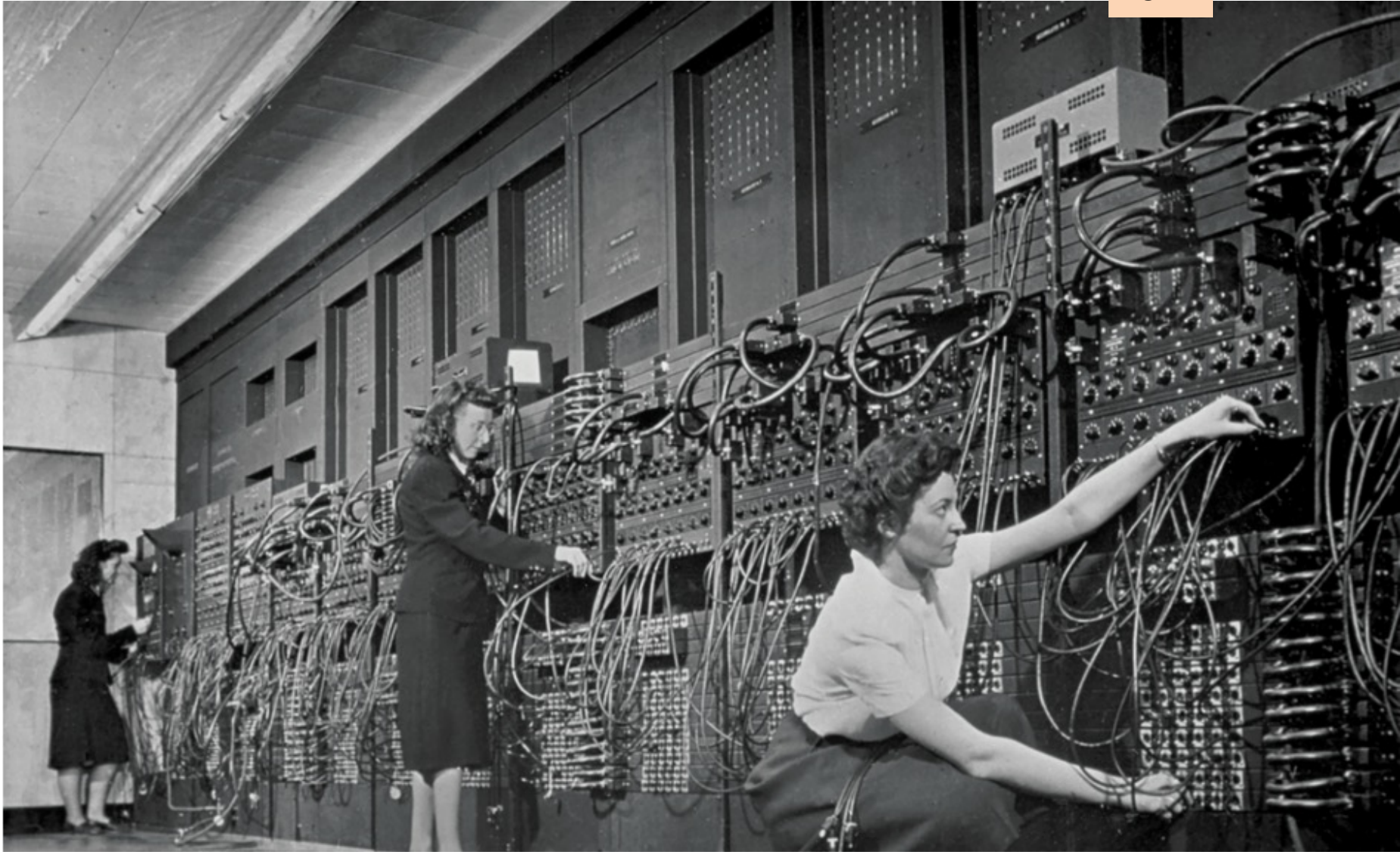
On June 26, 1947, J. Presper Eckert and John Mauchly were the first to file for patent on a digital computing device (ENIAC), much to the surprise of Atanasoff. The ABC had been examined by John Mauchly in June 1941, and Isaac Auerbach, a former student of Mauchly's.

The ENIAC patent did not issue until 1964. In 1967 Honeywell sued Sperry Rand in an attempt to break the ENIAC patents, arguing the ABC constituted prior art. The case was legally resolved on October 19, 1973, when U.S. District Judge Earl R. Larson held the ENIAC patent invalid, ruling that the ENIAC derived many basic ideas from the Atanasoff–Berry Computer.



# ENIAC

1944



Computer operators with an Eniac — the world's first programmable general-purpose computer.

Corbis/Getty Images

# ENIAC

Quora

1944



Andrew Silverman, Long-time Microsoft employee, tinkerer, maker, and computer history buff.

Updated Aug 12, 2021


## How much memory did the ENIAC computer have?

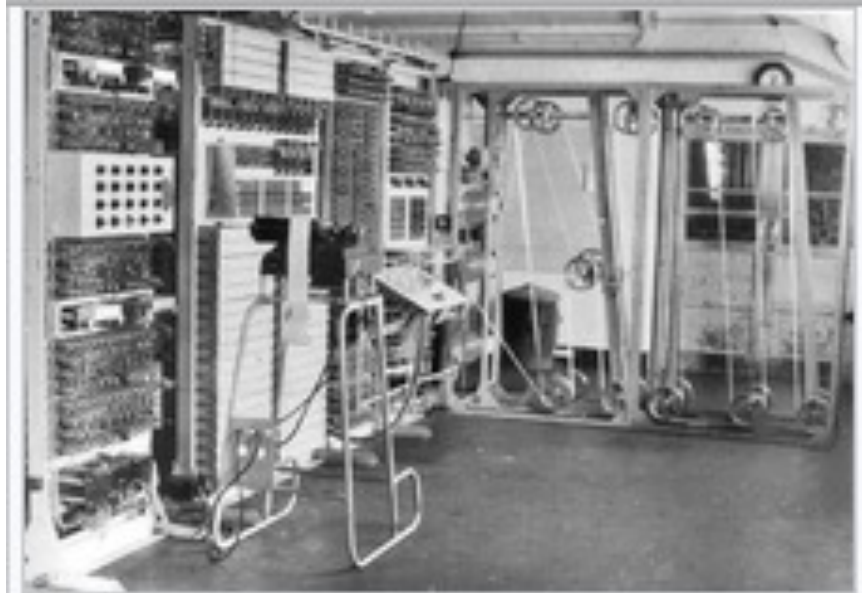
ENIAC's architecture was rather different from what we see in modern computers but the shortcomings of this machine were precisely what steered Von Neumann, Eckert, and Mauchly towards the combined instruction/data memory architectures that followed.


Strictly speaking, ENIAC had 1248 decimal digits and 208 signs (pos/neg) of "function tables" (essentially read-only numerical data switches that were usable as either program instructions or data in later configurations), and a mere 200 decimal digits of writable data, spread across about twenty individual accumulators. This lack of sufficient memory and the enormous number of tubes required implementing each digit eventually led Eckert to design the mercury delay-line memory circuit. Alongside cathode ray-tube memory, which was invented around the same time, these newer options drastically increased storage capacity and lowered costs in the designs that followed ENIAC.

# ENIAC & Colossus



**ENIAC** was the first Turing-complete  electronic device, and performed ballistics trajectory calculations for the United States Army.<sup>[93]</sup>



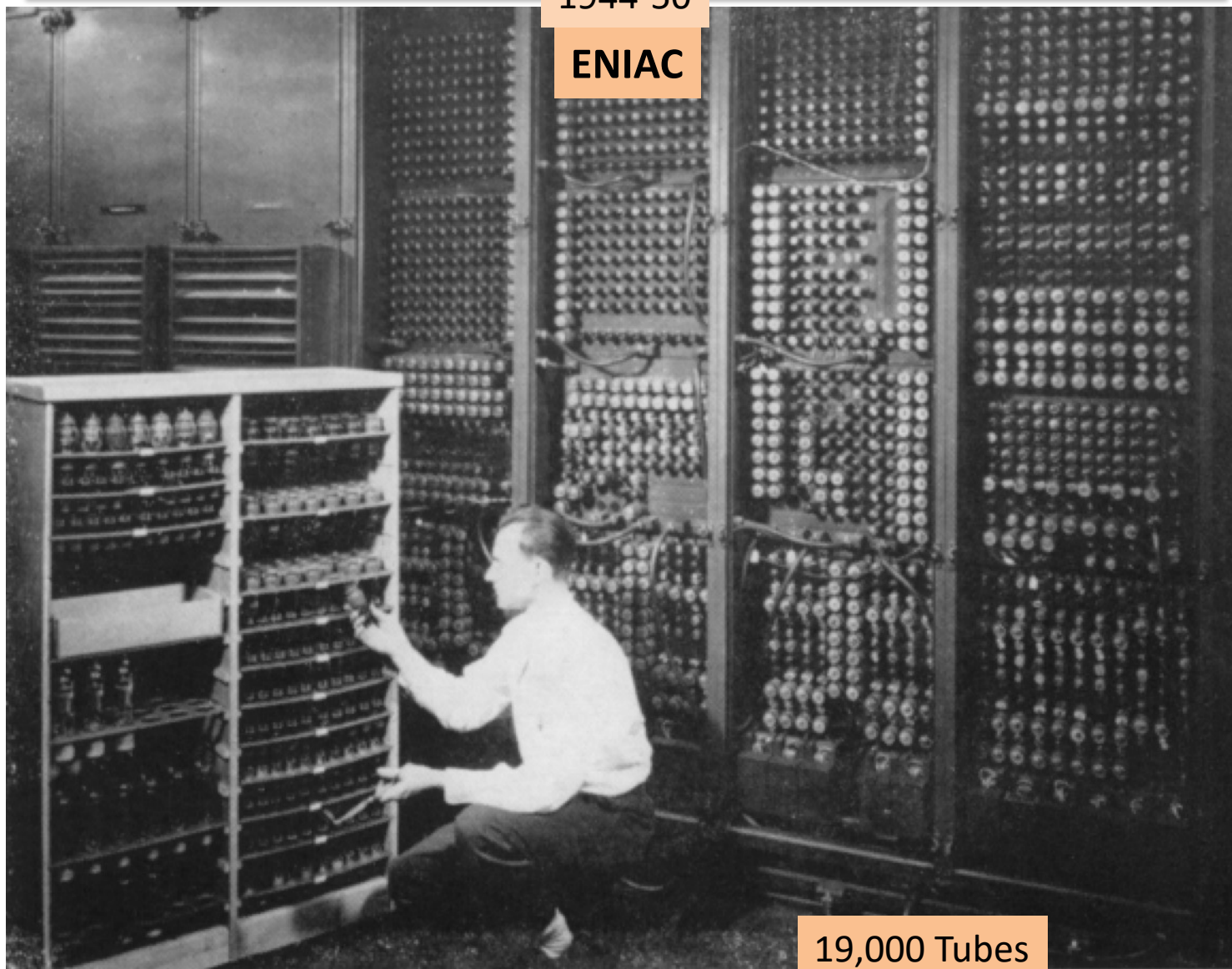
Wartime photo of Colossus No. 10 



# 1<sup>st</sup> Gen Mainframes

1944-50

ENIAC



19,000 Tubes

Replacing a bad tube meant checking among ENIAC's 19,000 possibilities.



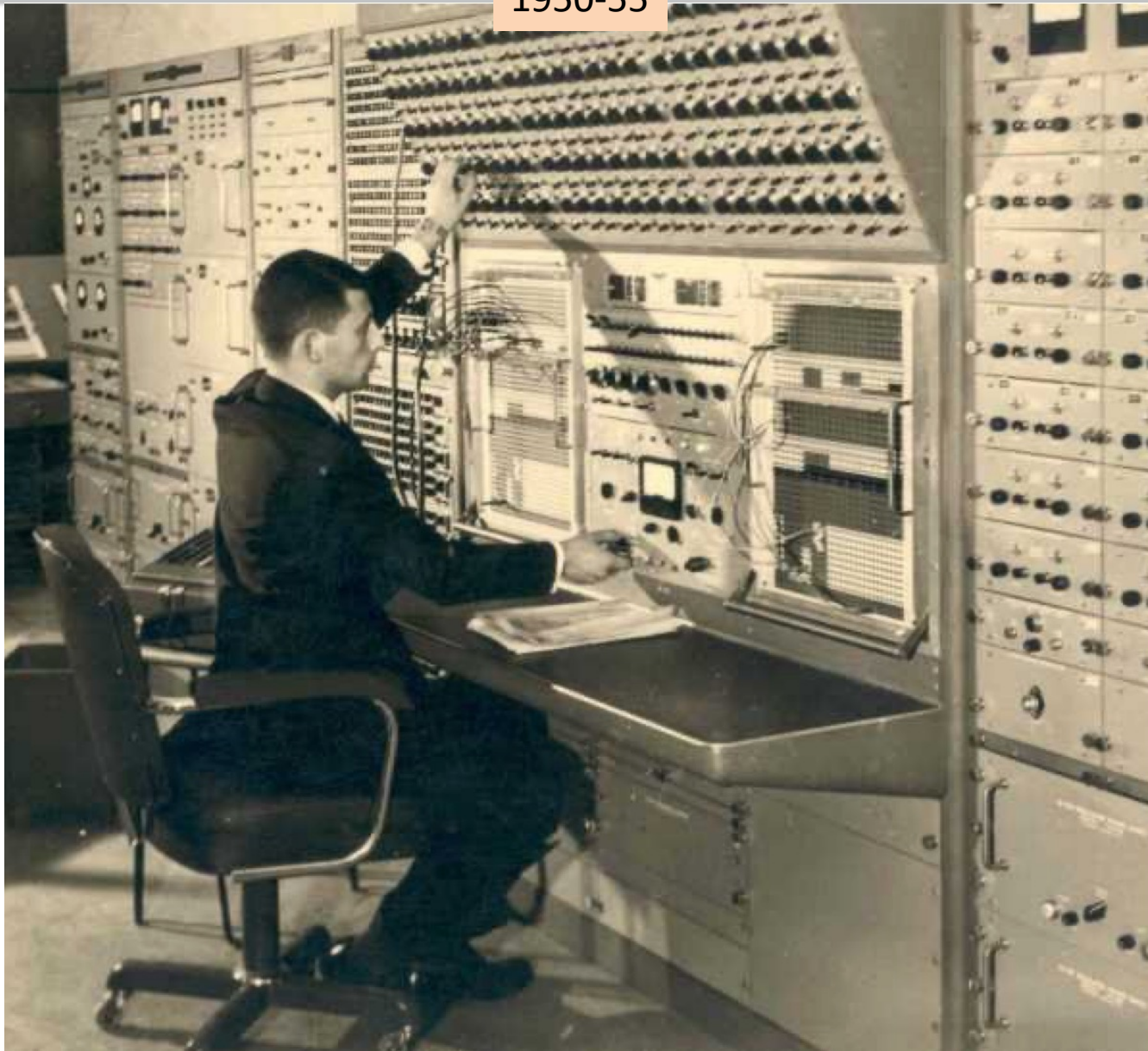
# 1<sup>st</sup> Gen Mainframes

1950-55



**DR JEFF**  
**SOFTWARE**  
INDIE APP DEVELOPER

Jeff Drobman  
©2016-23



# 1<sup>st</sup> Gen Mainframes

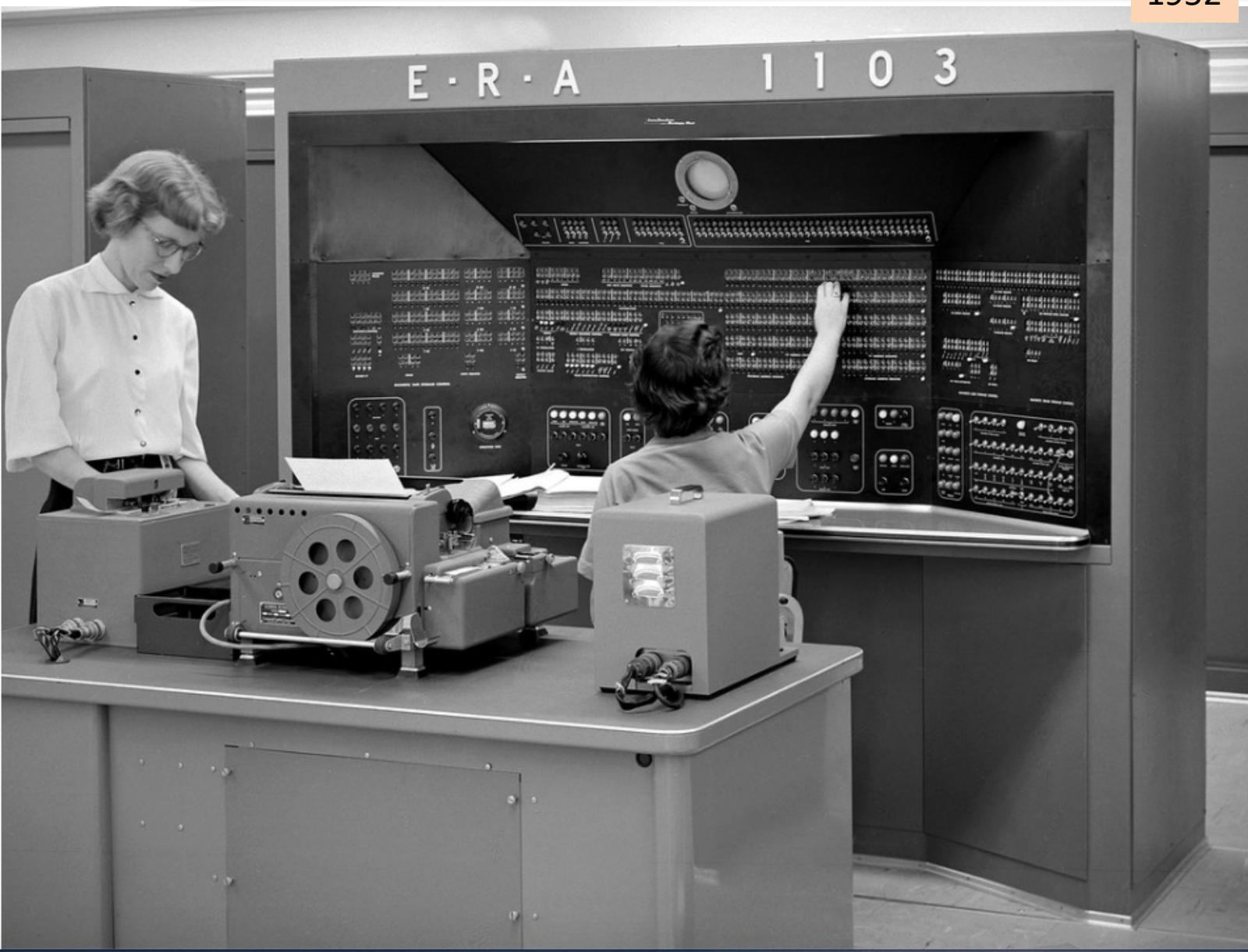
1950-55





# Univac 1103

1952



An E.R.A./Univac 1103  
computer in the 1950s.  
Hum Images/Alamy

# IBM 701

1952



IBM 701 processor frame, showing  
1071 of the vacuum tubes



Vacuum tube logic module from a  
700 series IBM computer.



Williams tube from an IBM  
701 at the [Computer History Museum](#)






# IBM 704

1<sup>st</sup> with FP

1954



An IBM 704 computer, with **IBM 727** tape drives and **IBM 780** CRT display 

# IBM 1401

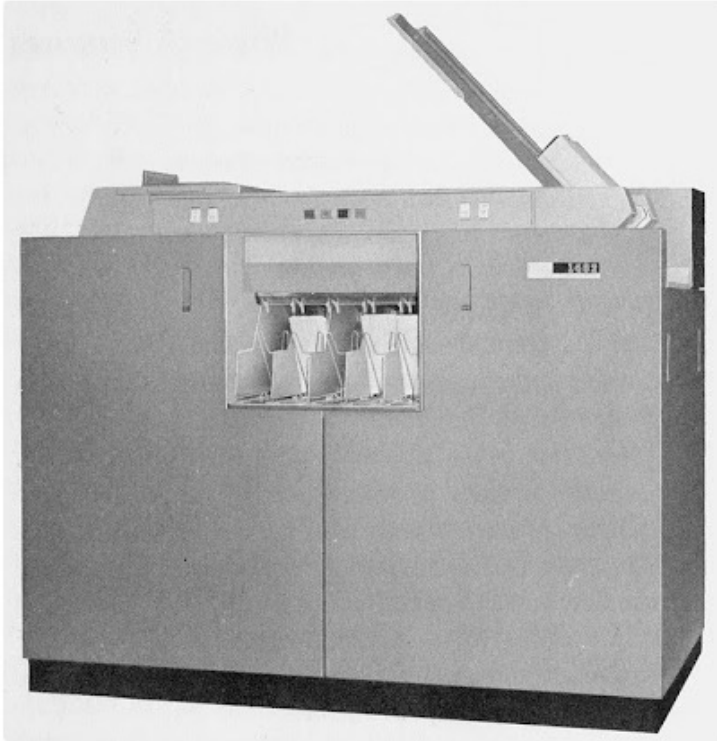
1959



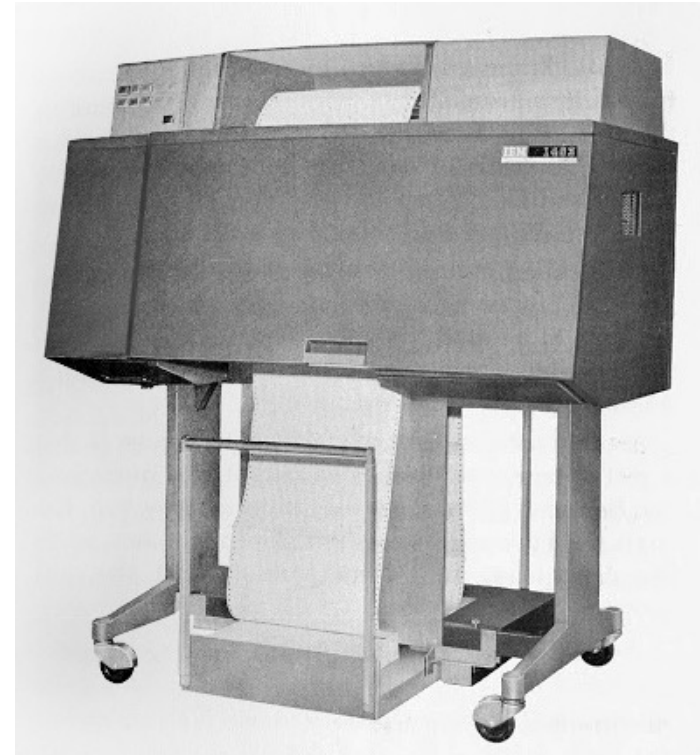
The IBM 1401 "mainframe".

# IBM 1401

1959



1402 Card reader/punch



1403 Printer

# IBM 1401

1959



**IBM 729 Tape Drives — with vacuum tape loop buffering**



# IBM 7090

1962



Dual 7090s at NASA during [Project Mercury](#).

# IBM 7074

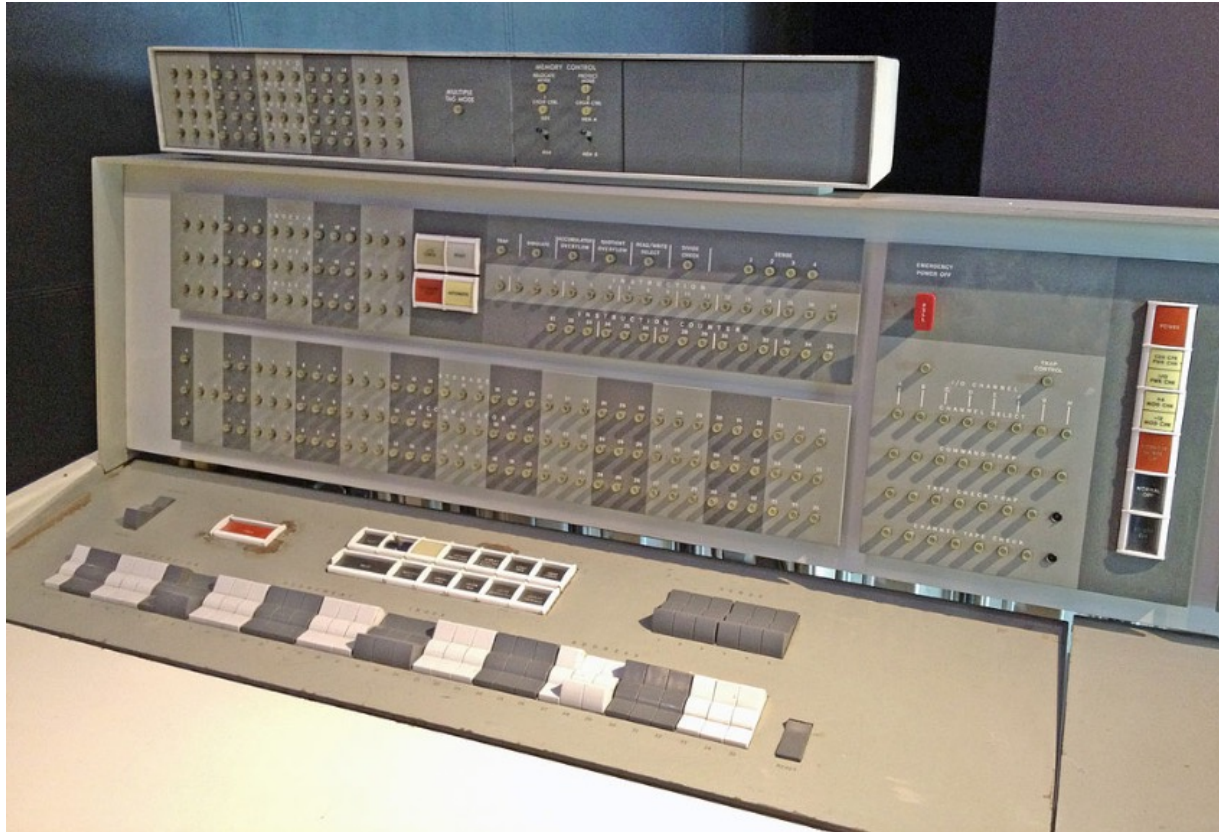
1964





# IBM 7094

1965



IBM 7094 operator's console showing additional index register displays in a distinctive extra box on top. Note "Multiple Tag Mode" light in the top center.

# IBM System 360

1965



System/360 Model 65 operator's console, with register value lamps and toggle switches (middle of picture) and "emergency pull" switch (upper right)



IBM System/360 Model 50 CPU, computer operator's console, and peripherals at Volkswagen

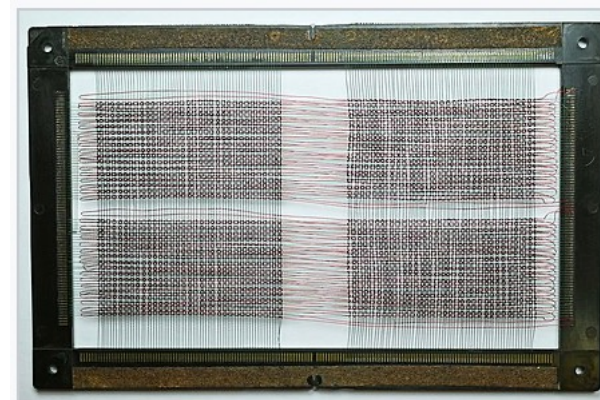


# IBM System 360

1965




IBM System 360 Model 91 operator's console at NASA, sometime in the late 1960s.

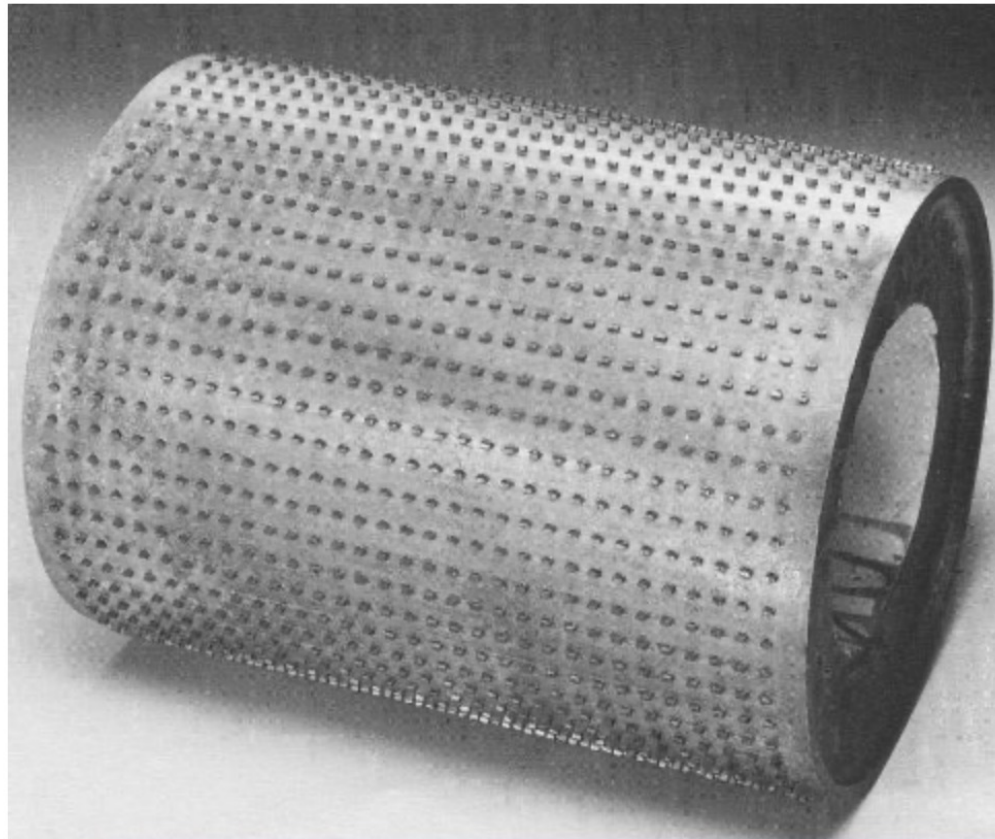


Magnetic core memory, probably from a 360

UCLA had 2 of these Model 91's (out of only 3 built) 1968-80

# Drum Storage

But did you know that the concept of regenerative capacitive memory was invented in the early 1940s? The very first electronic digital computer, [the ABC](#)  (Atanasoff–Berry computer), had a pair of drums, each containing 1600 capacitors that rotated on a common shaft once per second. The capacitors on each drum were organized into 32 "bands" of 50, so it could store 32 50-bit floating point numbers.



Picture from [ABC Computer - Notes](#) 

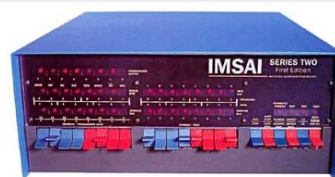
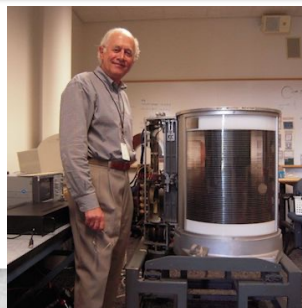
Each of the little squares is connected to a 0.0015  $\mu$ F paper capacitor



# Computers

ENIAC

44. ENIAC, the first computer ever built



DEC  
PDP/VAX



Google TPU



Apple  
Mac



Apple II



Data  
Center

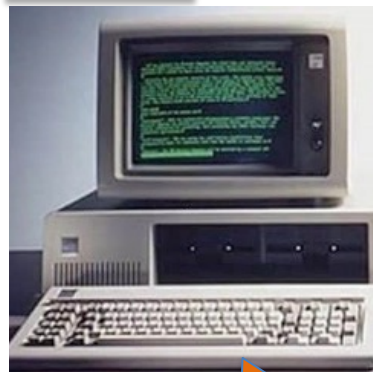


CDC



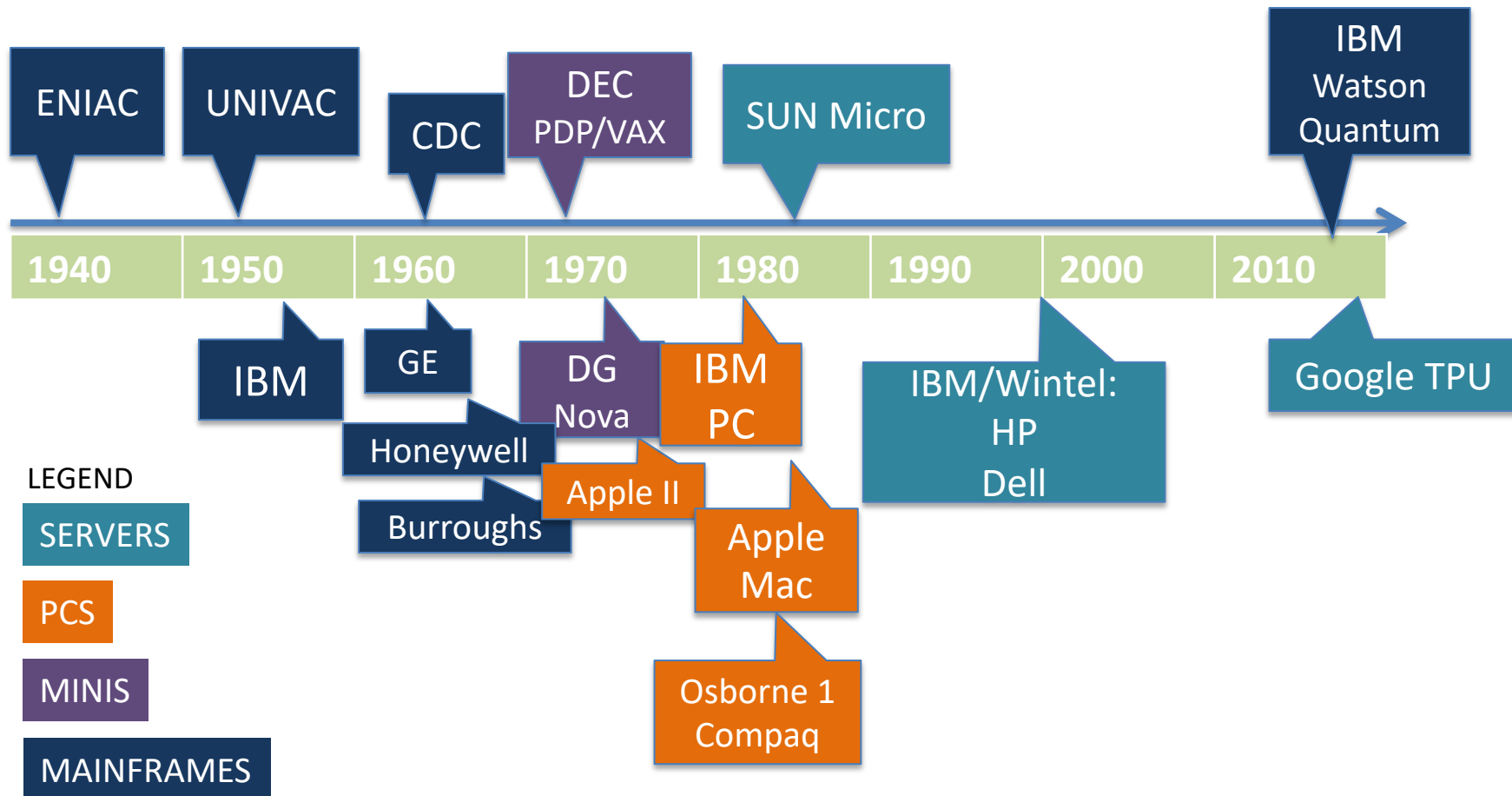
IBM 360

IBM PC



# Computers

## TIMELINE



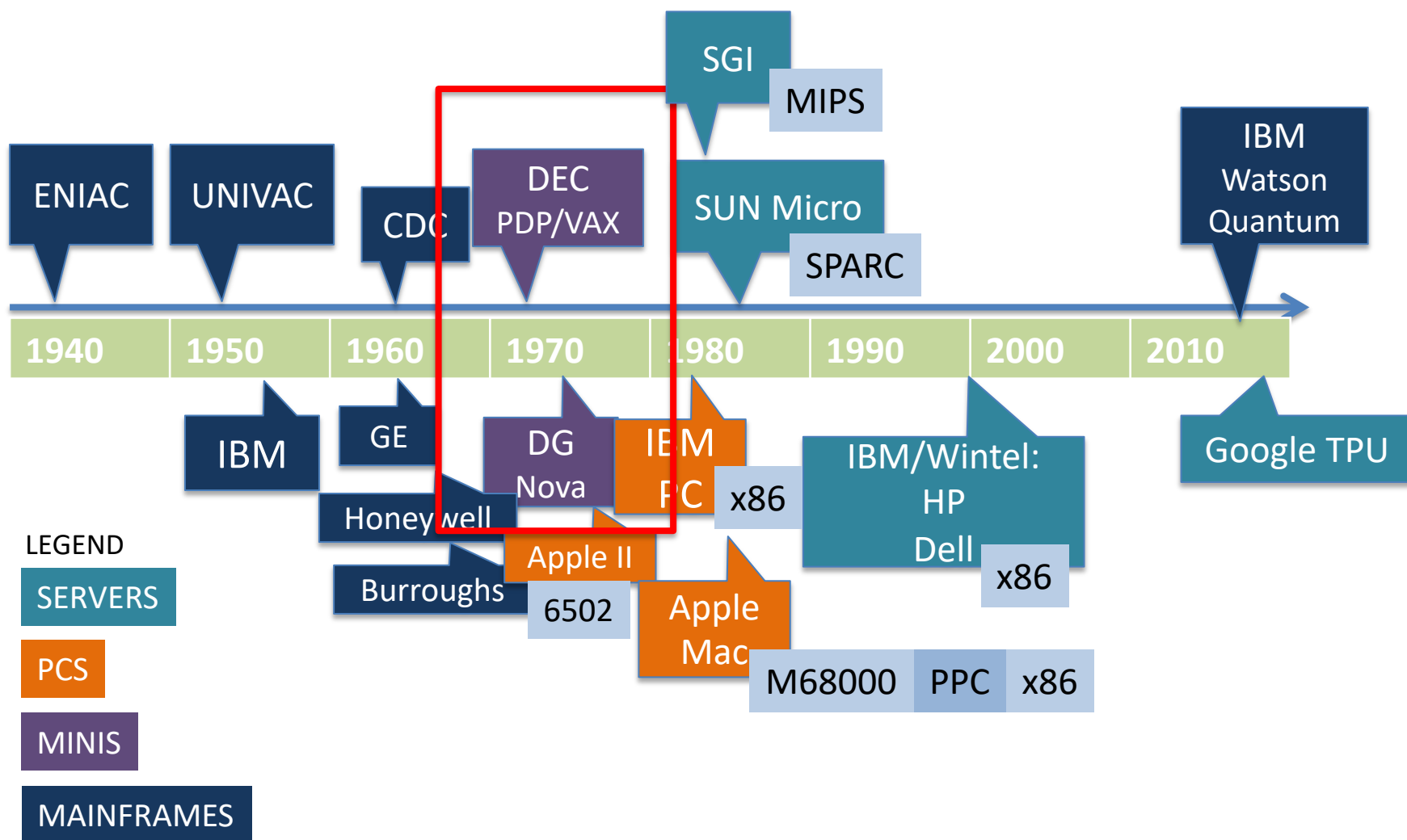


# Computers

Minicomputers of the 1970's  
Used Am2900 *bit-slices*

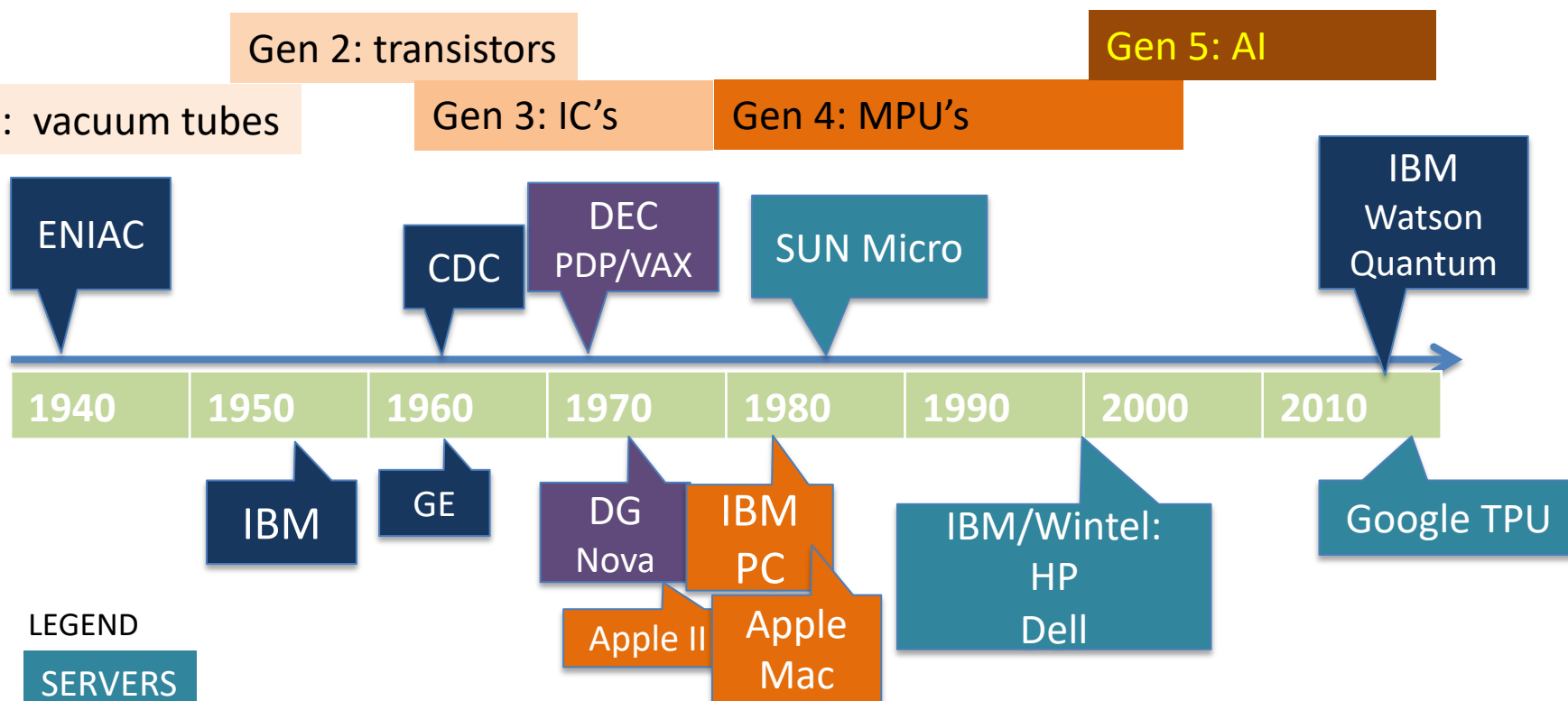
TIMELINE

Computers of the 1990's  
Used RISC CPU's



# Computer Generations

## TIMELINE



**1940 – 1956: First Generation – Vacuum Tubes**

**1956 – 1963: Second Generation – Transistors**

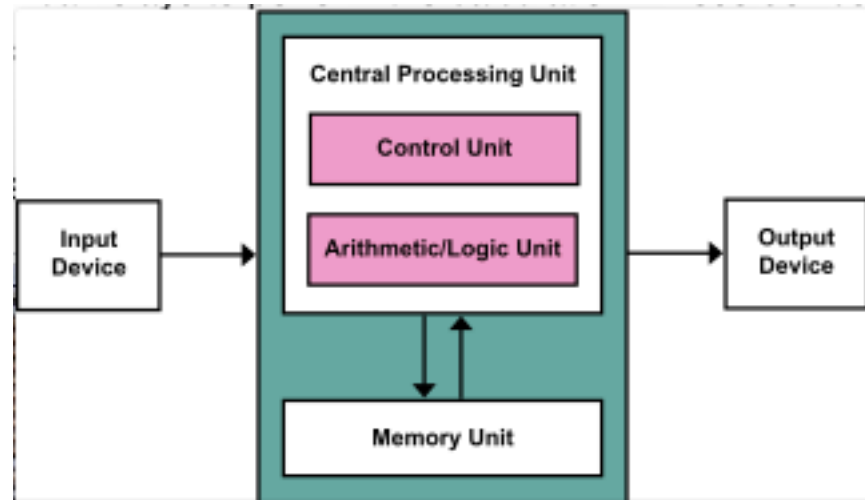
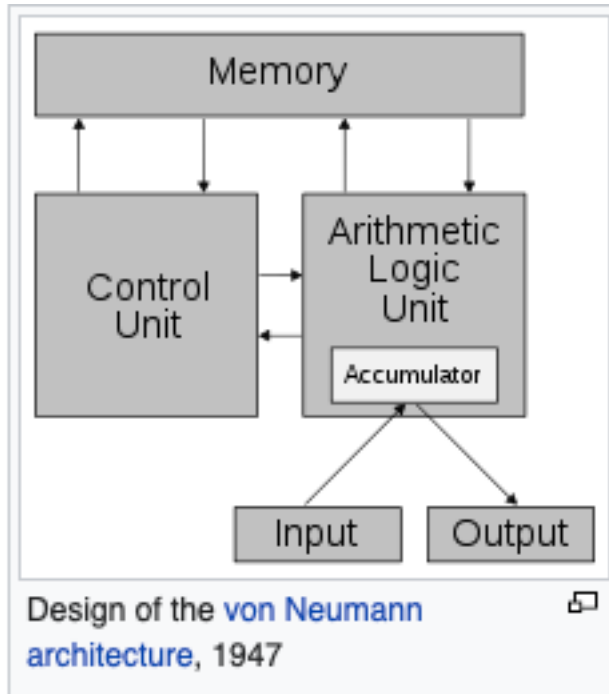
**1964 – 1971: Third Generation – Integrated Circuits**

**1972 – 2010: Fourth Generation – Microprocessors**

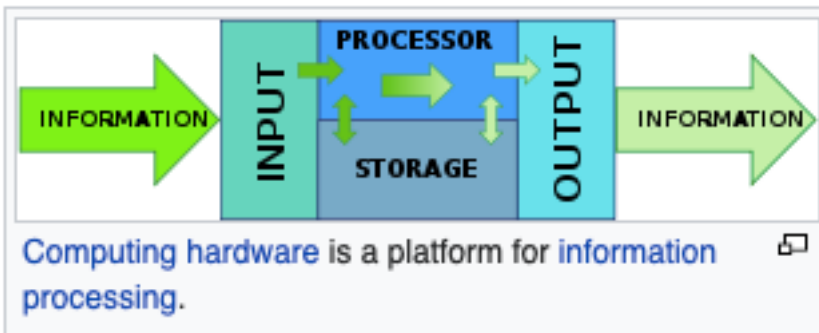
**2010- : Fifth Generation – Artificial Intelligence**

# 1<sup>st</sup> Gen Architecture

von Neumann



The **von Neumann architecture**—also known as the **von Neumann model** or **Princeton architecture**—is a computer architecture based on a 1945 description by Hungarian-American mathematician and physicist John von Neumann and others in the *First Draft of a Report on the EDVAC*. Th



# Old Computer Tech

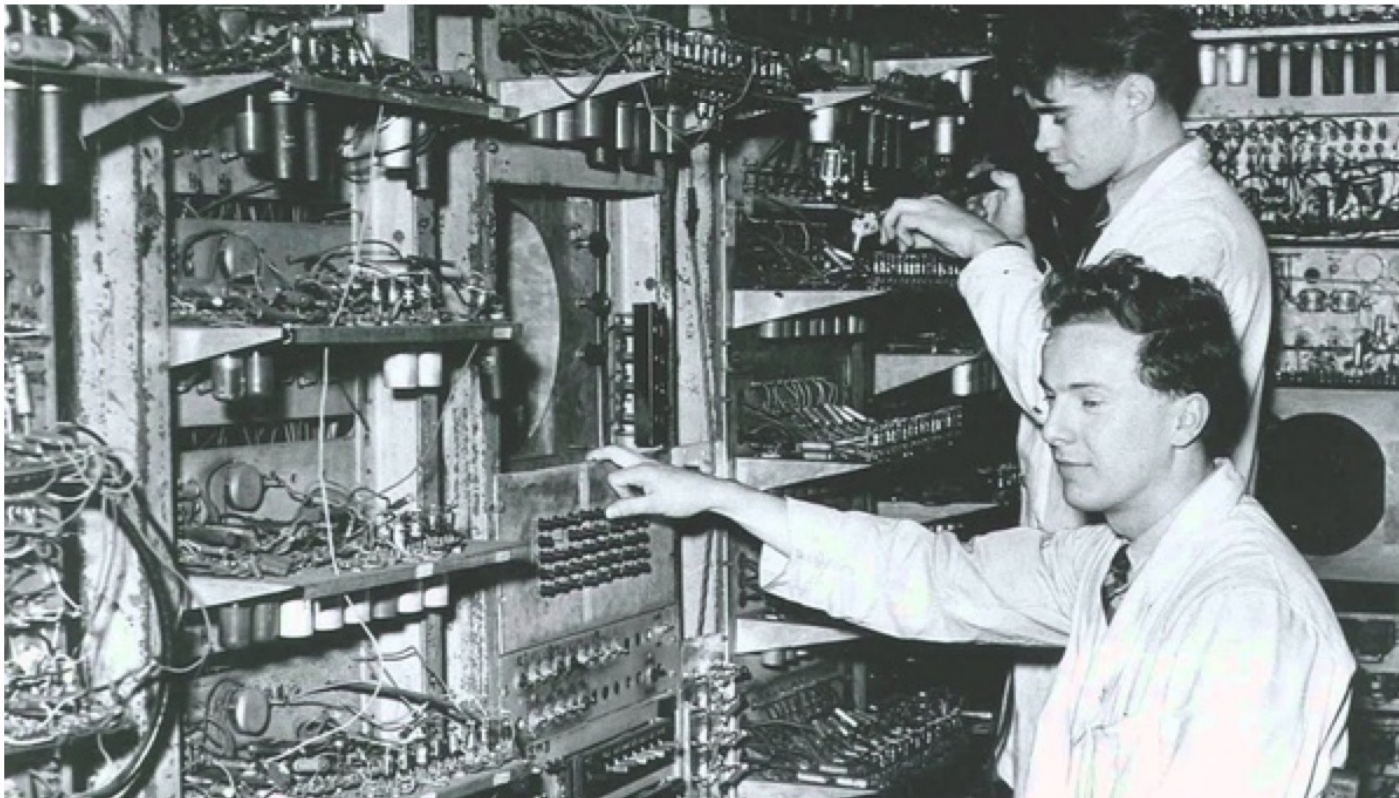
## Vacuum Tubes



**Richard Urwin**, Software engineer for 30+ years

Answered 9h ago

There were no very small components in the earliest computers. They used vacuum tubes.



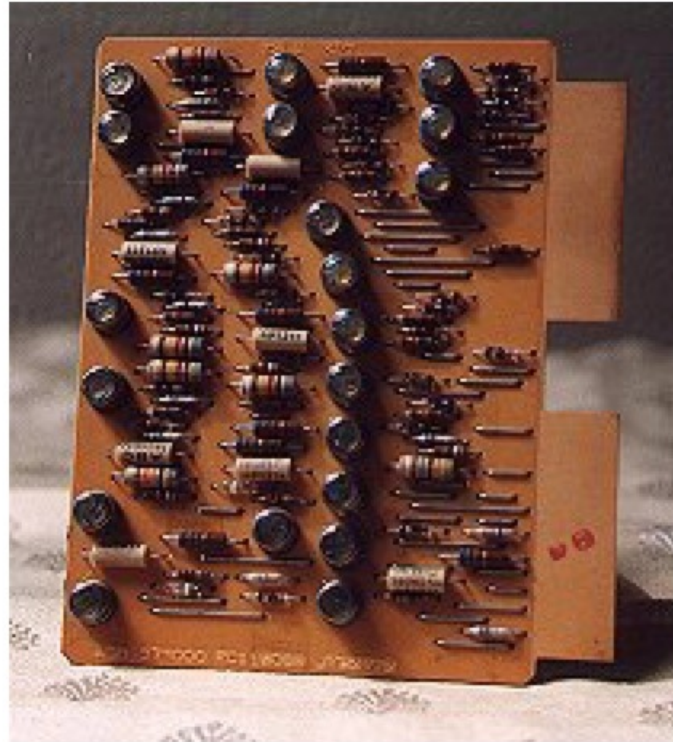
Each of the silver cylinders in the picture is a vacuum tube, approximately equivalent to a transistor. They were about an inch (2.5cm) across and two inches (5cm) high.



# Old Computer Tech

Discretes R/T

This is a circuit board from an IBM 7040, built in 1963.

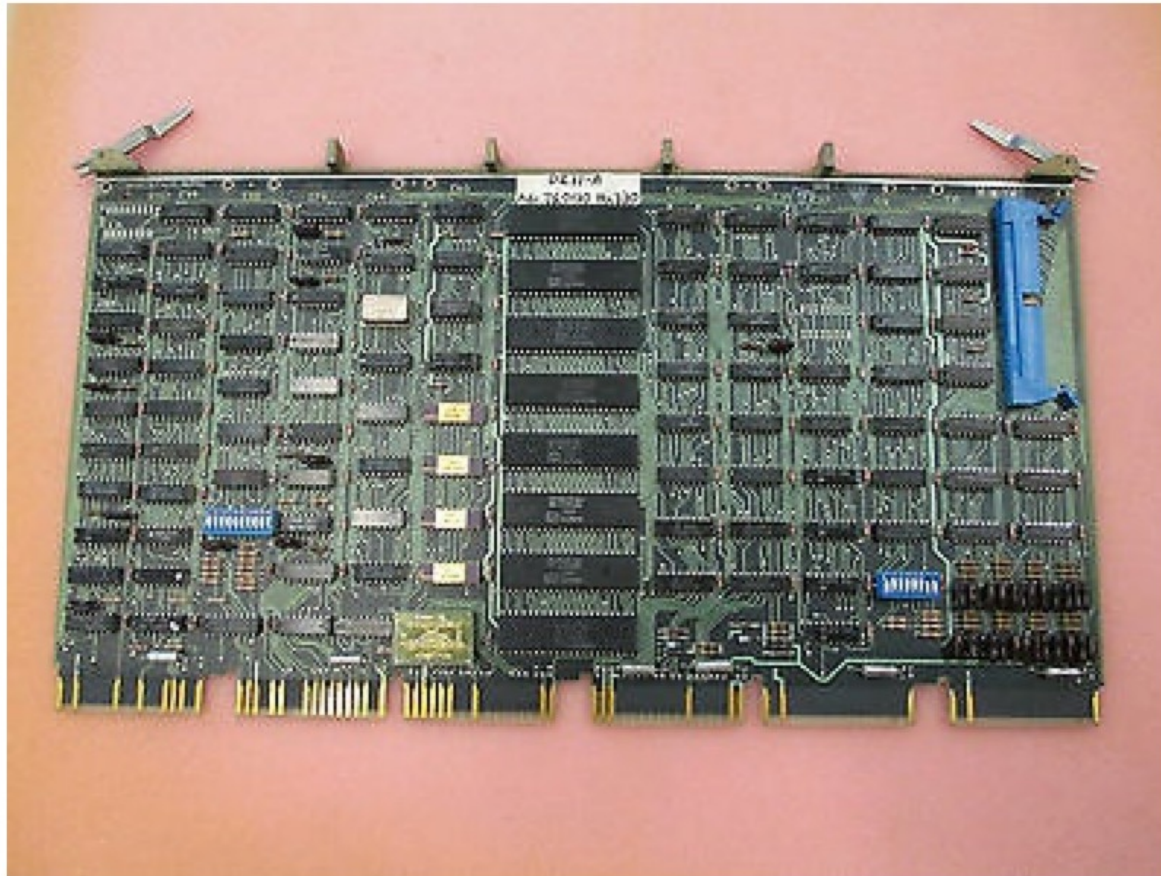


There are no small components there. Those horizontal cylinders are maybe half an inch (12mm) long.

# Old Computer Tech

MSI/LSI IC's

This is a serial interface board for a DEC PDP-11



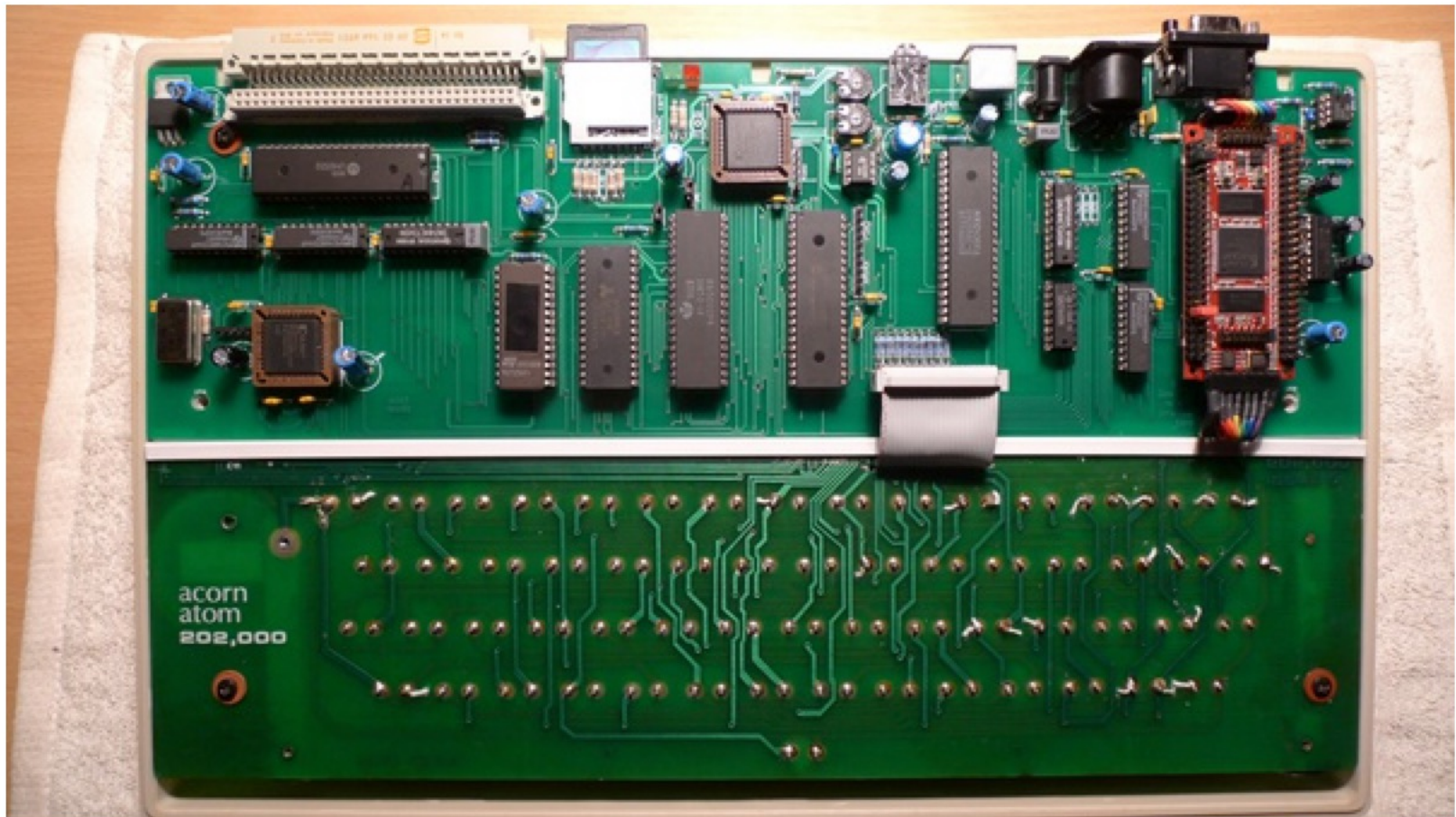
The integrated circuits were very simple with only a few dozen transistors in, so they didn't need very precise machines to make them. The boards could still be assembled by hand.



# Old Computer Tech

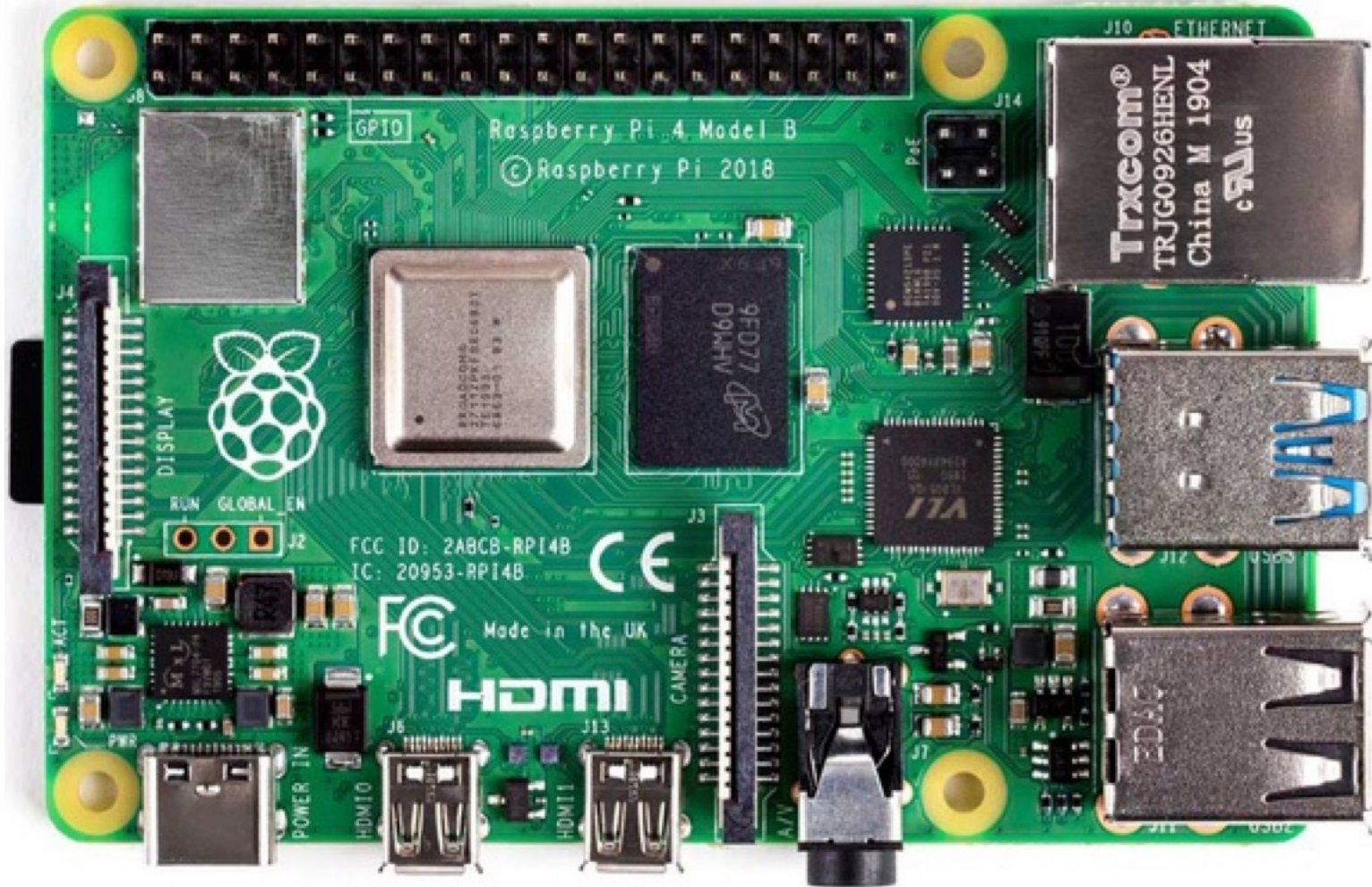
LSI IC's

This is the second computer I assembled, the Acorn Atom



# New Computer Tech

VLSI IC's







# Computers

---

Minis

DEC  
PDP/VAX

# DEC PDP-11

1<sup>st</sup> LSI-chip Computer

1970

Wiki

DEC  
PDP/VAX



Mag tape

PDP-11/40. The processor is at the bottom. A TU56 dual DECTape drive is installed above it.



# DEC PDP-8e

1<sup>st</sup> MSI-chip Computer

1965

DEC  
PDP/VAX



Here is a picture of one of the more popular versions, the PDP8/e. (By Florian Schäffer - Own work, CC BY-SA 4.0, [File:Digital pdp8-e2.jpg](#) ↗)



DEC  
PDP/VAX

# DEC PDP-11

1970

Wiki

**PDP-11**

From Wikipedia, the free encyclopedia  
(Redirected from [DEC PDP-11](#))

*This article is about the PDP-11 series of minicomputers. For the PDP-11 processor architecture, see [PDP-11 archi](#)*

The **PDP-11** is a series of [16-bit minicomputers](#) sold by [Digital Equipment Corporation](#) (DEC) from 1970 into the 1990s, one of a succession of products in the [PDP](#) series. In total, around 600,000 PDP-11s of all models were sold, making it one of DEC's most successful product lines. The PDP-11 is considered by some experts<sup>[1][2][3]</sup> to be the [most popular](#) minicomputer ever.

The PDP-11 included a number of innovative features in its [instruction set](#) and additional [general-purpose registers](#) that made it much easier to program than earlier models in the PDP series. Additionally, the innovative [Unibus](#) system allowed external devices to be easily interfaced to the system using [direct memory access](#), opening the system to a wide variety of [peripherals](#). The PDP-11 replaced the [PDP-8](#) in many [real-time applications](#), although both product lines lived in parallel for more than 10 years. The ease of programming of the PDP-11 made it very popular for general-purpose computing uses as well.

The design of the PDP-11 inspired the design of late-1970s microprocessors including the [Intel x86](#)<sup>[1]</sup> and the [Motorola 68000](#). Design features of PDP-11 operating systems, as well as other operating systems from Digital Equipment, influenced the design of other operating systems such as [CP/M](#) and hence also [MS-DOS](#). The first officially named version of [Unix](#) ran on the [PDP-11/20](#) in 1970. It is commonly stated that the [C programming language](#) took advantage of several low-level PDP-11-dependent programming features,<sup>[4]</sup> albeit not originally by design.<sup>[5]</sup>

An effort to expand the PDP-11 from 16 to 32-bit addressing led to the [VAX-11](#) design, which took part of its name from the PDP-11.

## No dedicated I/O instructions [\[ edit \]](#)

Early models of the PDP-11 had no dedicated [bus](#) for [input/output](#), but only a [system bus](#) called the [Unibus](#), as input and output devices were mapped to memory addresses.

An input/output device determined the memory addresses to which it would respond, and specified its own [interrupt vector](#) and [interrupt priority](#). This flexible

## Interrupts [\[ edit \]](#)

The PDP-11 supports hardware [interrupts](#) at [four priority levels](#). Interrupts are serviced by software service routines, which could specify whether they themselves [could be interrupted](#) (achieving [interrupt nesting](#)). The event that causes the interrupt is indicated by the device itself, as it informs the processor of the address of its own interrupt vector.

Interrupt vectors are blocks of two [16-bit words in low kernel address space](#) (which normally corresponded to low physical memory) between 0 and 776. The first word of the interrupt vector contains the [address of the interrupt service routine](#) and the second word the [value to be loaded into the PSW](#) (priority level) on entry to the service routine.

## Instruction set orthogonality [\[ edit \]](#)

See also: [PDP-11 architecture](#)

The PDP-11 processor architecture has a mostly [orthogonal instruction set](#). For example, instead of instructions such as *load* and *store*, the PDP-11 has a *move* instruction for which either operand (source and destination) can be memory or register. There are no specific *input* or *output* instructions; the PDP-11 uses [memory-mapped I/O](#) and so the same *move* instruction is used; orthogonality even enables moving data directly from an input device to an output device. More complex instructions such as *add* likewise can have memory, register, input, or output as source or destination.

Most operands can apply any of eight addressing modes to eight registers. The addressing modes provide register, immediate, absolute, relative, deferred (indirect), and indexed addressing, and can specify autoincrementation and autodecrementation of a register by one (byte instructions) or two (word instructions). Use of relative addressing lets a machine-language program be [position-independent](#).

DEC  
PDP/VAX

# DEC PDP-11

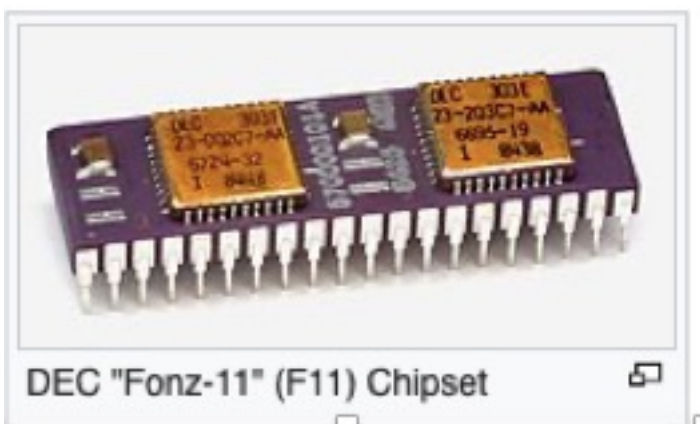
1970

Wiki

**LSI-11** [ [edit](#) ]

The LSI-11 (PDP-11/03), introduced in February 1975<sup>[10]</sup> is the first PDP-11 model produced using [large-scale integration](#); the entire CPU is contained on four LSI chips made by [Western Digital](#) (the [MCP-1600](#) chip set; a fifth chip can be added to

The CPU [microcode](#) includes a [debugger](#): firmware with a direct serial interface ([RS-232](#) or [current loop](#)) to a [terminal](#). This lets the operator do [debugging](#) by typing commands and reading [octal](#) numbers, rather than operating switches and reading lights, the typical debugging method at the time. The operator can thus examine and modify the computer's registers, memory, and input/output devices, diagnosing and perhaps correcting failures in software and peripherals (unless a failure disables the microcode itself). The operator can also specify which disk to [boot](#) from.





# DEC System 10



# K-202

Mini 1972

A printer, camera, radar



**Jacek Karpinski, creator of the K-202 minicomputer, at the Poznań International Fair, photo: Aleksander Jalosiński**



# K-202

Mini 1972



Photo on an advertising leaflet handed out in 1972 at the Poznań International Fair





# Computers

---

PC's

# Early PC

1974

## MITS Altair 8800



Altair 8800 Computer with 8-inch floppy disk

The **Altair 8800** is a [microcomputer](#) designed in 1974 by [MITS](#) and based on the [Intel 8080 CPU](#) at 2 MHz

# Apple I Computer

1976



**Robert Mudry**, Retired Silicon Valley engineering geek.

Shared Feb 6

## A Hand-Built, Original Apple 1 Computer Is Yours for Just 1.5 Million Dollars





# Early PC's

Commodore PET

1977



The Commodore PET 2001-8 alongside its rivals, the Apple II and the TRS-80 Model I



# Early PC

1977

## Commodore PET

A Commodore PET 2001

**Manufacturer** Commodore International

**Type** Personal computer

**Release date** January 1977; 44 years ago<sup>[1]</sup>

**Introductory price** US\$795 (equivalent to \$3,354 in 2019)<sup>[2]</sup>

**Discontinued** 1982; 39 years ago<sup>[3]</sup>

**Operating system** Commodore BASIC 1.0 ~ 4.0

**CPU** MOS Technology 6502 @ 1 MHz

**Memory** 4–96 KB

**Storage** cassette tape, 5.25-inch floppy, 8-inch floppy, hard disk

**Display** 40x25 or 80x25 text

**Graphics** monochrome character graphics

**Sound** none or beeper

**Successor** Commodore VIC-20



The chiclet keyboard of the PET 2001 series



Commodore 8028 Daisy wheel printer

# IBM Datamaster



IBM's System 23 Datamaster, pictured here at the IBM Hursley Museum, cost \$9,000 US



# IBM PC

1981

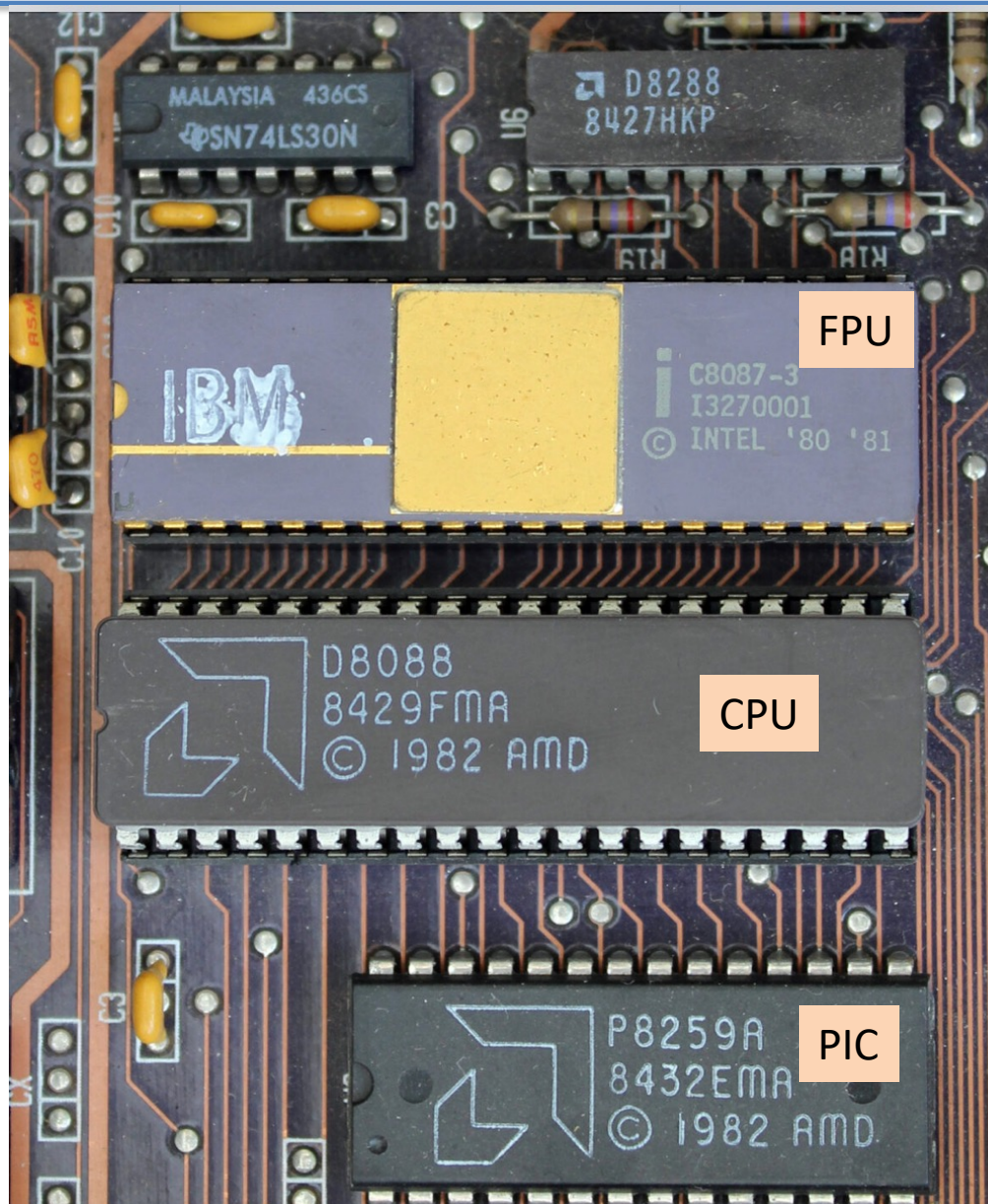
- ❖ Designed and built by IBM (Boca Raton, FL) in 1981
- ❖ CPU: **i8088** (i8086 with an 8-bit data bus)
- ❖ Speed: 4.77 MHz
- ❖ Memory – DRAM: 64KB (48KB soldered, 16KB socketed)
- ❖ Disk: 5.25 inch floppy – 2 drives (A:, B:)
- ❖ OS: MS/PC-DOS (derived from CP/M)

## The IBM PC



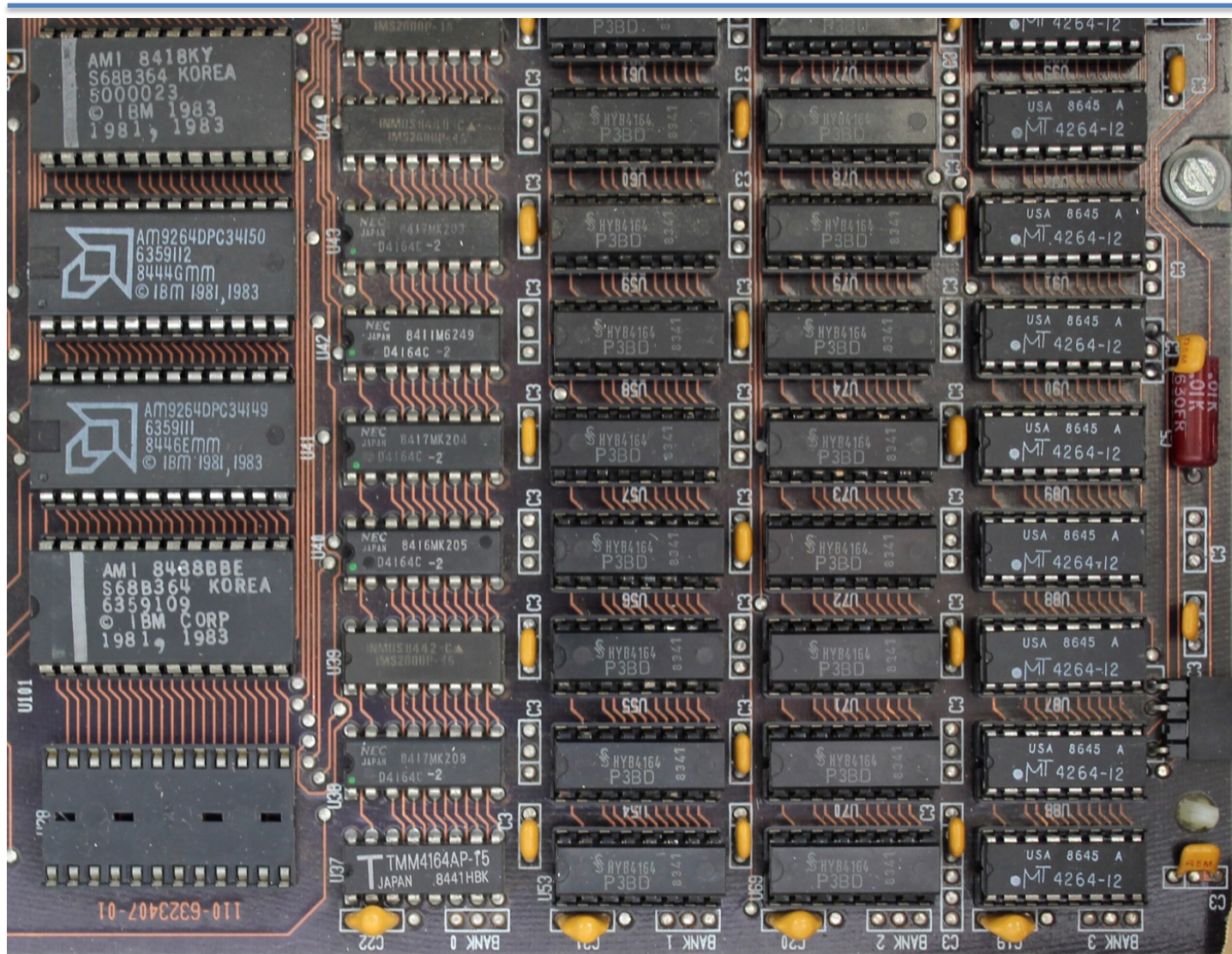
# IBM PC Chips

1981





# IBM PC – Large Motherbd



The memory is organised in four banks in the bottom right corner of the motherboard – in this case there are four 64KB banks, adding up to a total of 256KB



# Osborne 1 Portable PC

1981

## Osborne 1

From Wikipedia, the free encyclopedia

The **Osborne 1** is the first commercially successful portable [microcomputer](#), released on April 3, 1981 by [Osborne Computer Corporation](#).<sup>[1]</sup> It weighs 10.7 kg (24.5 lb), cost US\$1,795, and runs the [CP/M 2.2](#) operating system. It is powered from a [wall socket](#), as it has no on-board battery, but it is still classed as a portable device since it can be hand-carried when packed.

The computer shipped with a large bundle of software that was almost equivalent in value to the machine itself, a practice adopted by other CP/M computer vendors. Competitors quickly appeared, such as the [Kaypro II](#).



Compaq followed Osborne when founded in Feb 1982, and produced the first widely successful "portable" computer. I recall seeing at the Compaq booth at Comdex in Las Vegas in 1983. It ran Lotus 123 as a demo, both in Compaq's booth and in Lotus's booth. reason was Ben Rosen was VC who funded both companies. Ben Rosen met me there, and introduced me to both company founders, Mitch Kapor and Rod Canion.

# Osborne 1 Portable PC

1981

## Osborne 1



<b>Developer</b>	Adam Osborne
<b>Manufacturer</b>	Osborne Computer Corporation
<b>Type</b>	Portable computer
<b>Release date</b>	April 3, 1981; 39 years ago
<b>Introductory price</b>	US\$1795 (today \$5047.94)
<b>Discontinued</b>	1983
<b>Operating system</b>	CP/M
<b>CPU</b>	Zilog Z80 @ 4.0 MHz
<b>Memory</b>	64 KB RAM

# Osborne 1 Portable PC



**DR JEFF**  
**SOFTWARE**  
INDIE APP DEVELOPER

Jeff Drobman  
©2016-23

1981



**Lee Felsenstein** · Updated July 25, 2019  
Electronic design engineer, PC pioneer

Designer

## **The laptop was invented by Adam Osborne in 1981. Why is Adam Osborne not as well known as Steve Jobs and/or Steve Wozniak?**

I designed the Osborne-1, and was a founder of the company (part of my compensation for the design). It was intended not so much as a portable computer to be used "on the go" but as a self-contained CP/M computer which could hold its software disk library internally and make minimal demands on its owner for configuration and customization.

The weight was not 55 or 60 pounds - it was 23.5 pounds, and it created the class of computers that become known as "luggables". Someone once commented that most were only carried from one side of the office to the other. We never considered it a "laptop", though we were in discussions with multiple Japanese companies for years working toward a laptop.

I was aware of Alan Kay's "Dynabook" conceptual design at the time (1980) and attempted to advocate making that our design goal, but adequate flat-panel displays were not then available (just look at the small display on the Epson HX-20) and the cost of memory ICs did not then permit a graphic display.

I describe the Osborne-1 as "the first commercially successful portable computer" - others had been sold before with handles on them and IBM called their 1975 5100 a "Portable computer" (with cartridge tape storage and a price tag in the several thousands of dollars) but it did not provide an interoperable operating system).

Osborne Computer Corporation announced their first product in March 1981 and entered chapter 11 bankruptcy in September of 1983. If the company had been managed properly it might still be in business today. Innovators are not the ones in



# Apple

1984

## The Macintosh



Apple II

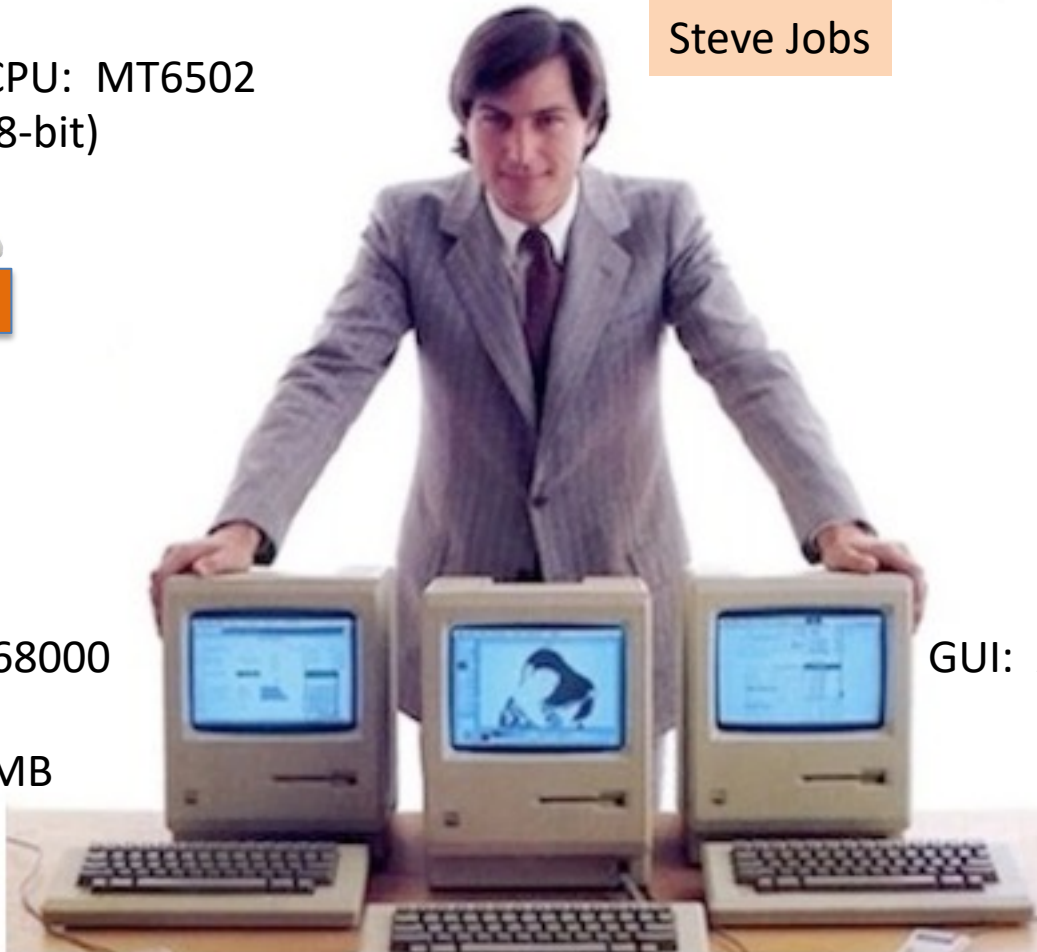
CPU: MT6502  
(8-bit)

Wozniak

Steve Jobs

CPU: M68000  
(16-bit)  
RAM: 1MB

GUI: Xerox PARC (Alan Kay)



# Microsoft's New PC's



**DR JEFF**  
**SOFTWARE**  
INDIE APP DEVELOPER

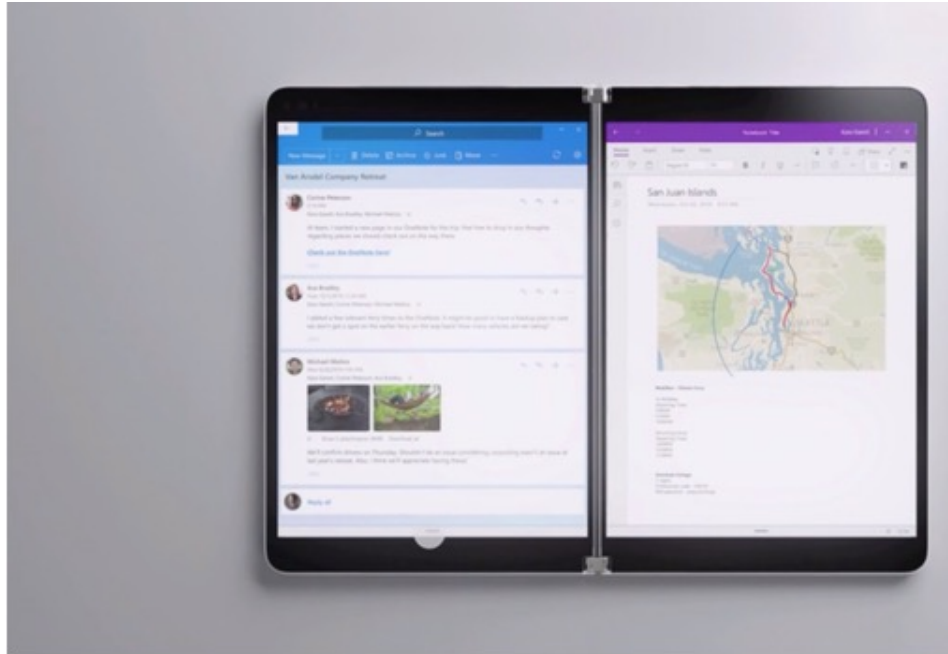
Jeff Drobman  
©2016-23



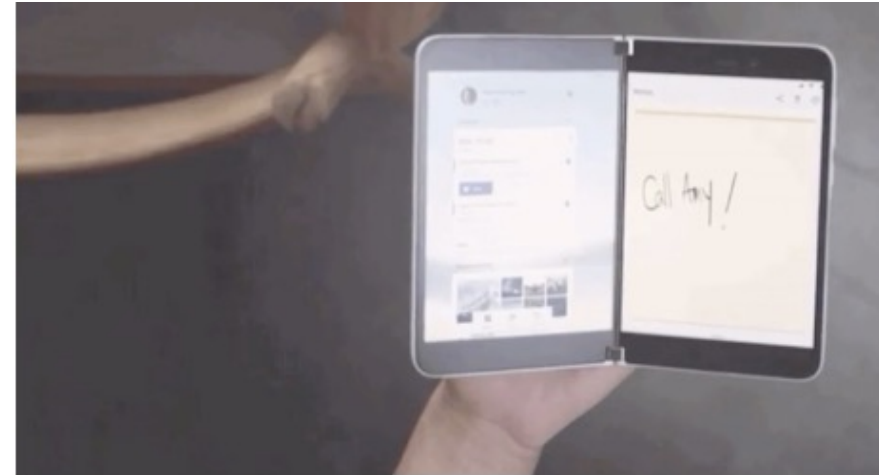
Microsoft's Surface Laptop 3 is 3x more powerful than a MacBook Air

See this

# Microsoft's New PC's



'This is Surface Duo': Yes, Microsoft will release a dual-screen phone



The new Microsoft phone, the Surface Duo.

Microsoft

Microsoft is making a phone. Again.



# Microsoft's New PC's

Microsoft is making a phone. Again.

The tech giant, which stopped producing phones years ago, is hoping to stage a comeback with the Surface Duo. As the name suggests, the device has two screens, connected by a hinge. (Here's how the Surface Duo compares to the Galaxy Fold.)

"This product brings together the absolute best of Microsoft, and we're partnering with Google to bring the absolute best of Android in one product," said Microsoft Product Chief Panos Panay. "This is industry-pushing technology."



**Now playing:** Microsoft unveils Surface Duo, a foldable Android phone

▶  
4:58

The whole thing is a bit of a surprise, considering Microsoft eventually gave up making phones after its troubled 2014 purchase of phone giant Nokia for more than \$7 billion. This time, Microsoft says its new innovations, like the dual-screen folding display and special technology it built for the Google Android software that powers the gadget, will help make the difference. We won't know for sure until the Surface Duo is released next year.

# Microsoft's New PC's

---

## Everything announced

- **Surface Duo:** Microsoft is making a dual-screen Android phone called Surface Duo. Yes, that Microsoft.

The company known for its Windows operating system is getting back into smartphones by embracing its rival's ecosystem.

- **Surface Neo:** Dual-screen Microsoft Surface Neo is coming, eventually.

Like other Windows 10 X systems, this dual-screen Surface isn't likely to be in stores till the 2020 holiday season.

- **Windows 10 X:** Windows 10 X OS will work with new dual-screen Surface Neo devices.

The dual-screen Surface Neo gadgets will be out next year, says Microsoft.

- **Surface Laptop 3:** Microsoft announced a laptop 3x more powerful than the MacBook Air.

Microsoft's Surface Laptop 3 has USB-C, a bigger screen and a modular design. It comes in 13.5- and 15-inch models and starts at \$999.

- **Surface Pro X and Surface Pro 7:** Microsoft unveils \$999 Surface Pro X, a tablet with a phonelike Windows experience.

We also got a minimal update for the Surface Pro 7, now with USB-C.

- **SQ1 custom Arm chip:** Microsoft tries Windows on Arm chips again with the SQ1-powered Surface Pro X.

The chips are designed to consume less power than those from Intel, Microsoft's traditional partner.

# Microsoft's New PC's

The Surface Laptop 3 has a custom Ryzen Surface Edition processor on the 15-inch model, while the Surface Pro X goes the ARM-powered route with a new SQ1 processor co-engineered with Qualcomm. It's a big change for the Surface line, even if Intel will still power the Surface Pro 7 and the smaller 13-inch Surface Laptop 3 models.

ARM ← New Windows!

AMD Ryzen

## Inside Microsoft's new custom Surface processors with AMD and Qualcomm

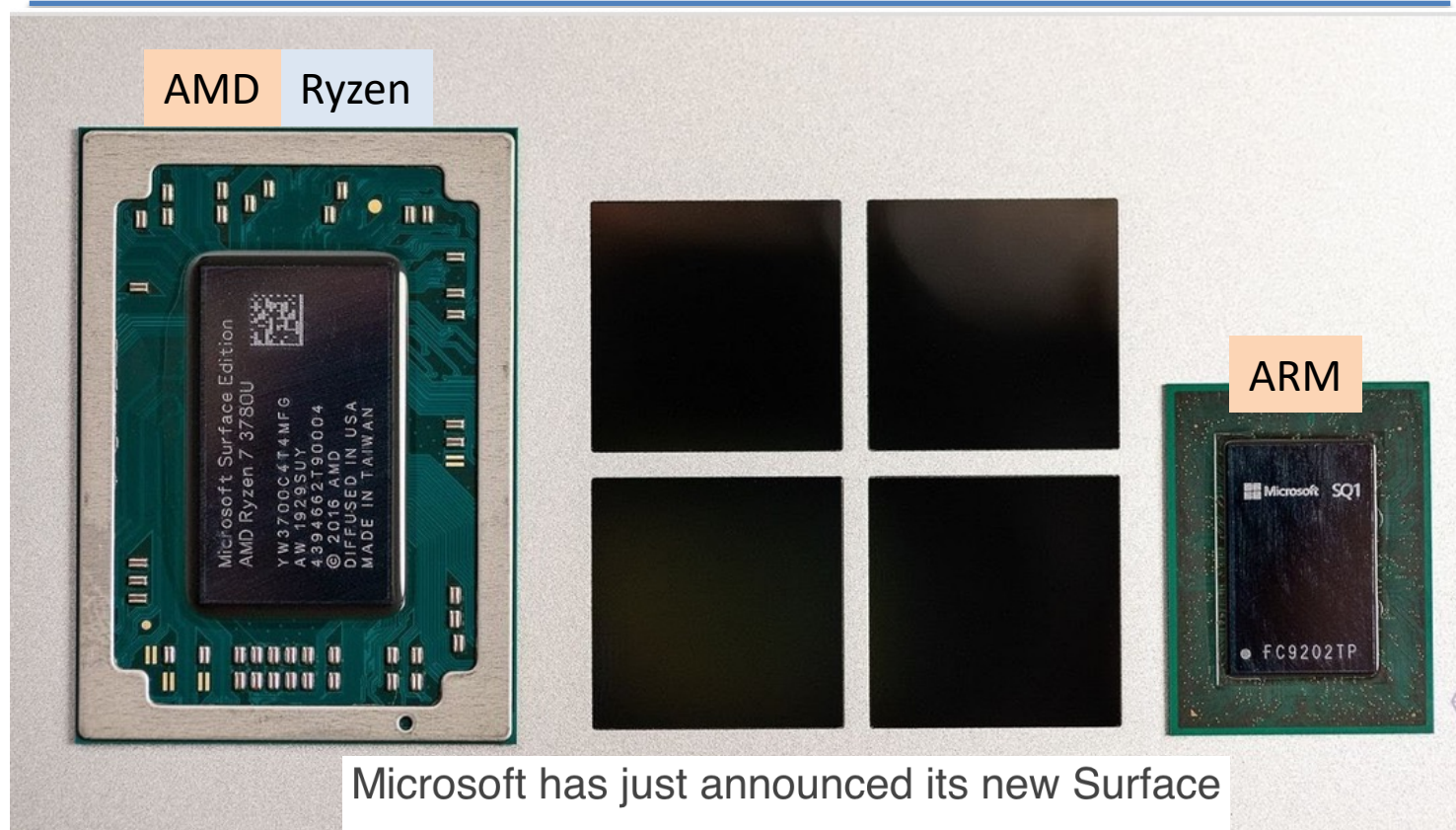
*Surface Ryzen Edition and SQ1 processors have been co-engineered*

By [Tom Warren](#) on October 2, 2019 11:30 am

On the AMD side, this Ryzen processor will be available exclusively in the 15-inch model of the Surface Laptop 3, a notebook that also has a metal finish instead of the fabric we've seen on previous Surface Laptop models. Microsoft has worked closely with AMD to add an additional graphics core on the 12nm Ryzen 5 and Ryzen 7 Surface parts that are built on Zen+, and to optimize the chip to fit inside the slim-and-light chassis it uses for the Surface Laptop 3.



# Microsoft's New PC's



Microsoft has just announced its new Surface Laptop 3 and Surface Pro X devices, and neither will come with an Intel processor. The software giant is diversifying its silicon for Surface this year by partnering closely with AMD and Qualcomm, respectively, to create custom processors for its Surface line.

# Prices for Top CPU's

## THE BEST CPUS AT THE BEST PRICE

AMD Ryzen 7 2700X Processor with Wraith Prism LED Cooler – YD270XBGAFBOX



amazon.com

~~\$329.00~~  
**\$236.46**

VIEW

Intel Core i5-8500 Desktop Processor 6 Core up to 4.1GHz Turbo LGA1151 300 Series 65W



amazon.com

**\$239.97**

VIEW

Intel Core i9-9900K Desktop Processor 8 Cores up to 5.0 GHz Turbo unlocked LGA1151 300 Series 95W



amazon.com

**\$494.99**

VIEW

# Intel Systems: NUC 11



Intel Core i5/7 CPU's + GPU's

The [Intel](#) Phantom Canyon NUC 11 Extreme features a Tiger Lake-U 28W Core i7 or Core i5 processor. Both processors will be equipped with the latest generation of integrated Intel GPU Xe graphics processors.



# Intel Systems: NUC 11

---

## CPU

NUC 11 Extreme has a CPU with 4 cores and 8 threads, which has a clock base of 2.3 GHz and a maximum boost of 4.4 GHz. When tested with 3DMark, this CPU **scores about 4,590 points, which is slightly lower than the Core i7-1165G7 CPU.**

## GPU

The Intel Canyon NUC 11 Extreme will use a discrete GPU in addition to the Intel Xe GPU. The American company plans to embed an NVIDIA GTX 1660 TI 80W GPU with 1,536 CUDA cores and a GPU clock frequency of around 1600 MHz.

## RAM

Users will also receive RAM support up to DDR4-3200 with a capacity of up to 64 GB. Users will also receive 2 M.2 slots (1x 22×80 / 110 & 1x 22×80) and a **PCIe** x4 Gen 3 NVMe connector.

## I/O

Front and rear extensions are equally plentiful, including two Thunderbolt 3, HDMI 2.0, MiniDP 1.4, and many USB extensions that also support an 8K output. Also available on the rear is a 2.5 Gbps Gigabit LAN (Intel solution) with IEEE 802.11ax (Intel Wireless-AX 201), WiFi 6 Wireless, Bluetooth 5.0 and more.

# Industrial PC's

Introducing...

## LITESHIELD 2.0

our newest industrial  
product line.

**NO FANS. NO PROBLEM.**



[> VIEW THIS PRODUCT](#)

[Why fanless? >](#)

**Up to intel i9 capability.**  
**8 cores/16 threads**  
**wi-fi.**  
**4k on dual displays.**  
**Rigid aluminum enclosure.**  
**Optional Internal 2.5" SSD slot.**  
**100% fanless. 100% silent.**



# Industrial PC's



**Nuvo Series**

- Intel® 9th/8th-Gen CPU
- Core™ i7/i5/i3
- Fanless Box PC
- Multi-PoE & GbE

Rugged Computer



**Nuvo VTC Series**

- Intel® 9th/8th-Gen CPU
- Isolated CAN bus
- Isolated DIO
- E-Mark & EN50155

In-vehicle PC



**Nuvis Series**

- Core™ i7/i5
- Deterministic I/O
- Real-time Control
- NVIDIA® 75W GPU

Machine Vision



**Nuvo GC Series**

- Intel® 9th/8th-Gen CPU
- 250W GPU or Tesla T4
- M.2 2280 NVMe socket
- Wide-temp Operation

GPU Computing

Intel Core i3/5/7 CPU's

+Nvidia GPU's



# Computers

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HPC

\*see separate slide set

# Hardware

---

## Quantum Computers

\*see separate slide set

# Quantum Computers (QC)



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## Outlook

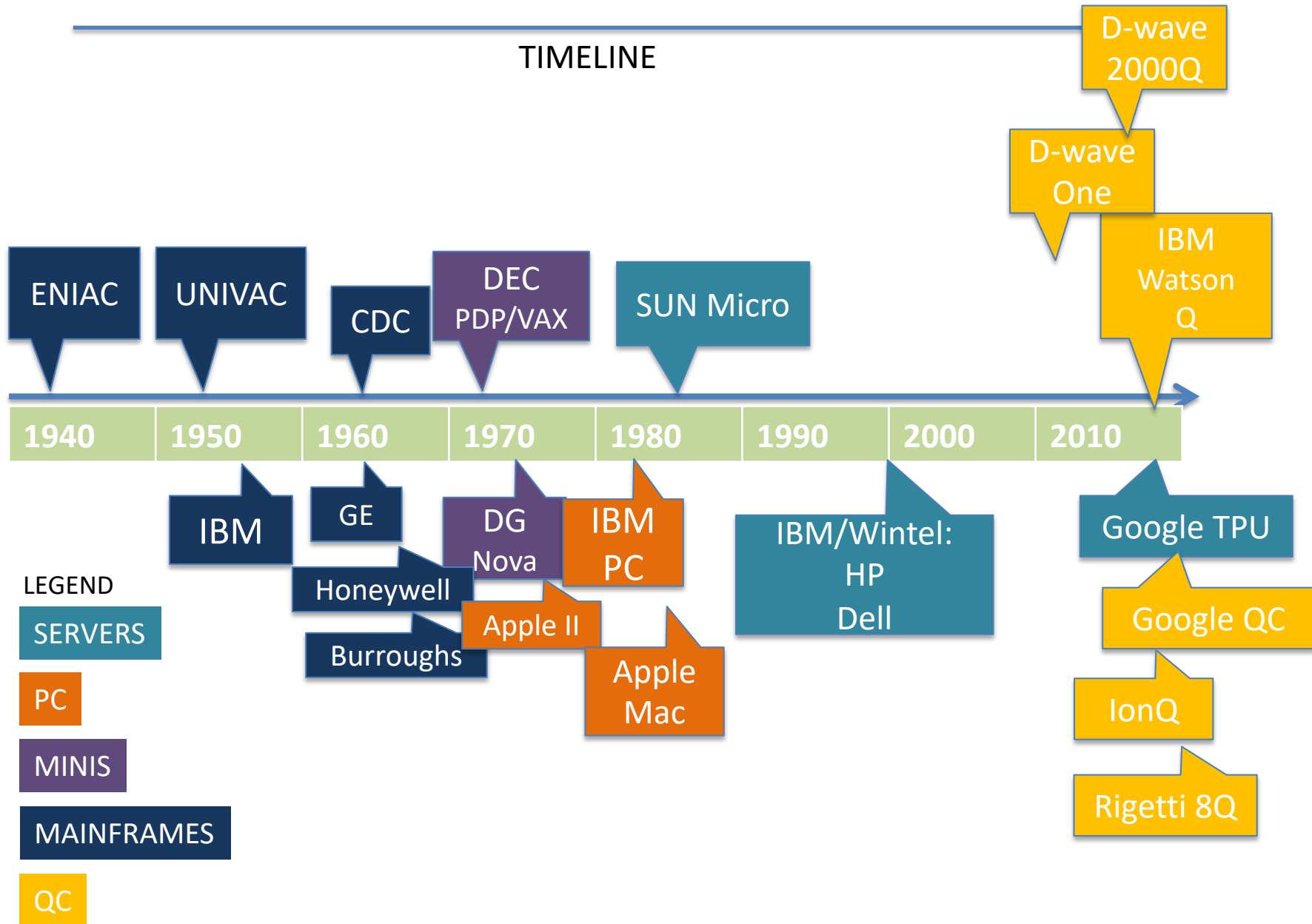
- ❖ Google
- ❖ IBM
- ❖ Intel
- ❖ Microsoft

Businesses are hoping the advancement of quantum computers—by tech giants such as Google, [IBM](#), and [Intel](#), as well as startups such as Rigetti Computing—will lead to unprecedented scientific and technical breakthroughs in the coming years. They're eyeing applications from new chemical reactions for the development of drugs, fertilizers, and batteries, to the improvement of optimization algorithms and mathematical modeling.



# Computers & QC's

## TIMELINE



# Commercial QC's

## List of quantum processors

From Wikipedia, the free encyclopedia

### Circuit-based quantum processors [\[ edit \]](#)

These QPUs are based on the [quantum circuit](#) and [quantum logic gate](#)-based [model of computing](#).

Manufacturer ↕	Name/Codename/Designation ↕	Architecture ↕	Layout ↕	Socket ↕	Fidelity ↕	Qubits ↕	Release date ↕
<a href="#">Google</a>	N/A	<a href="#">Superconducting</a>	N/A	N/A	99.5% <sup>[1]</sup>	20 qb	2017
<a href="#">Google</a>	N/A	<a href="#">Superconducting</a>	7×7 lattice	N/A	99.7% <sup>[1]</sup>	49 qb <sup>[2]</sup>	Q4 2017 (planned)
<a href="#">Google</a>	Bristlecone	<a href="#">Superconducting</a>	6×12 lattice	N/A	99% (readout) 99.9% (1 qubit) 99.4% (2 qubits)	72 qb <sup>[3][4]</sup>	5 March 2018
<a href="#">Google</a>	Sycamore	Nonlinear <a href="#">superconducting</a> resonator	N/A	N/A	N/A	54 transmon qb 53 qb effective	2019

# Commercial QC's

IBM	IBM Q 5 Tenerife	Superconducting	bow tie	N/A	99.897% (average gate) 98.64% (readout)	5 qb	2016 <sup>[1]</sup>
IBM	IBM Q 5 Yorktown	Superconducting	bow tie	N/A	99.545% (average gate) 94.2% (readout)	5 qb	
IBM	IBM Q 14 Melbourne	Superconducting	N/A	N/A	99.735% (average gate) 97.13% (readout)	14 qb	
IBM	IBM Q 16 Rüschlikon	Superconducting	2x8 lattice	N/A	99.779% (average gate) 94.24% (readout)	16 qb <sup>[5]</sup>	17 May 2017 (Retired: 26 September 2018) <sup>[6]</sup>
IBM	IBM Q 17	Superconducting	N/A	N/A	N/A	17 qb <sup>[5]</sup>	17 May 2017
IBM	IBM Q 20 Tokyo	Superconducting	5x4 lattice	N/A	99.812% (average gate) 93.21% (readout)	20 qb <sup>[7]</sup>	10 November 2017
IBM	IBM Q 20 Austin	Superconducting	5x4 lattice	N/A	N/A	20 qb	(Retired: 4 July 2018) <sup>[6]</sup>
IBM	IBM Q 50 prototype	Superconducting	N/A	N/A	N/A	50 qb <sup>[7]</sup>	
IBM	IBM Q 53	Superconducting	N/A	N/A	N/A	53 qb	October 2019



# Commercial QC's

Rigetti	8Q Agave	Superconducting	N/A	N/A	N/A	8 qb	4 June 2018 <sup>[11]</sup>
Rigetti	16Q Aspen-1	Superconducting	N/A	N/A	N/A	16 qb	30 November 2018 <sup>[11]</sup>
Rigetti	19Q Acorn	Superconducting	N/A	N/A	N/A	19 qb <sup>[12]</sup>	17 December 2017

IBM	IBM Ourense <sup>[13]</sup>	Superconducting	T	N/A	N/A	5 qb	03 July 2019
IBM	IBM Vigo <sup>[13]</sup>	Superconducting	T	N/A	N/A	5 qb	03 July 2019
IBM	IBM London <sup>[13]</sup>	Superconducting	T	N/A	N/A	5 qb	13 September 2019
IBM	IBM Burlington <sup>[13]</sup>	Superconducting	T	N/A	N/A	5 qb	13 September 2019
IBM	IBM Essex <sup>[13]</sup>	Superconducting	T	N/A	N/A	5 qb	13 September 2019

## Annealing quantum processors [\[ edit \]](#)

These QPUs are based on [quantum annealing](#).

Manufacturer ↕	Name/Codename/Designation ↕	Architecture ↕	Layout ↕	Socket ↕	Fidelity ↕	Qubits ↕	Release date ↕
D-Wave	D-Wave One (Ranier)	Superconducting	N/A	N/A	N/A	128 qb	11 May 2011
D-Wave	D-Wave Two	Superconducting	N/A	N/A	N/A	512 qb	2013
D-Wave	D-Wave 2X	Superconducting	N/A	N/A	N/A	1152 qb	2015
D-Wave	D-Wave 2000Q	Superconducting	N/A	N/A	N/A	2048 qb	2017
D-Wave	D-Wave Advantage	Superconducting	N/A	N/A	N/A	5000 qb	2020

# Computer Architecture

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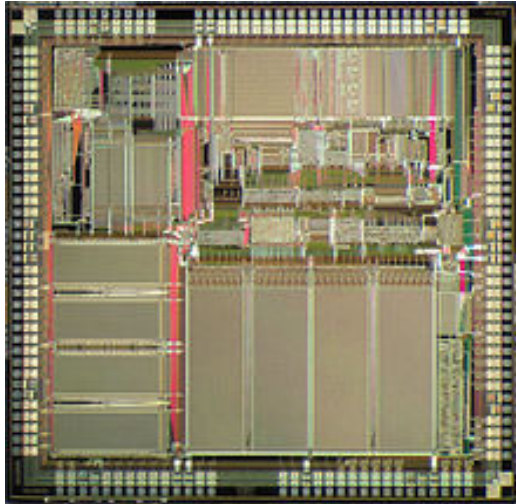


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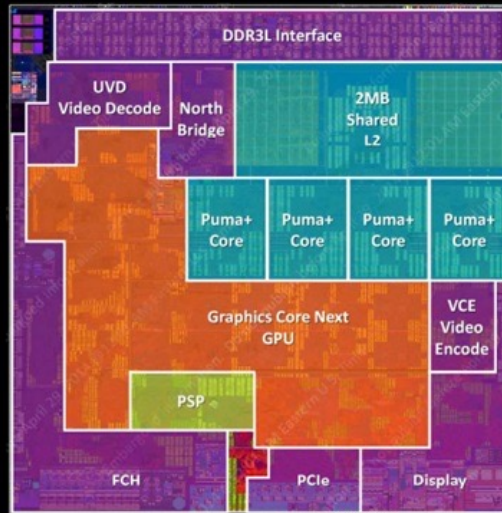
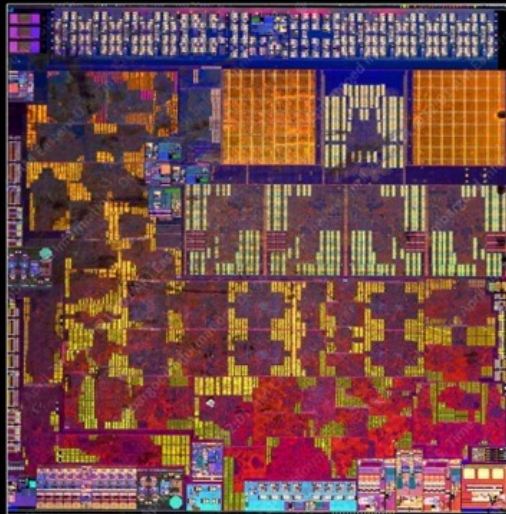
## Modern Microprocessors **AMD**

# Modern CPUs



ARM 610

AMD “Mullins” APU



Intel “Westmere” CPU

The Westmere Die, a processor introduced by Intel in 2010. Intel



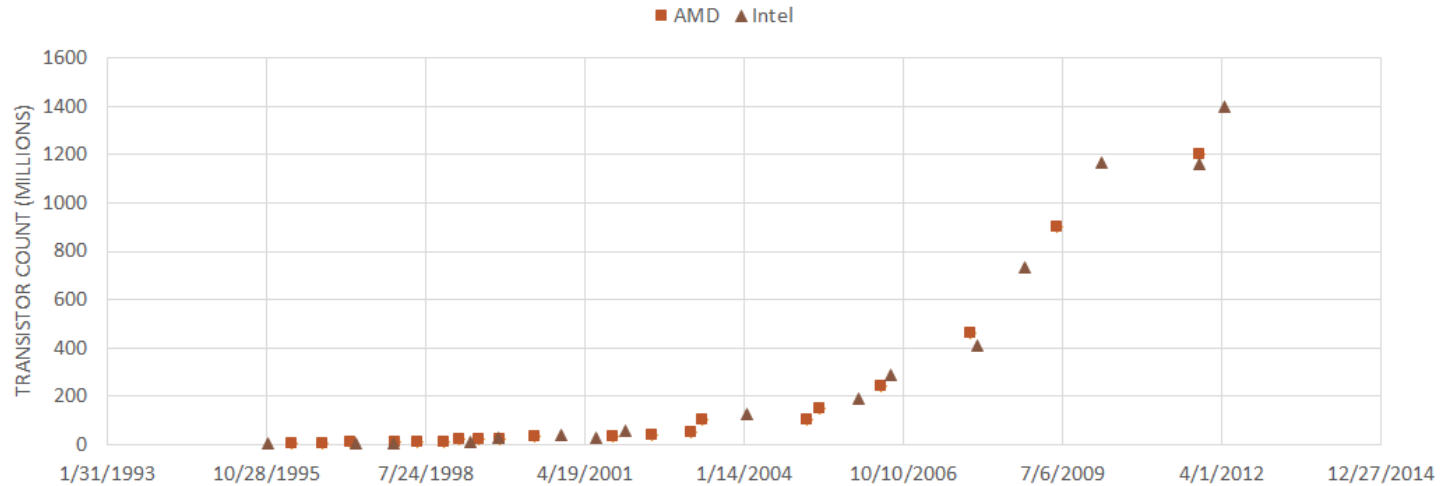
# AMD vs. Intel



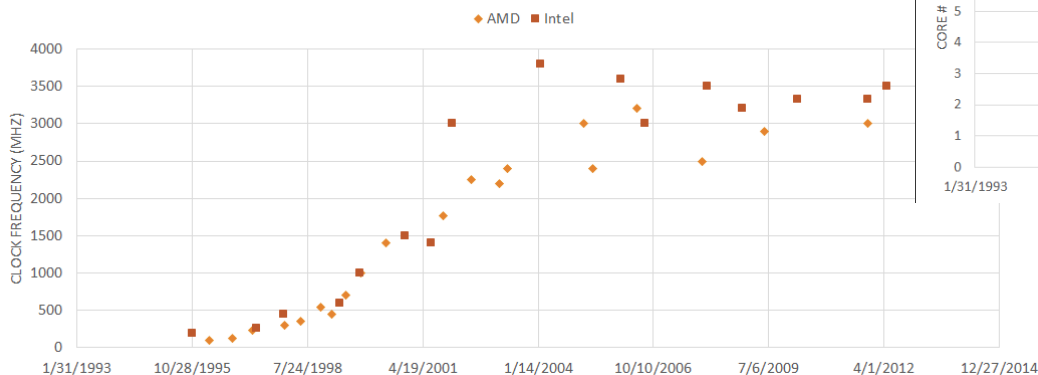
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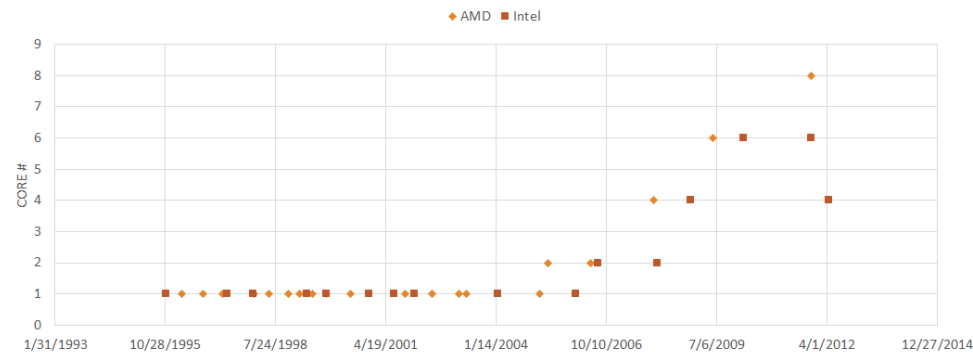
## INTEL & AMD TRANSISTOR COUNT VS. TIME



## INTEL & AMD CLOCK FREQUENCY VS. TIME



## INTEL & AMD CORE COUNT VS. TIME





# AMD CPU's

## AMD x86

V•T•E		AMD processors
<b>Lists</b>		Microprocessors • Microarchitectures • Chipsets • Sockets • Duron • Athlon (XP) • Athlon 64 (X2) • Sempron • Phenom • Ryzen •
<b>Microarchitectures</b>	<b>IA-32 (32-bit)</b>	K5 • K6 • Athlon/K7
	<b>x86-64 desktop</b>	K8 • K9 • K10 (aka 10h) • 15h (Bulldozer • Piledriver • Steamroller • Excavator) • Zen (Zen+ • Zen 2)
	<b>x86-64 low-power</b>	Bobcat (aka 14h) • 16h (Jaguar • Puma)
	<b>ARM64</b>	K12 (aka 12h)
<b>Current products</b>	<b>IA-32 (32-bit)</b>	Geode
	<b>x86-64 (64-bit)</b>	APU • Athlon X4 • FX • Ryzen • Epyc • Opteron
<b>Discontinued</b>	<b>Early x86 (16-bit)</b>	Am286
	<b>IA-32 (32-bit)</b>	Am386 • Am486 • Am5x86 • K5 • K6 • K6-2 • K6-III • Duron • Athlon (XP • MP)
	<b>x86-64 (64-bit)</b>	Sempron • Athlon 64 (X2 • II) • Phenom (II) • Turion
	<b>Other</b>	Am9080 • <b>Am2900</b> (list) • Am29000 • Alchemy (MIPS32)

# AMD's Zen

## AMD News AMD's new Zen Processor



AMD Zen

*stock news usa (2016)*

(Click image to view full size)

AMD made radical alterations to its Zen design while keeping itself distant from an ugly past. The company knew it had to make the changes to become a force to reckon with in the server and PC markets. So when the designers of the chip sat down to map the Zen design, they had two priorities: To boost CPU performance to maximum and to stabilize power efficiency.

According to a company spokesperson, the chips will come with 8 to 32 cores. The 32-core chips may come in the quad-CPU configurations although those details haven't been finalized yet.

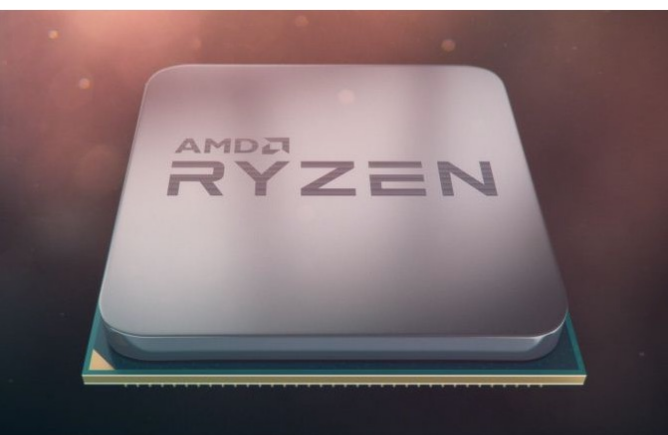
**5-19B** Transistors

❖ CPU performance  
❖ Power efficiency

8-32 cores

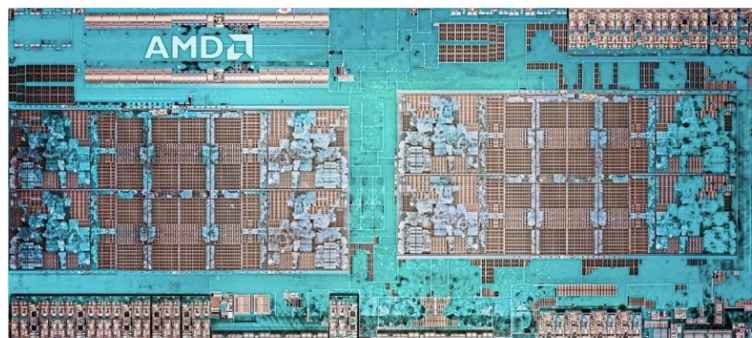
*Source: stocknewsusa (2016-08-26)*

## Inside AMD's Production Of The Zen CPU



Ryzen 7 will have three CPUs to start, all having eight cores and supporting simultaneous multi-threading:

- Ryzen 7 1800X: 8C/16T, 3.6 GHz base, 4.0 GHz turbo, 95W, \$499
- Ryzen 7 1700X: 8C/16T, 3.4 GHz base, 3.8 GHz turbo, 95W, \$399
- Ryzen 7 1700: 8C/16T, 3.0 GHz base, 3.7 GHz turbo, \$329



Ryzen

4.8 billion transistors and more than 2,000m of signal wire



# AMD RyZen

128GiB DRAM



The big old Threadripper in my desktop PC only supports 128GiB DRAM. But processors built for servers, Intel® Xeon® and AMD EPYC, will support 1TB+ DRAM. The EPYC 7742 will support 4TiB DRAM, and the price of the DRAM won't seem so shocking when you learn the price of your 64-core CPU is about \$7,500!



# AMD CPU's in PS5

7nm Ryzen



PS5 - CPU

## PS5 Specs: Rumors and Current Predictions

Before we dive into our in-depth look at potential PS5 specs, let's start with the current predictions. The system's architect, Mark Cerny, revealed [some official details in April 2019](#), but the exact specs still remain a mystery. Here is what we know from that reveal:

- PS5 will support up to 8K resolutions
- The system will include an SSD that will drastically reduce load times
- Ray tracing (a powerful graphics technique) is supported by PS5
- The system uses a variation of AMD's third generation Ryzen with eight cores of the new 7nm Zen 2 microarchitecture
- GPU is a variation of the Radeon Navi family
- The system provides 3D audio without any additional hardware



# AMD CPU's in PS5

7nm Ryzen

These are our current spec predictions based on rumors and what was revealed by Mark Cerny:

- CPU: 8 core/16 threads at 3.2Ghz with a Zen2 architecture
- GPU: Navi-based with AMD next-gen features at 12.6 to 14.2 teraflops
- Memory: 24GB total with reportedly 20GB GDDR6 at 880GB/S and 4GB DDR4 for the operating system
- 2 TB SSD

# AMD Over-clocked

AMD Ryzen 9 vs. Intel i9

## AMD Update

### AMD News

#### **Overclocked Ryzen Sets New Performance Record.**

A liquid nitrogen-cooled AMD Ryzen 9 3900X processor has just set a new overclocking world record in the wPrime benchmark, beating the previous title holder, the Intel Core i9-7920X.

The feat was performed by Australian overclocker jordan.hyde99, who got the AMD Ryzen 9 3900X to reach speeds of 5,625 MHz to complete the tests in just 35 seconds and 517 milliseconds.

[Liquid nitrogen-cooled AMD Ryzen 9 3900X is the new world overclocking champ](#)

*Source: Tech radar (16 Dec 2019)*

# Computer Architecture

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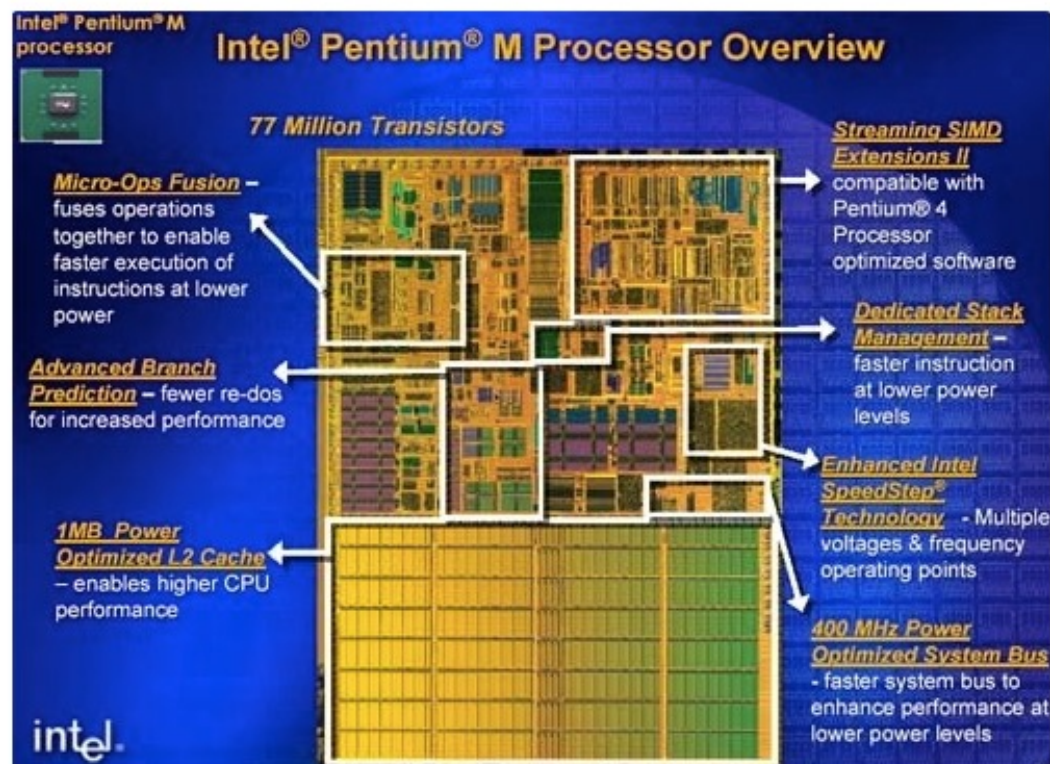


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## Modern Microprocessors Intel

# Intel Pentium “M”



The arrival of the Pentium M on the market immediately gave Intel back the performance lead in the mobile segment. A second revision, the "Dothan," increased this lead. The Pentium M was so superior to even desktop Pentium 4's that many gamers bought them and ran them on desktop motherboards released for exactly that purpose. Of course, it wasn't long before Intel started contemplating the release of a real desktop version of the Pentium M. When the next-generation Netburst design, called "Tejas," proved to be a disaster (engineering samples used 150W at 2.8 GHz), Intel cancelled it and decided to make the Pentium M design the basis of all future Intel releases.



# Intel Core i3/5/7/9 + Xeon



## Intel® Core™

Intel® Core™ X-Series

9th Gen Intel® Core™ i9

10th Gen Intel® Core™ i7

10th Gen Intel® Core™ i5

10th Gen Intel® Core™ i3

8th Gen Intel® Core™ m3

9th Gen Intel® Core™ vPro™

1 or 2 **Threads**/Core

**1.75-3B** Transistors



## Intel® Xeon®

Intel® Xeon® Scalable

Intel® Xeon® D

Intel® Xeon® W

Intel® Xeon® E



## Intel Atom®

Intel Atom® C

Intel Atom® E

Intel Atom® X



## Pentium®



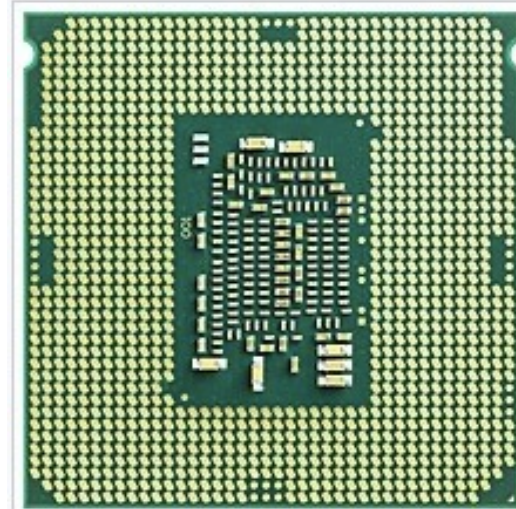
## Celeron®



## Itanium®



## Intel® Quark™



Bottom of an LGA1151 CPU.



Top of an Intel Core i7-6700K (6th Gen).

# Intel Xeon

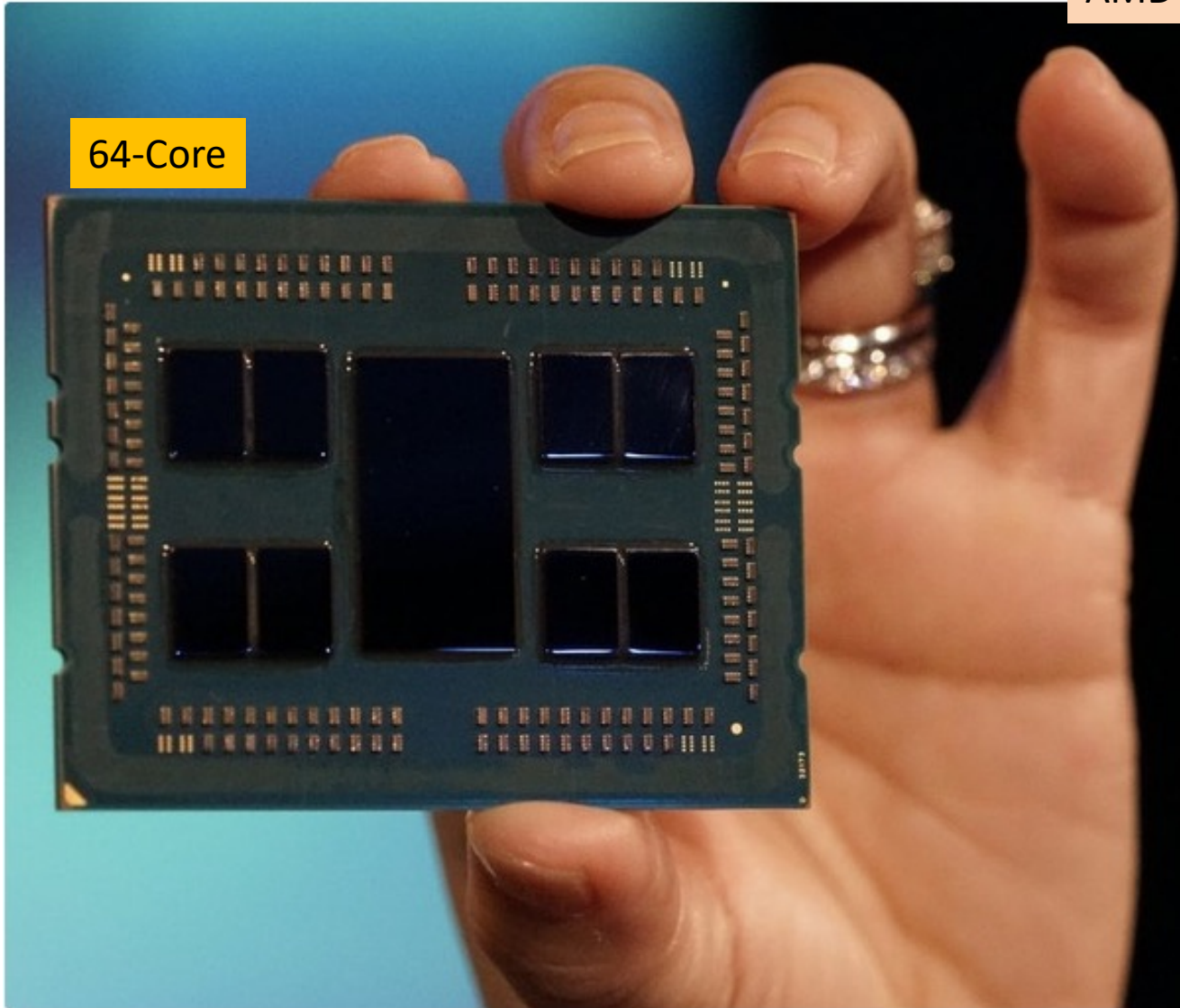
>60 Cores

Xeon Phi 7200 Series	sSpec Number	Cores (Threads)	Clock (MHz)		L2 Cache	MCDRAM Memory		DDR4 Memory		Peak DP Compute	TDP (W)	Soc- ket	Release Date	Part Number						
			Base	Turbo		Quantity	BW	Quantity	BW											
Xeon Phi 7210 <sup>[81]</sup>	SR2ME (B0)	64 (256)	1300	1500	32 MB	16 GB	400+ GB/s	384 GB	102.4 Gbit/s	2662 GFLOPS	215	SVLCLGA3647	20 June, 2016	HJ8066702859300						
	SR2X4 (B0)																			
Xeon Phi 7210F <sup>[82]</sup>	SR2X5 (B0)																			
Xeon Phi 7230 <sup>[83]</sup>	SR2MF (B0)																			
	SR2X3 (B0)																			
Xeon Phi 7230F <sup>[84]</sup>	SR2X2 (B0)															230			HJ8066702269002	
Xeon Phi 7250 <sup>[85]</sup>	SR2MD (B0)	68 (272)	1400	1600	34 MB											3046 GFLOPS <sup>[86]</sup>	215			HJ8066702859200
	SR2X1 (B0)																			
Xeon Phi 7250F <sup>[87]</sup>	SR2X0 (B0)																			230
Xeon Phi 7290 <sup>[88]</sup>	SR2WY (B0)	72 (288)	1500	1700	36 MB											3456 GFLOPS	245			HJ8066702974700
Xeon Phi 7290F <sup>[89]</sup>	SR2WZ (B0)													260			HJ8066702975200			

# Multi-Cores + L2/L3

AMD

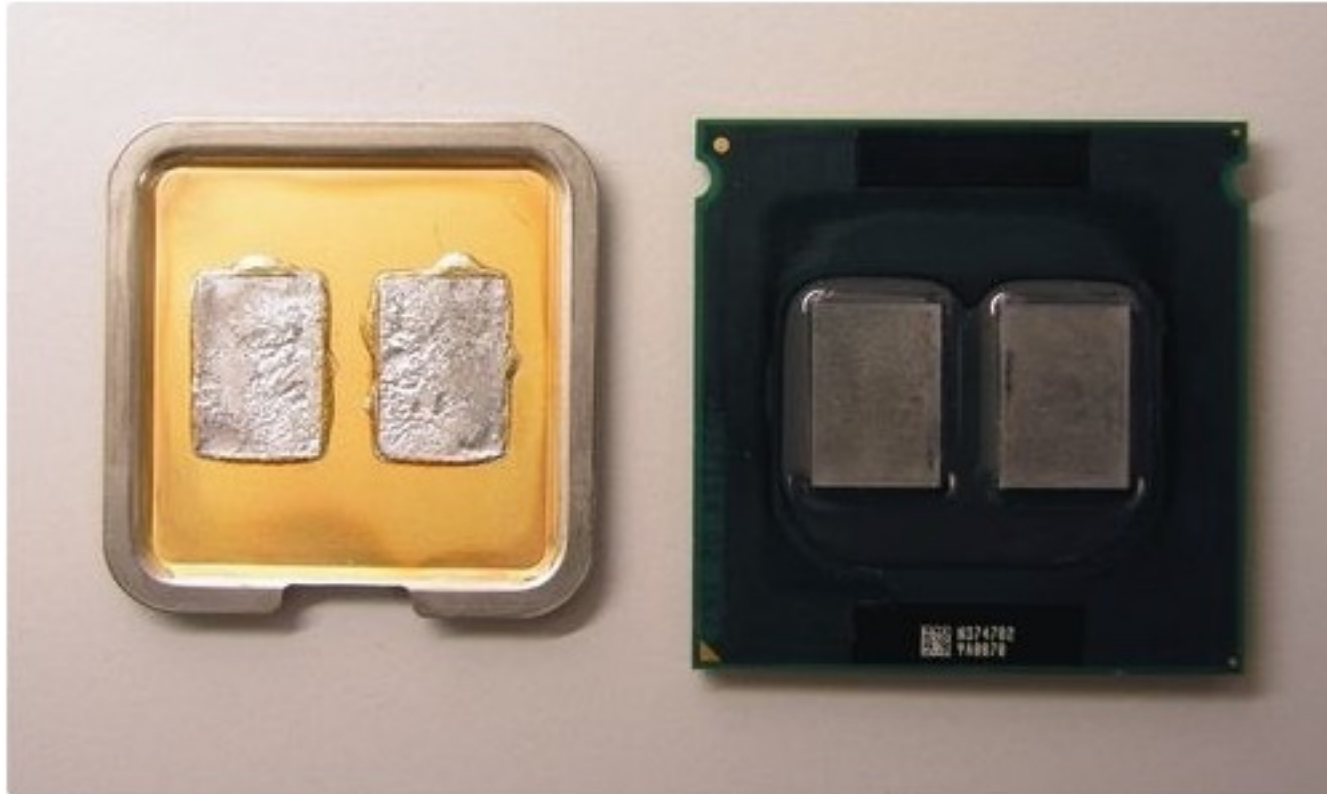
64-Core



*Lisa Su proudly shows off her 64-core EPYC monster at CES.*

# Multi-Cores + L2/L3

Intel

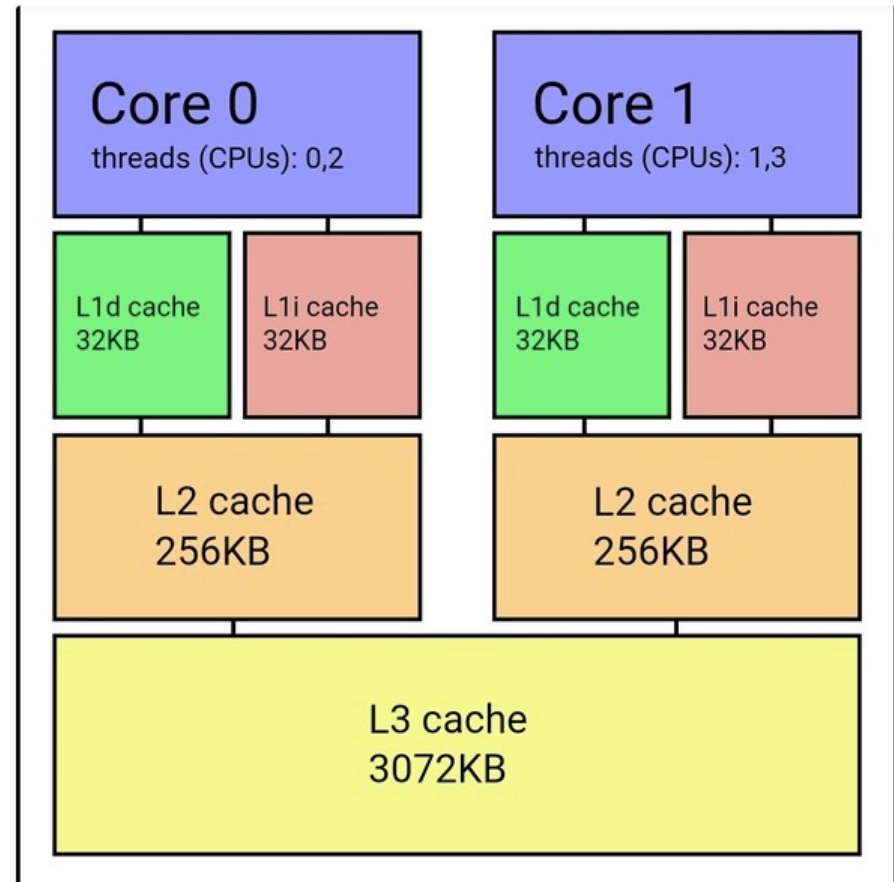
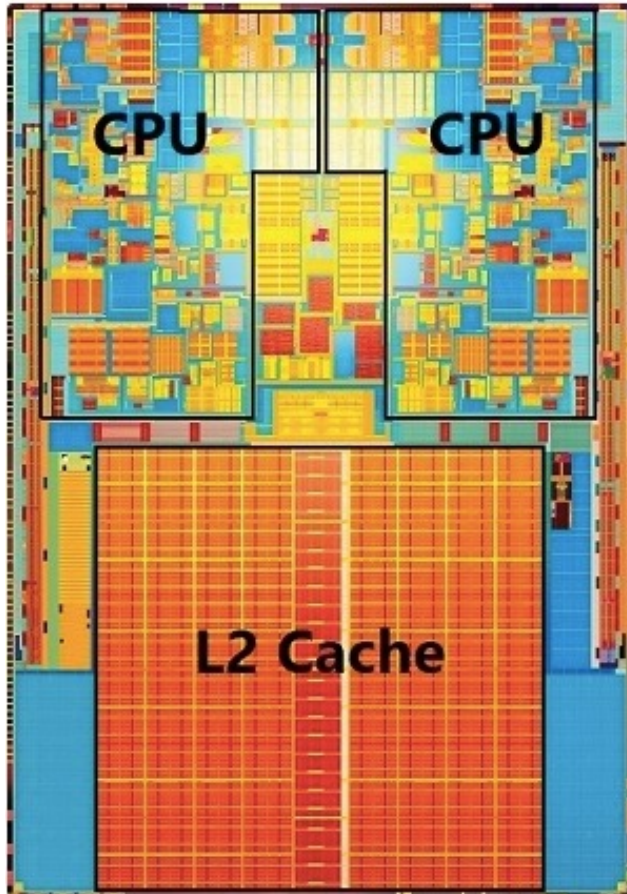


*This is a delidded Core 2 Quad with the two Core 2 Duo dies.*



# Multi-Cores + L2/L3

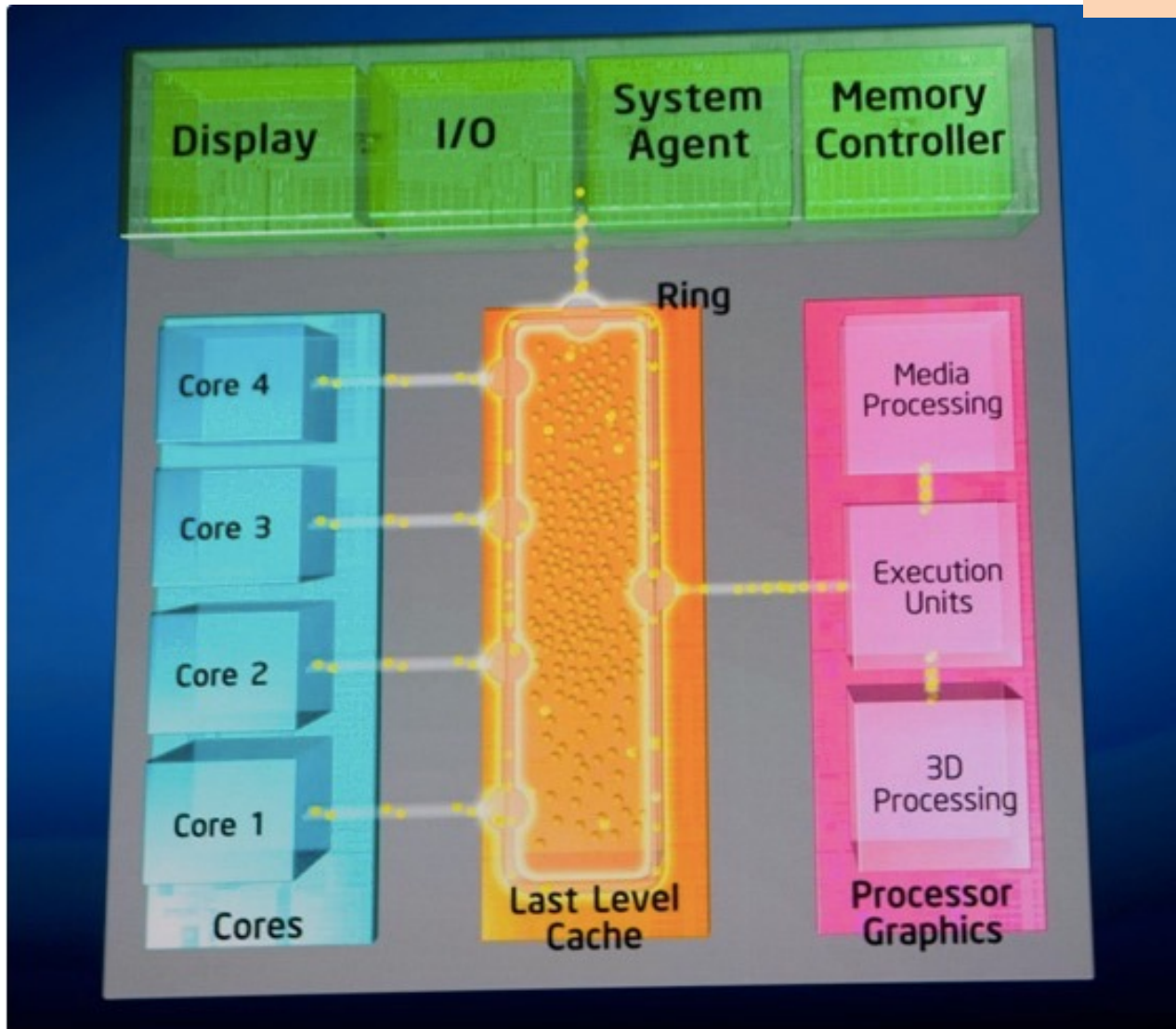
Intel



*This is a late Core 2 Duo (Wolfdale), note how massive the uncore L2 is compared to the actual CPU cores. (uncore = outside the CPU)*

# Multi-Cores + L2/L3

Intel



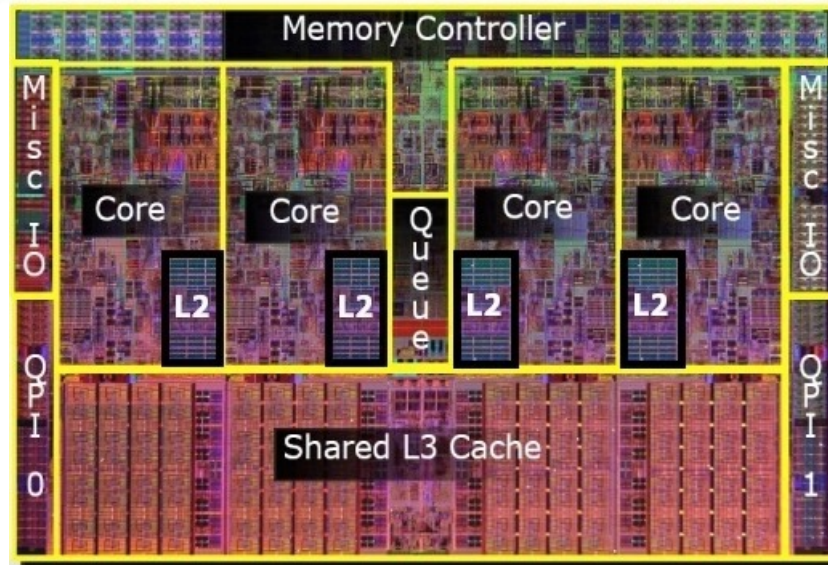
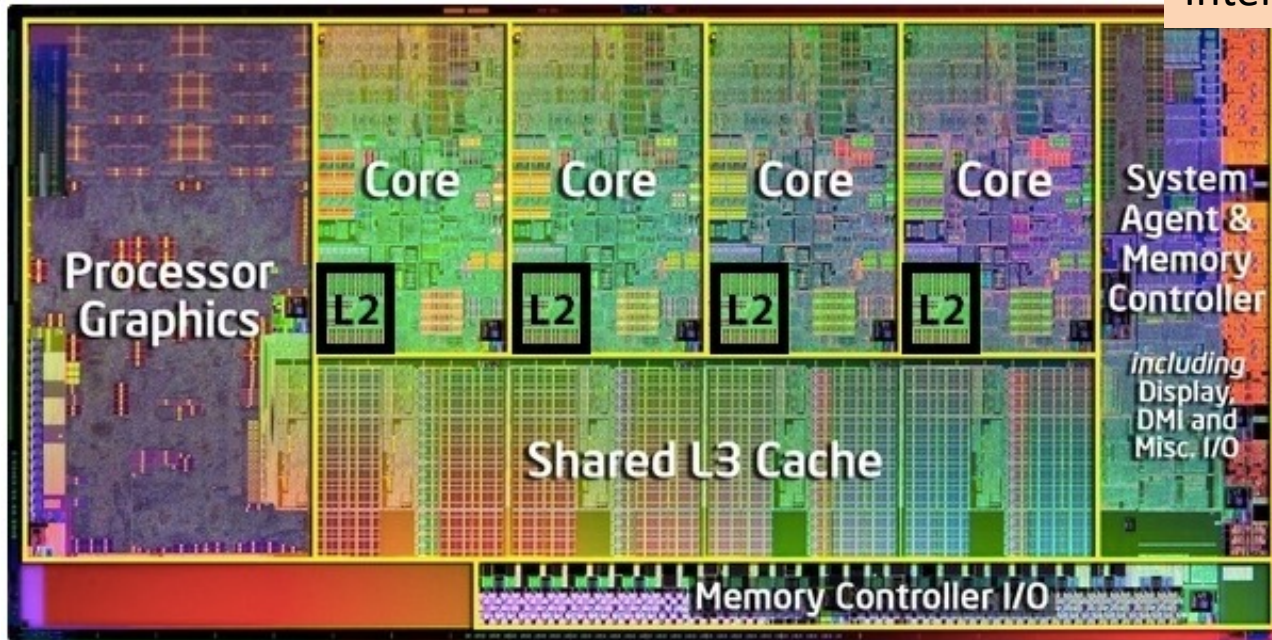
This special 'glue' remains in use today in all non-HEDT Intel CPUs.



# Multi-Cores + L2/L3

Intel

Core 4

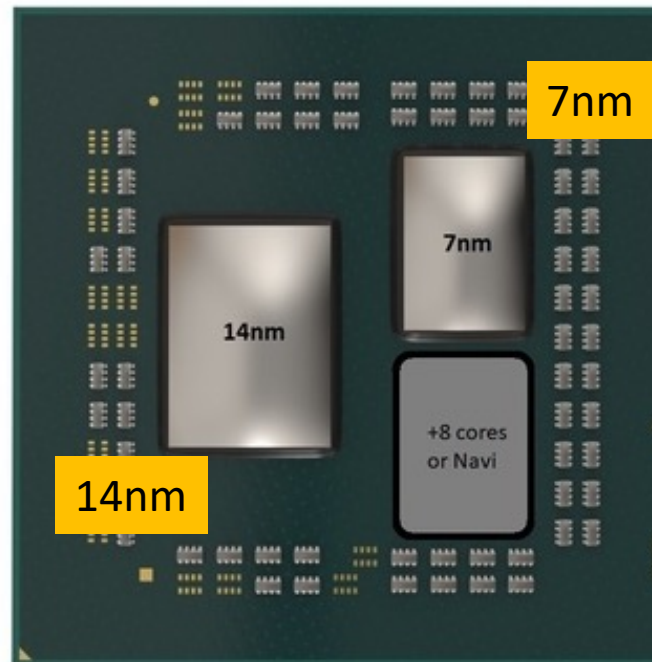


# Multi-Cores + L2/L3

AMD

Zen 2

AMD is taking a creative approach with its “7nm” production by keeping the most problematic part of the CPU at 14nm and putting the scalable “core” segments on 7nm octa-core “chiplets” that can be used alone or doubled up with another octa-core chiplet or (shhh...) a Navi GPU.



AMD kills two birds with one stone thinking outside the box with this creative Zen 2 layout: silicon yield at 7nm is vastly improved by making smaller chips, and the final product can be reconfigured to produce either workhorse 16-core CPU's or excellent SOC chips with a massive Navi GPU.



# Multi-Cores + L2/L3



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AMD



## GPU

10.7 teraflops of power

56 compute units

HBM2 Memory

## CPU

Custom x86 Processor

2.7 GHz

Hyperthreaded

AVX 2

## Memory

16GB of total RAM

Up to 484GB/s transfer speed

L2+L3 Cache of 9.5MB



# Intel Future CPUs

Xeon

Intel



*Source: Intel*

## Next-Gen Intel Xeon Scalable Processors to Deliver Breakthrough Platform Performance

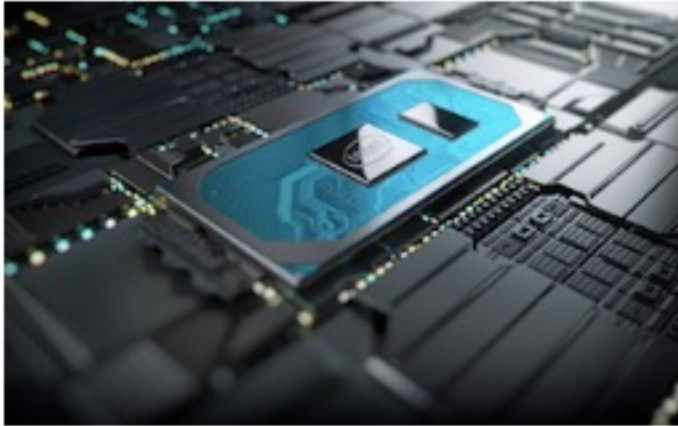
This week, Intel announced its next-generation Intel Xeon Scalable processor platform. Codenamed Cooper Lake, the latest addition to the processor family boasts up to 56 processor cores per socket, higher memory bandwidth, and built-in AI inference and training acceleration. Learn more about the high-core-count Cooper Lake processor platform, which will be available in the first half of 2020.

$\leq$  56 cores in 1H 2020

# Intel Future CPUs

Ice Lake

Intel



Source: TechRadar

## Intel Ice Lake Has Landed, and It's Smarter, Faster and More Efficient Than Ever

Built on 10nm technology, Intel's Ice Lake platform is the first step toward Project Athena—an initiative that aims to leverage next-generation tech for advanced mobile computing experiences. Ice Lake's deep-learning capabilities will deliver optimized performance while the inclusion of Gen11 graphics will make for more sophisticated gaming experiences. Here's what else you can expect from Ice Lake.

# Intel Future CPUs

Intel



*Source: Intel IT Peer Network*

## Exascale Computing Will Redefine Content Creation

In line with Intel's pursuit of exponential increases in computing capabilities, Intel's Architecture, Software, and Graphics group has been challenged to deliver a 1000x workflow improvement for content creators. Enter exascale computing. With the ability to process a quintillion (that's a billion billion, for those who can't count that high) calculations per second, exascale computing will enable content creators to push the limits for high-quality animation.

Exascale =  $10^{18}$  IPS





# Intel Future CPUs



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Hot Chips 2019 Intel

## AT HOT CHIPS, INTEL PUSHES 'AI EVERYWHERE'

**What's New:** At Hot Chips 2019, Intel revealed new details of upcoming high-performance artificial intelligence (AI) accelerators: Intel® Nervana™ neural network processors, with the NNP-T for training and the NNP-I for inference. Intel engineers also presented technical details on hybrid chip packaging technology, Intel® Optane™ DC persistent memory and chiplet technology for optical I/O.



Source: Intel



# Intel Future CPUs



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Hot Chips 2019 Intel

## What Intel Presented at Hot Chips 2019:

**Intel Nervana NNP-T: Built from the ground up to train deep learning models at scale:** Intel Nervana NNP-T ([Neural Network Processor](#)) pushes the boundaries of deep learning training. It is built to prioritize two key real-world considerations: training a network as fast as possible and doing it within a given power budget. This deep learning training processor is built with flexibility in mind, striking a balance among computing, communication and memory. While Intel® Xeon® Scalable processors bring AI-specific instructions and provide a great foundation for AI, the NNP-T is architected from scratch, building in features and requirements needed to solve for large models, without the overhead needed to support legacy technology. To account for future deep learning needs, the Intel Nervana NNP-T is built with flexibility and programmability so it can be tailored to accelerate a wide variety of workloads – both existing ones today and new ones that will emerge. [View the presentation](#) for additional technical detail into Intel Nervana NNP-T's (code-named Spring Crest) capabilities and architecture.

**Intel Nervana NNP-I: High-performing deep learning inference for major data center workloads:** Intel Nervana NNP-I is purpose-built specifically for inference and is designed to accelerate deep learning deployment at scale, introducing specialized leading-edge deep learning acceleration while leveraging Intel's 10nm process technology with Ice Lake cores to offer industry-leading performance per watt across all major datacenter workloads. Additionally, the Intel Nervana NNP-I offers a high degree of programmability without compromising performance or power efficiency. As AI becomes pervasive across every workload, having a dedicated inference accelerator that is easy to program, has short latencies, has fast code porting and includes support for all major deep learning frameworks allows companies to harness the full potential of their data as actionable insights. [View the presentation](#) for additional technical detail into Intel Nervana NNP-I's (code-named Spring Hill) design and architecture.





# Intel Future CPUs



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**TeraPHY: An in-package optical I/O chiplet for high-bandwidth, low-power communication:** Intel and Ayar Labs demonstrated the industry's first integration of monolithic in-package optics (MIPO) with a high-performance system-on-chip (SOC). The Ayar Labs TeraPHY\* optical I/O chiplet is co-packaged with the [Intel Stratix 10 FPGA](#) using [Intel Embedded Multi-die Interconnect Bridge \(EMIB\) technology](#), offering high-bandwidth, low-power data communication from the chip package with determinant latency for distances up to 2 km. This collaboration will enable new approaches to architecting computing systems for the next phase of Moore's Law by removing the traditional performance, power and cost bottlenecks in moving data. [View the presentation](#) for additional technical detail and design decisions on creating processors with optical I/O.

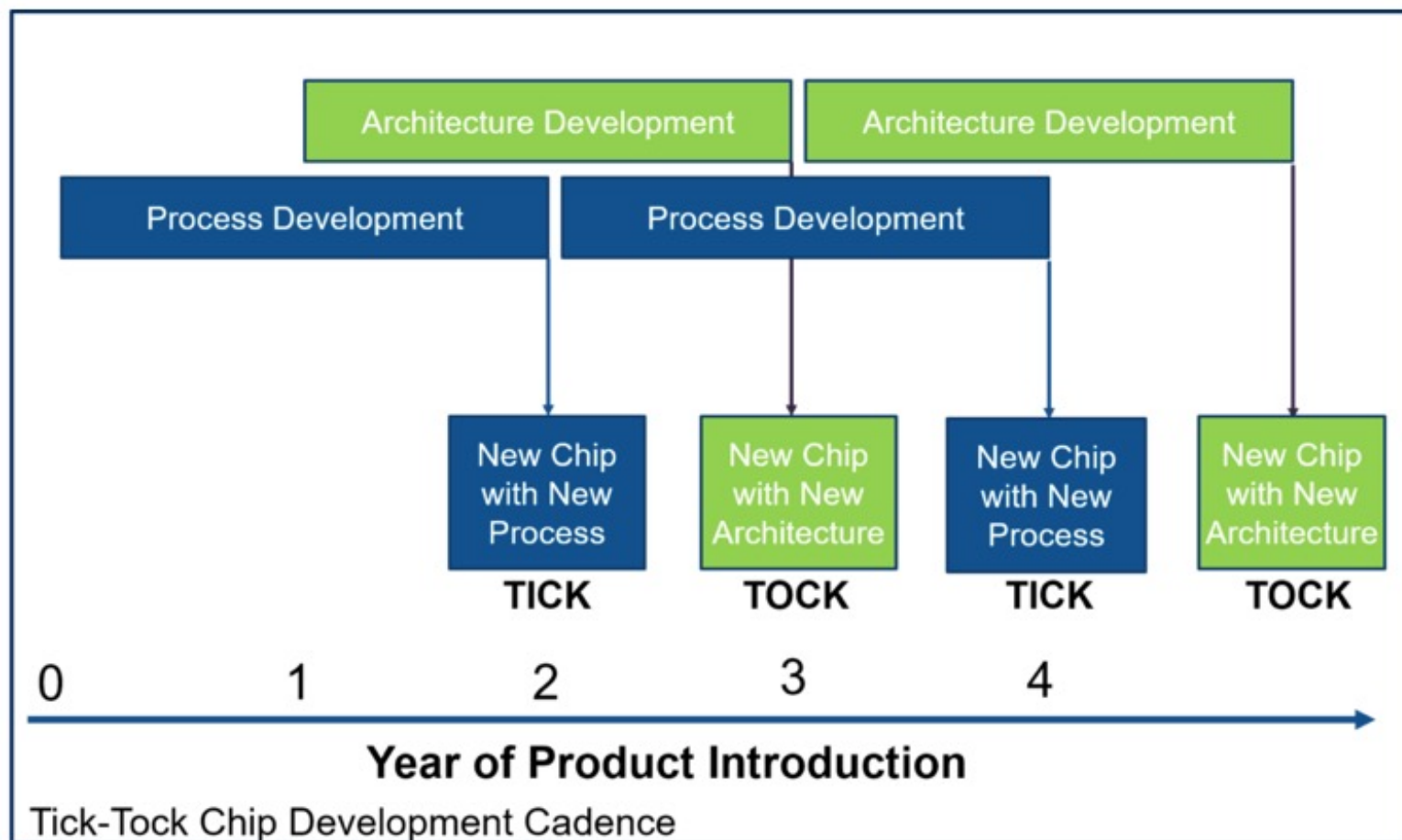
**Intel Optane DC persistent memory: Architecture and performance:** [Intel Optane DC persistent memory](#), now shipping in volume, is the first product in the memory/storage hierarchy's entirely new tier called persistent memory. Based on Intel® 3D XPoint™ technology and in a memory module form factor, it can deliver large capacity at near-memory speeds, latency in nanoseconds, while also natively delivering the persistence of storage. Details of the two operational modes (memory mode and app direct mode) as well performance examples show how this new tier can support a [complete re-architecting of the data supply subsystem](#) to enable faster and new workloads. [View the presentation](#) for additional architectural details, memory controller design, power fail implementation and performance results for Intel Optane DC persistent memory.

# Intel Moore's Tick Tock

## Pipelined Architecture

staggered it allows a once a year cadence of new product introduction. One year the new chip is a process shrink of an existing architecture. The next year the new chip uses the same process node but introduces a new architecture.

The beauty of this chip development model is that it is a business innovation that takes advantage of a classic pipeline that hides latency to achieve throughput.





# Computer Architecture

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Modern  
Microprocessors  
**ARM → Apple**

# Apple ARM A Series

Quora post

According to Apple, the chip is capable of performing one trillion operations per second and with an eight-core neural engine, A13 Bionic chip has the most Machine Learning performance that adds 6x faster matrix multiplication.

This time Apple has focused mainly on machine learning and the A13 Bionic has Fastest CPU and GPU in a Smartphone.

Qualcomm Snapdragon 800 Series flagship is the biggest competitor of Apple. Qualcomm has its Snapdragon 855 and 855 Plus flagship SoC but the successor to Snapdragon 855 is yet to get announced were Apple has already unveiled A13 Bionic.

The Apple A13 Bionic is fabricated on TSMC 2nd (EUV Lithography Process) Generation 7nm process and Snapdragon 855 and 855 Plus Both are fabricated on TSMC 7nm DUV process. And A13 has over 8.3 Billion Transistors and that of 855 Snapdragon has 6.9 Billion Transistors.



Apple A13

# Apple ARM A12/13 SoC



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Quora



Home



Answer <sup>121</sup>



Spaces



Notifications <sup>45</sup>



Sea

## 3 Answers



Matthew J. Stott, Senior Systems & Mac Engineer (1996-present)

Answered Sep 30



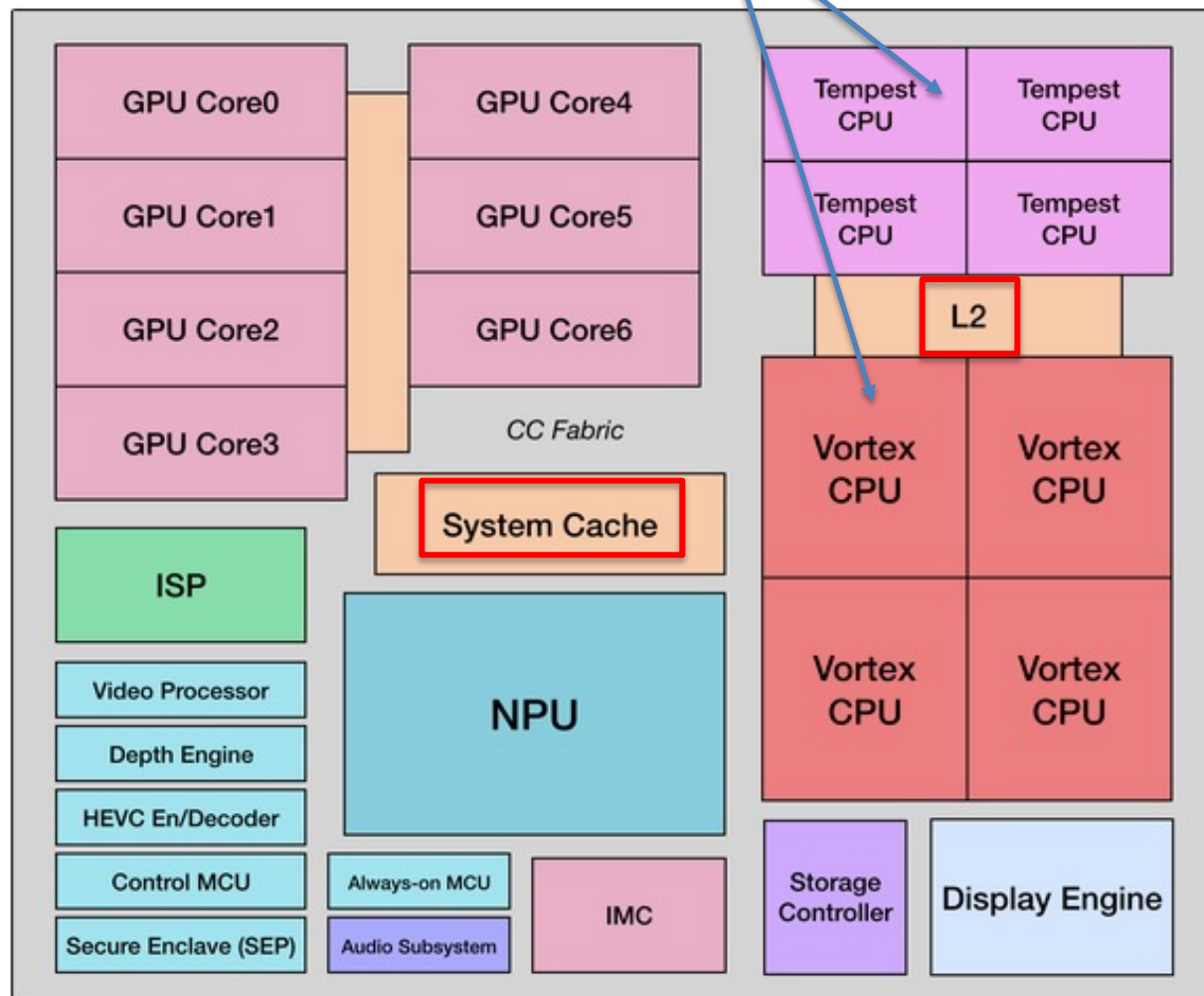
It's called a **SoC - System on Chip**. It means the CPU package includes a lot more than just the CPU cores. What's changed with the **A13** is even more power management abilities to shut off unused parts of the A13 but also right down to individual transistors as well. It is the most advanced power management in use right now. It is responsible for the excellent battery life of the 11, 11 Pro, 11 Pro Max iPhones. Yes, they increased the battery capacity a bit at the same time but that is just improved battery engineering.

Add to Yowan's **A12X** the Image Processing Core, a couple of Machine Learning accelerator cores and a bit less on the GPU with the **A13 Bionic SoC**. It is expected there will be an A13X for upgrade iPad Pros coming soon.

# Apple ARM A12/13 SoC

This is a block diagram of the Apple A12X with 10 billion transistors. Of that amount, only 25% is dedicated to the two CPU clusters:

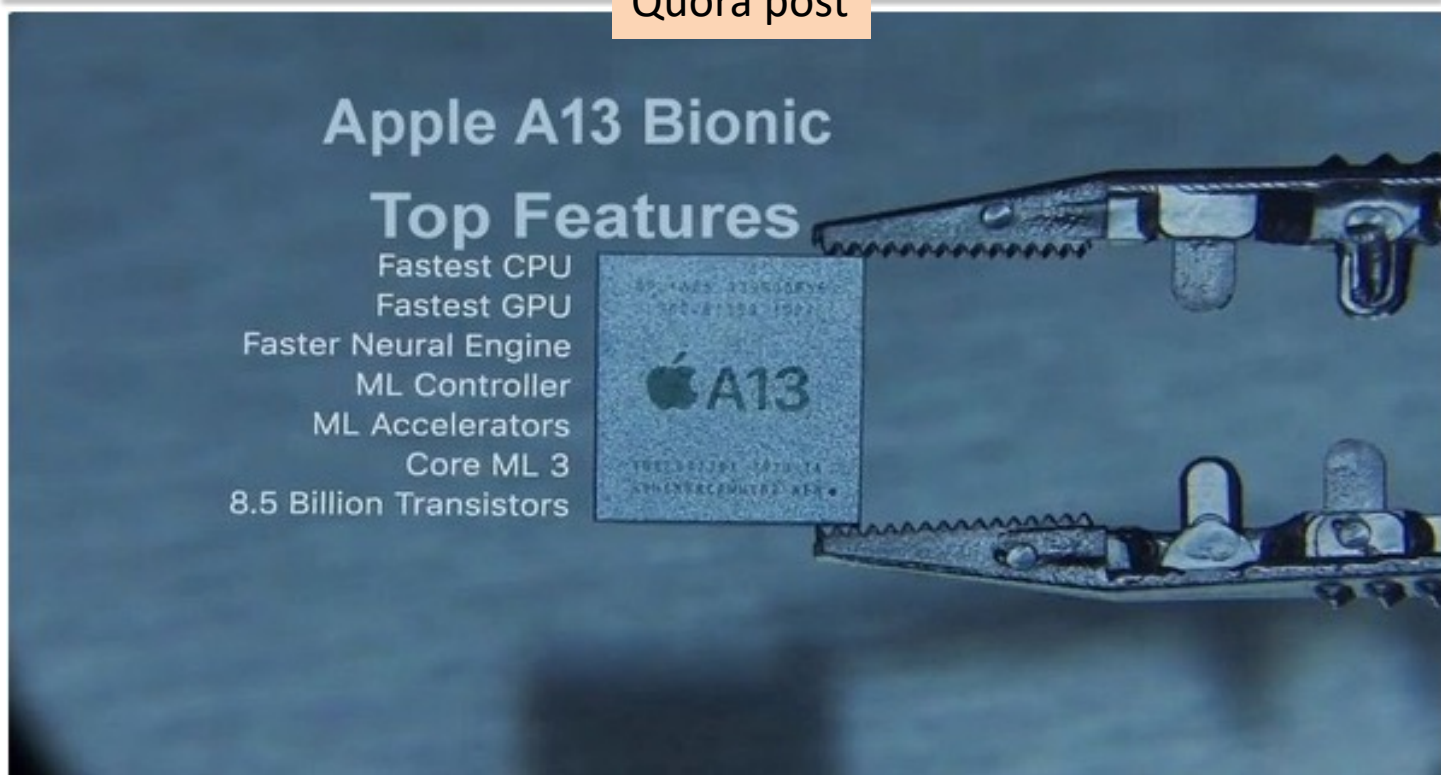
- ❖ 8 CPU
- ❖ 7 GPU
- ❖ 1 NPU
- ❖ 2 MCU





# Apple A13

Quora post



In Steve Jobs Studio, Apple launched three new iPhones - iPhone 11, iPhone 11 Pro and iPhone 11 Pro Max. All these three new iPhones are based on the new Apple A13 Bionic chipset. The company launched this SoC with these iPhones. The A13 Bionic is a successor of last year's A12 Bionic SoC. The last year's A12 Bionic is ahead of Snapdragon 855 in terms of performance. According to the company, Apple A12 Bionic is at least two years ahead of other Android smartphones in the race for fast processors. After all, what is new in the A13 Bionic that makes iPhones so powerful? Don't worry, here we [\(more\)](#)

# Apple A13

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## Quora post

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And I think iPhones are going to be more power-efficient than Snapdragon 855 powered Android Phones. If you are asking about CPU, then the A13 Bionic is based on 64-bit Fusion Architecture. It is a Hexa-Core CPU with 2 Performance cores and 4 Efficiency cores. And it consumes 40% less power than the A12 Bionic. Coming to 855 Snapdragon, both Snapdragon 855 and 855 Plus is an ARM 64-bit SoC with Kryo 485 Octa-Core CPU. And it has Three CPU Clusters: 1 Cortex-A76 Prime Core, 3 Cortex-A76 Performance Cores and 4 Cortex-A55 Efficiency Cores. From these it seems Snapdragon 855 will definitely be a strong competitor for the Apple A13 Bionic Chip.

Moreover, while talking about GPU, for Apple, it is an Apple-designed Quad Core GPU and Snapdragon 855 has Adreno 640 GPU. And I don't think the Snapdragon will beat the performance of Apple's A13 bionic chip.

# Computer Architecture

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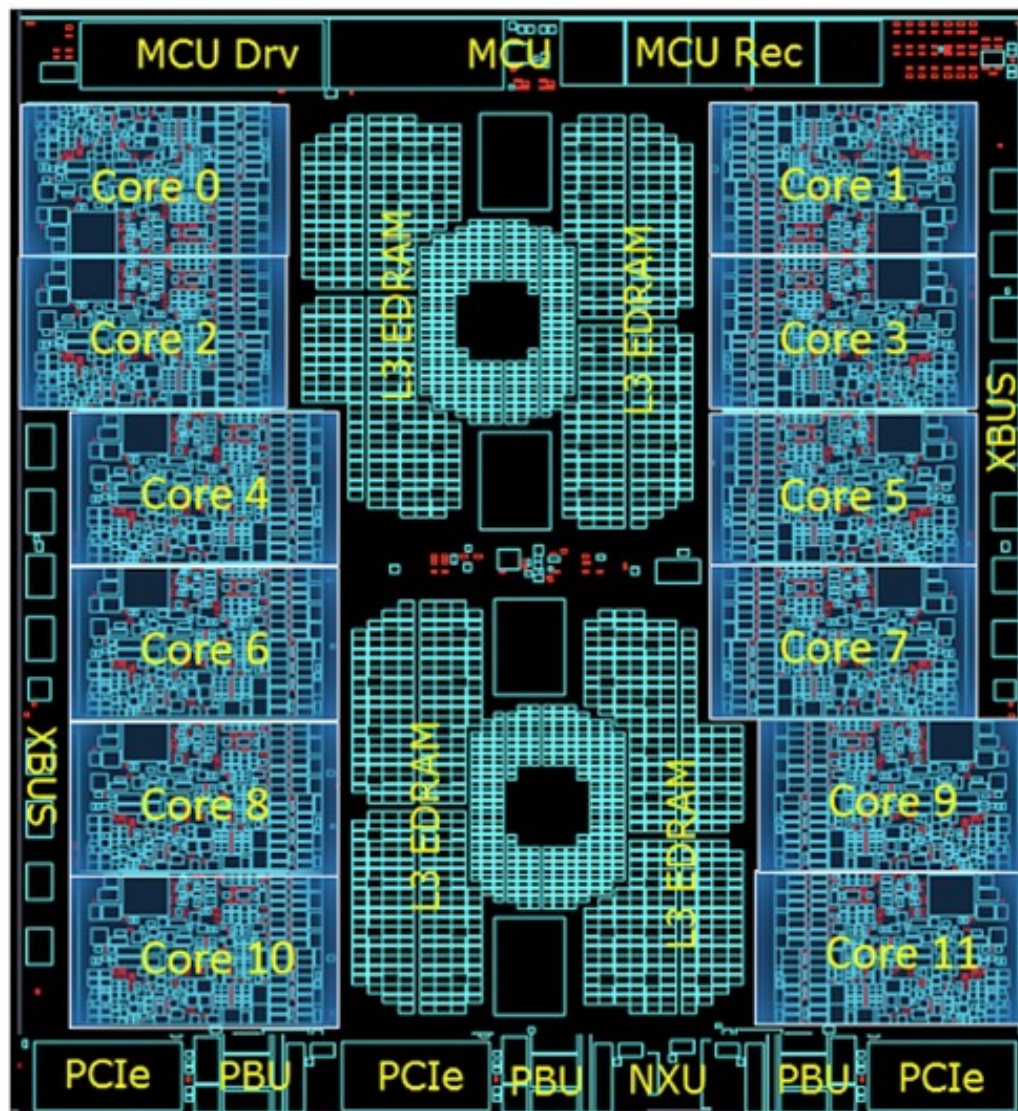
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## Modern Microprocessors **IBM z15**

# IBM CPU's: z15

z15 floorplan:





The z15 is almost exactly as large as Intel's Skylake XCC config. 695 mm<sup>2</sup> vs ~ 694 mm<sup>2</sup> for the Intel one. Intel places 28 cores vs the z15's 12. That alone tells you that IBM is placing a lot more resources per core than Intel or AMD. (That's not good or bad per se, just an observation)

[illegible]

Again, note the large L2 caches. In other CPUs that amount of real estate would typically be allocated for L3 cache.

# IBM CPU's: ISA

## Instruction Set Architecture

While AMD and Intel are using the x86-64 Instruction Set Architecture (ISA), IBM mainframe CPUs use the z/Architecture ISA, a traditional CISC architecture, which is a descendant of the original S/360 ISA released all the way back in 1964. IBM has another RISC ISA called IBM POWER and produces processors using it, but the two aren't related. Nothing too special about that, there are plenty of ISAs out there.

## Microarchitecture

When looking at the microarchitecture itself - or at least at what IBM is willing to publish - you'll see that IBM is trying to get the best of all worlds: A rich CISC instruction-set with over two thousand instructions and addressing modes, some of them extremely specific and complex. Combine that with very conservative instruction break-ups in the decode stage into  $\mu$ OPs, meaning that most instructions are actually implemented directly in hardware without the use of microcode (IBM calls it *millicode* for whatever reason). Add in very deep pipelines and you basically have a *braniac* CPU core, that tries to extract as much instruction and data-level parallelism as possible and that is both a *speed-demon*, running at insane clockspeeds. IBM manufactures the highest-clockspeed CPUs in the industry. The IBM z12 clocked in at a whopping 5.5 GHz for a six-core CPU, and that was sustained under all circumstances for all cores. No Turbo mode here. 5.5 GHz for six cores. All the time. The newest z15 manages 5.2 GHz across twelve cores. Under all circumstances, all the time.

# IBM CPU's: SFU's

## Decimal

### Special Function Units

IBM zSeries CPUs also contain dedicated execution units not found on many other architectures. One example would be decimal floating point and fixed point units, in addition to the more traditional binary FP units found in Intel or AMD machines. The reason for that is that IBM mainframes are traditionally used in the banking and insurance industries, both of which deal with handling high volume computations that represent actual money. A problem with binary floating point units is that due to the way they work, some fractions of real numbers cannot be accurately represented using a binary format. Just as the fraction  $1/3$  cannot be accurately represented in the decimal system, producing  $0.3333333...$  and being usually truncated to  $0.333...334$  in decimal representation, the value  $1/10$  cannot be accurately represented in binary. It too produces an infinite sequence of repeating numbers, that have to be truncated. Problem: Dollars aren't measured in "thirds", but "tenths" and "hundredths" of a Dollar. These values routinely come up in interest or premium or tax calculations. You can now live with ever more compounding errors or implement your money-calculations using some type of software library, which costs a lot of performance, or you can use an architecture that has dedicated decimal floating point units handling all of that in hardware. Another SFU would be dedicated compression and encryption units per core. While both AMD and Intel have implemented some form of AES instructions, IBMs are much more comprehensive, handling more encryption standards and compression operations in hardware.



# IBM CPU's: Cache

MLM

## Cache Hierarchy

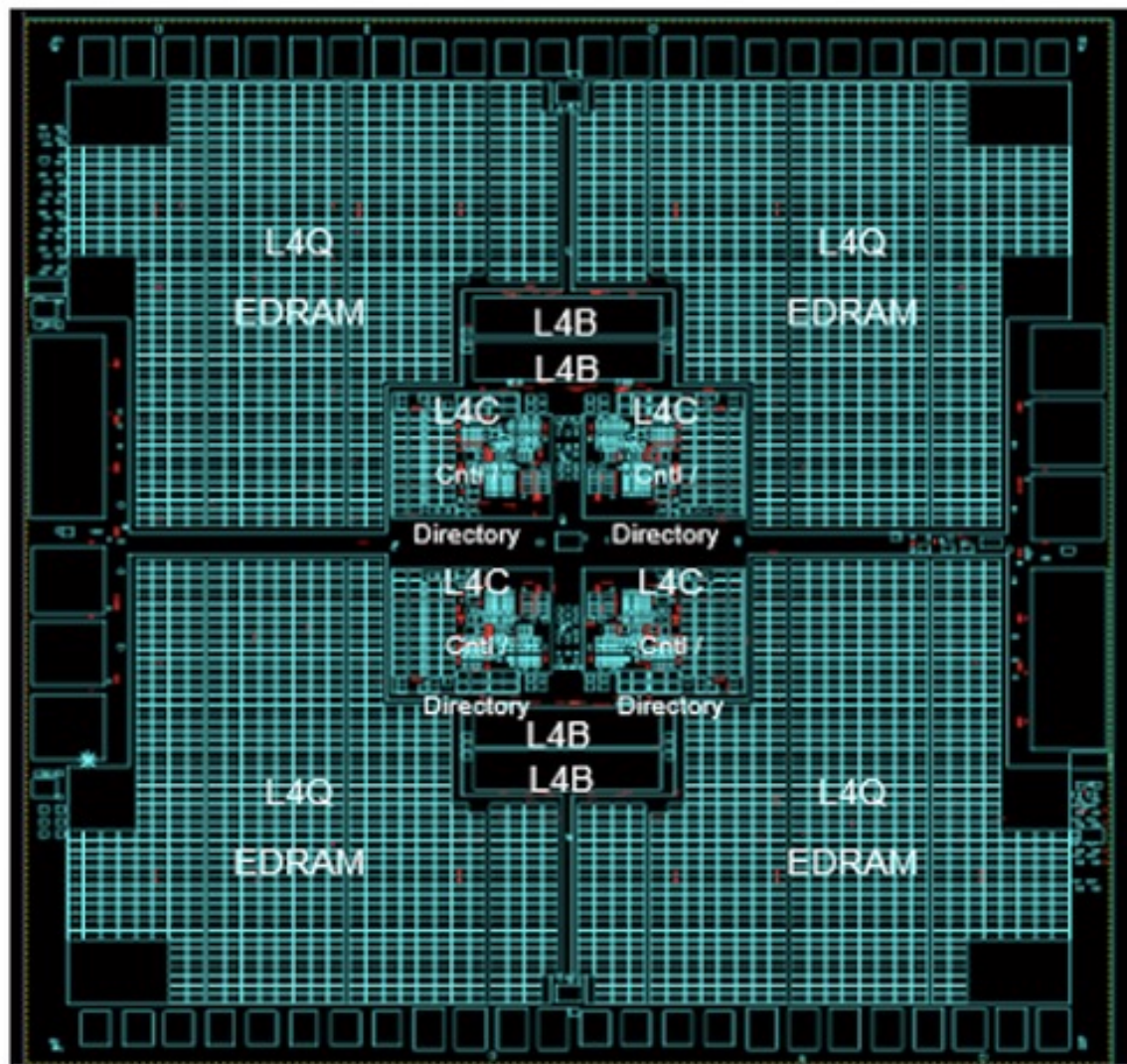
One unusual feature of IBM Mainframe CPUs is their cache hierarchy. Both in scope and implementation. L1D and L1I caches are fairly large at 128 kB each. L2 caches are huge in comparison to Intel and AMD CPUs, and they are also split into dedicated L2D and L2I caches, a whopping 4MB each per core. Compare that to the usual 1 - 2 MB unified L2 per core for Intel or AMD. The L3 cache is also special in that instead of using SRAM cells, the L3 cache is implemented using embedded DRAM, which increases latency, but allows IBM to place much more L3 cache into a given silicon area. For the z15, that is 256 MB of unified L3 cache per CPU chip. Really unique to the IBM zSeries cache hierarchy is an additional off-chip unified L4 cache, also implemented using eDRAM, in case of the z15 that's 960 MB of L4, shared by four CPU chips. All of that cache is used to feed those beefy and fast execution units with as much data and instructions as possible to avoid bubbles in the deep pipelines.



# IBM CPU's: Cache

L4 OFF-CHIP

L4 Cache Chip floorplan:



# IBM CPU's: Memory ECC

## Memory Controllers

The memory controllers are almost one-of-a-kind: multi-channel memory controllers are nothing new or fancy, but the way IBM has implemented them in the zSeries is almost unique: each memory controller - one per chip - can handle 5 channels. The special sauce in this case is that those five channels are kind of RAIDed together. IBM calls it Redundant Array of independent Memory (RAIM). In addition to the usual SECDED ECC algorithms to protect against single chip memory errors, RAIM can tolerate an entire memory channel failure on the fly, without any OSes or applications noticing. Losing a memory channel on pretty much any other architecture will lock up your machine for good. AMD and Intel use memory mirroring to protect against that, but if you enable it you'll lose half your memory capacity and cut your memory bandwidth in half. IBM's approach means that you'll only be limiting yourself to 4/5-ths of the installed capacity and bandwidth. Pretty neat. The last general purpose CPU that could do this was the Alpha CPU, but they were phased out by HP in 2003 in favor of the ill-fated Itanium.

## RAS features

Anyone producing a server-grade, general-purpose CPU will need to address the problem of soft and hard failures inside their CPUs. DECTED ECC for the caches, SECDED for less critical data structures and at least parity checking for non-critical ones. Error and sanity checkers in critical pathways. That's pretty standard. IBM's zSeries CPUs take that to another level. IBM estimates (whatever that may mean, they don't know?), that they dedicate up to 10% of silicon real estate to error detection and correction. An important part of that are the R-Units, another type of SFU that periodically stores the entire architectural state of the core in question, and upon non-transient failures can transfer that state to one of two spare cores present on all but the smallest mainframe models for them to pick up the load.

# Computer Architecture

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## CPU Performance

# CPU Performance

$$\text{Time} = \text{Seconds/Program} = \frac{\text{Instructions}}{\text{Program}} \times \frac{\text{Clock cycles}}{\text{Instruction}} \times \frac{\text{Seconds}}{\text{Clock cycle}}$$

$$\text{CPU time} = \text{Instruction count} \times \text{CPI} \times \text{Clock cycle time}$$

$$\text{Clock rate} = 1/\text{Clock cycle time}$$

$$\text{CPU time} = \frac{\text{Instruction count} \times \text{CPI}}{\text{Clock rate}}$$



# CPU Performance

The following table summarizes how these components affect the factors in the CPU performance equation.

Hardware or software component	Affects what?	How?
Algorithm	Instruction count, possibly CPI	The algorithm determines the number of source program instructions executed and hence the number of processor instructions executed. The algorithm may also affect the CPI, by favoring slower or faster instructions. For example, if the algorithm uses more divides, it will tend to have a higher CPI.
Programming language	Instruction count, CPI	The programming language certainly affects the instruction count, since statements in the language are translated to processor instructions, which determine instruction count. The language may also affect the CPI because of its features; for example, a language with heavy support for data abstraction (e.g., Java) will require indirect calls, which will use higher CPI instructions.
Compiler	Instruction count, CPI	The efficiency of the compiler affects both the instruction count and average cycles per instruction, since the compiler determines the translation of the source language instructions into computer instructions. The compiler's role can be very complex and affect the CPI in varied ways.
Instruction set architecture	Instruction count, clock rate, CPI	The instruction set architecture affects all three aspects of CPU performance, since it affects the instructions needed for a function, the cost in cycles of each instruction, and the overall clock rate of the processor.

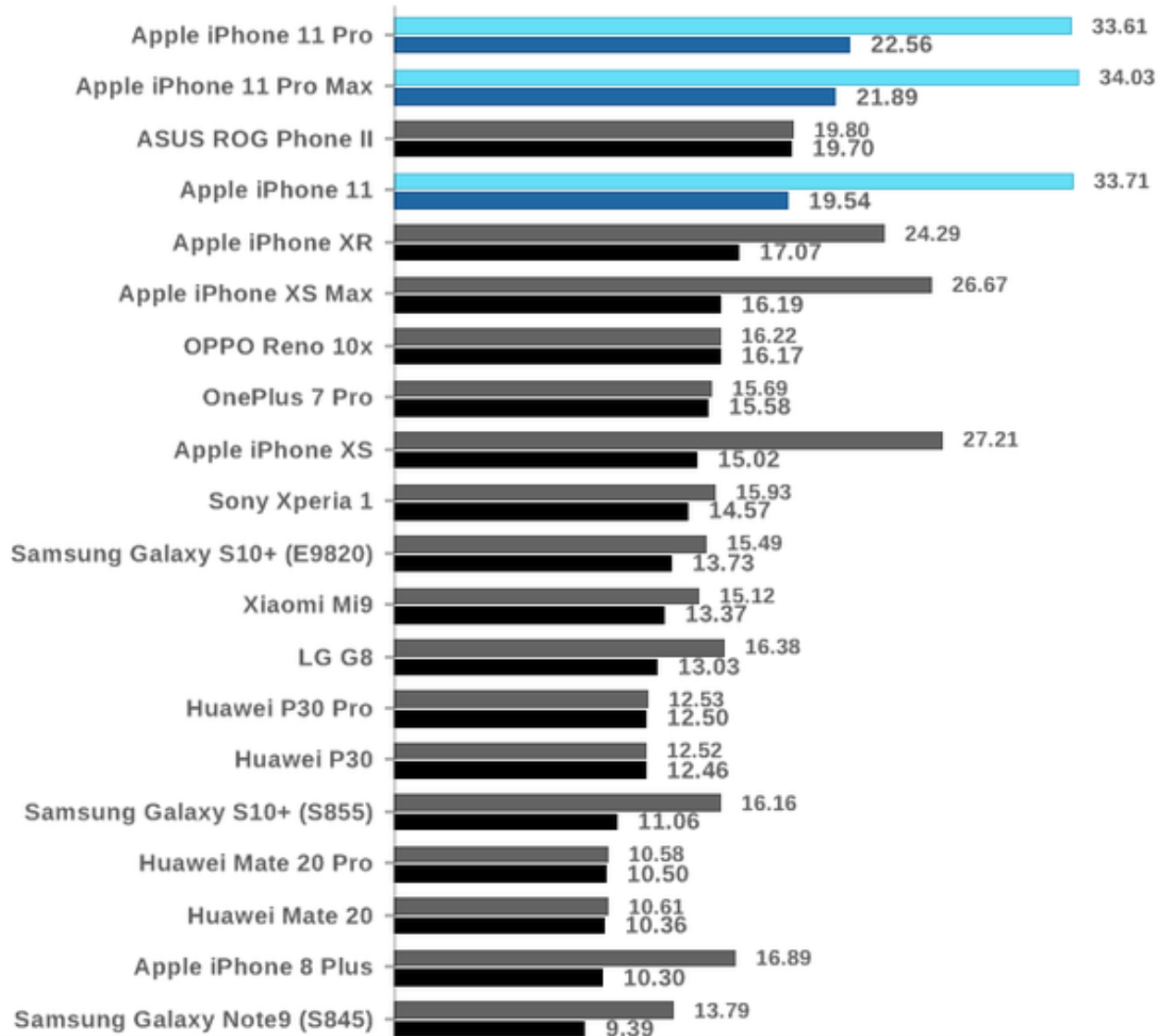
# CPU Performance



## GFXBench Aztec Ruins - High - Vulkan/Metal - Off-screen

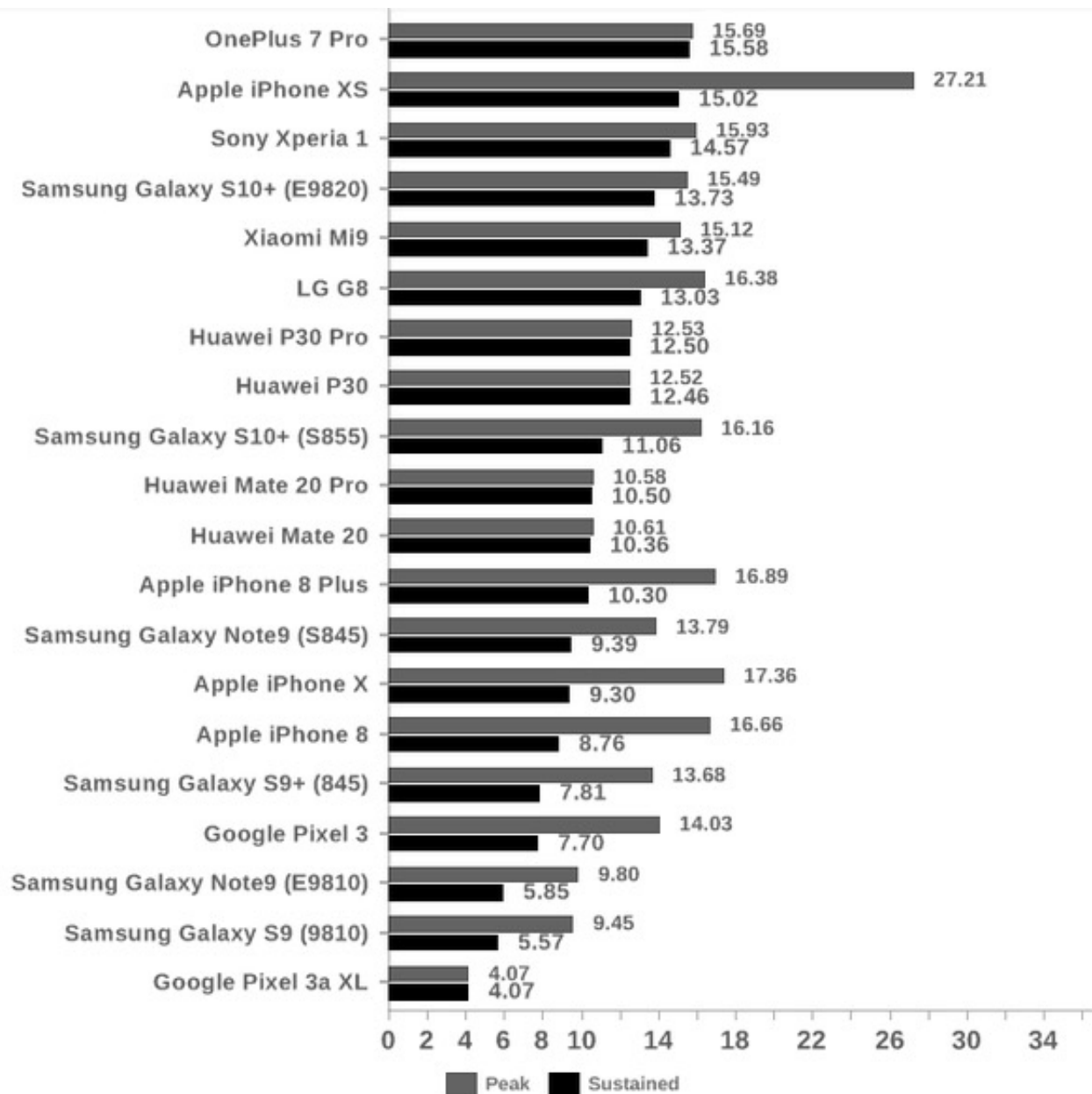
Frames per Second - Higher is Better

Frames/sec



# CPU Performance

Frames/sec



# Computer Architecture

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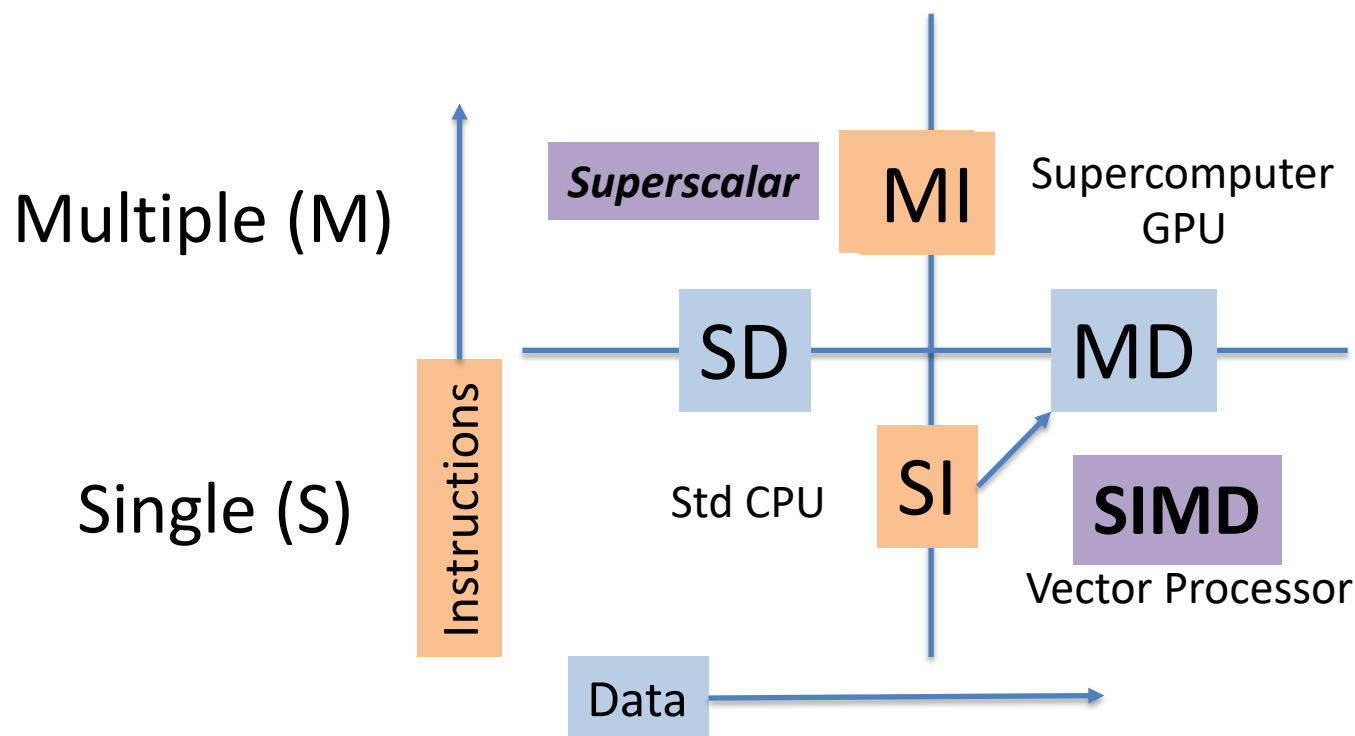
## Parallelism



# I-D Parallelism: SIMD

## Flynn Partition

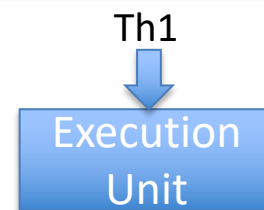
Michael J. Flynn paper (U Illinois (UIUC), Ca 1969)



# Instruction Level *Parallelism*

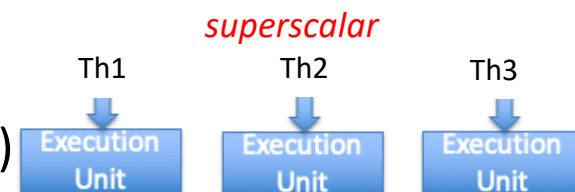
## ❖ Super- *Pipelining* **SISD**

- ❑ Split some pipeline stages (4-5 → 8-11)
- ❑ Faster clock cycle → higher *throughput* (*mips*)
- ❑ Affect CPI?



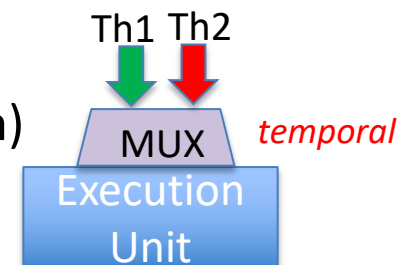
## ❖ Super- *Scalar* **SISD**

- ❑ Multiple **Execution Units** (multi-issue pipelines)
  - each EU = ICU+ALU, with shared GR's
- ❑ Hardware + compiler *schedules* instruction streams



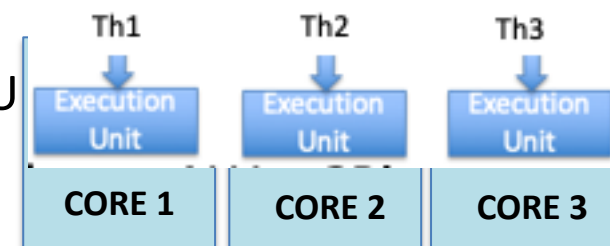
## ❖ Multi- *Threading* **SISD**

- ❑ Multiple control threads (usually 2, same/dif program)
- ❑ Programs can *allocate* code to threads
- ❑ Automatic *scheduling* of control threads
- ❑ 2 types: *SMT/superscalar* or *temporal* (interleaved: coarse/fine)



## ❖ Multi- *Core* **MISD**

- ❑ Classic Parallelism: multiple copies of the CPU
- ❑ **Multiple L1/L2 caches** (one set per core)



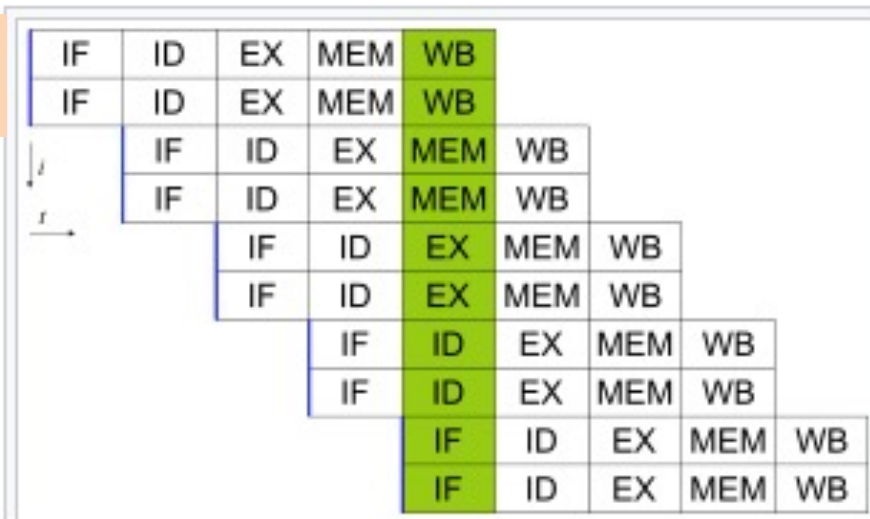
# Superscalar

## ❖ Super-Scalar SISD

- ❑ Multiple **Execution Units** (multi-issue pipelines)
  - each EU = ICU+ALU, with shared GR's
- ❑ Hardware + compiler schedules instruction streams



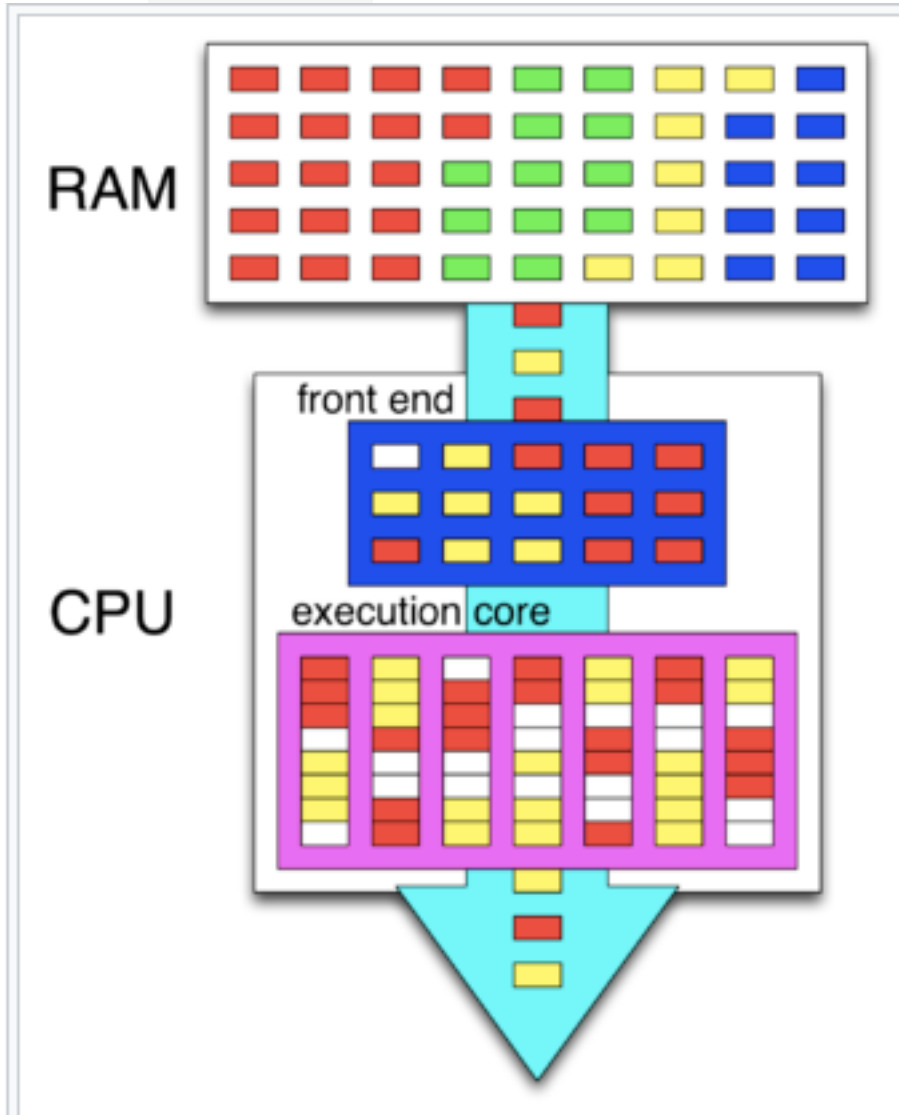
Th1 EU1 pipeline1  
Th2 EU2 pipeline2



Simple superscalar pipeline. By fetching and dispatching two instructions at a time, a maximum of two instructions per cycle can be completed. (IF = Instruction Fetch, ID = Instruction Decode, EX = Execute, MEM = Memory access, WB = Register write back,  $i$  = Instruction number,  $t$  = Clock cycle [i.e., time])

# Hyperthreading

WIKIPEDIA  
The Free Encyclopedia



Virtual **Thread** Machine

Sits on top of Superscalar Multi-cores

In this high-level depiction of HTT, instructions are fetched from RAM (differently colored boxes represent the instructions of four different **processes**), decoded and reordered by the front end (white boxes represent **pipeline bubbles**), and passed to the execution core capable of executing instructions from two different programs during the same **clock cycle**.<sup>[1][2][3]</sup>

Intel's proprietary **HTT**



# Computer Architecture

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## GPU

❖ See more at “GPU” slide set

# Special Processors

❖ MPU → CPU

Processor

❖ GPU

❖ CPU + GPU → APU

Graphics

❖ NPU

Network/Neural Processor

❖ DSP

DSP engine

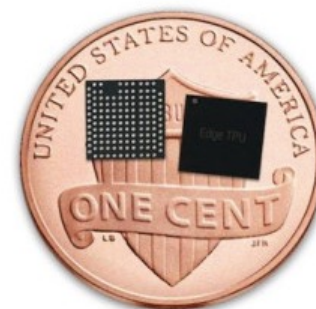
❖ AI: GPU → TPU ??

AI engine

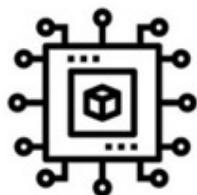
Single FF (1961)



Fairchild's first IC, the "71" element flip-flop compared to a dime coin. Photo: Getty Images



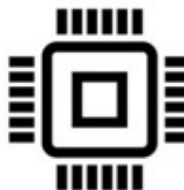
The Edge TPU, shown with a U.S. penny for reference



CPU



GPU



FPGA

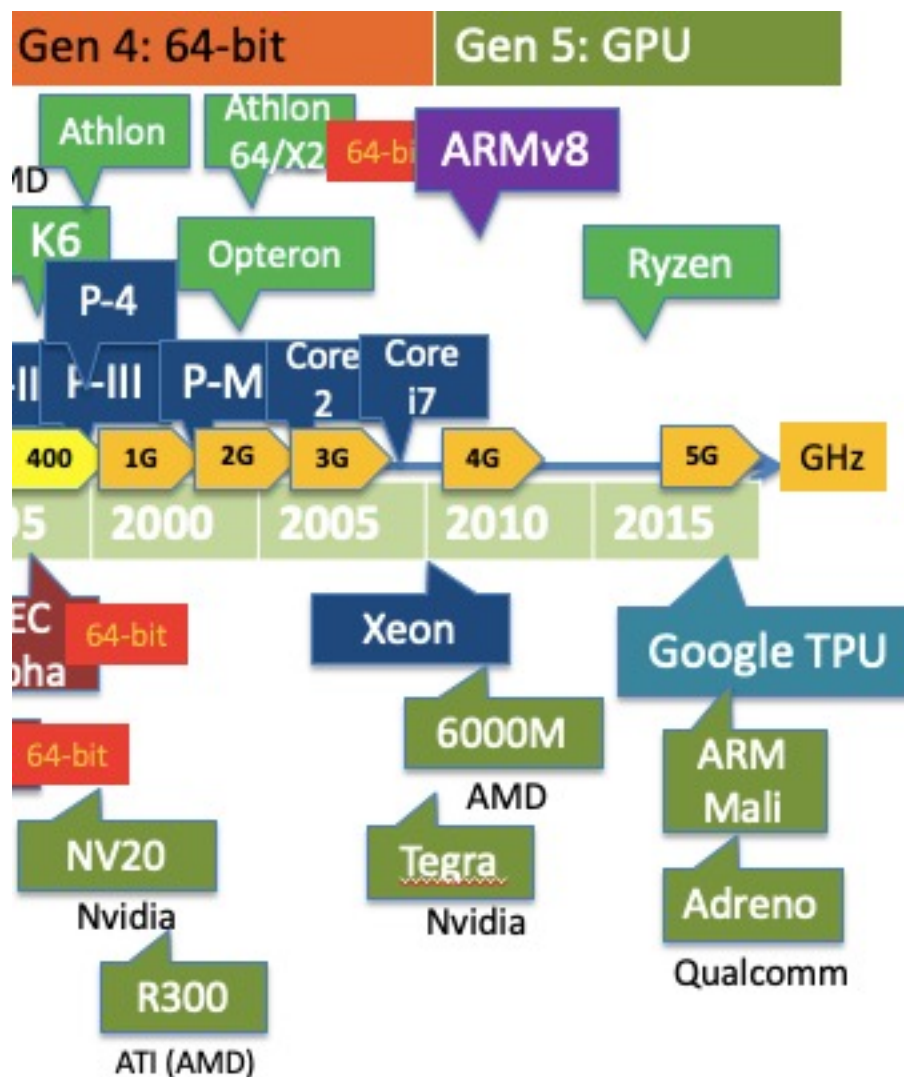


ASIC

FLEXIBILITY

EFFICIENCY

# GPU Timeline



# ARM Mali GPU

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## Mali (GPU)

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From Wikipedia, the free encyclopedia

The **Mali** series of [graphics processing units](#) (GPUs) and multimedia processors are [semiconductor intellectual property cores](#) produced by [ARM Holdings](#) for licensing in various [ASIC](#) designs by ARM partners.

Mali GPUs were developed by [Falanx Microsystems A/S](#), which was a [spin-off](#) of a research project from the [Norwegian University of Science and Technology](#).<sup>[1]</sup> [Arm Holdings](#) acquired Falanx Microsystems A/S on June 23, 2006 and renamed the company to [Arm Norway](#).<sup>[2]</sup>

## Technical details [\[ edit \]](#)

---

Like other embedded IP cores for 3D rendering [acceleration](#), the Mali GPU does not include [display controllers](#) driving monitors, in contrast to common desktop [video cards](#). Instead, the Mali ARM core is a pure 3D engine that renders graphics into memory and passes the rendered image over to another core to handle display.

ARM does, however, license display controller SIP cores independently of the Mali 3D accelerator SIP block, e.g. Mali DP500, DP550 and DP650.<sup>[3]</sup>

ARM also supplies tools to help in authoring [OpenGL ES shaders](#) named *Mali GPU Shader Development Studio* and *Mali GPU User Interface Engine*.

Display controllers such as the ARM HDLCD display controller are available separately.<sup>[4]</sup>



# Mali GPU Timeline

## Variants [\[ edit \]](#)

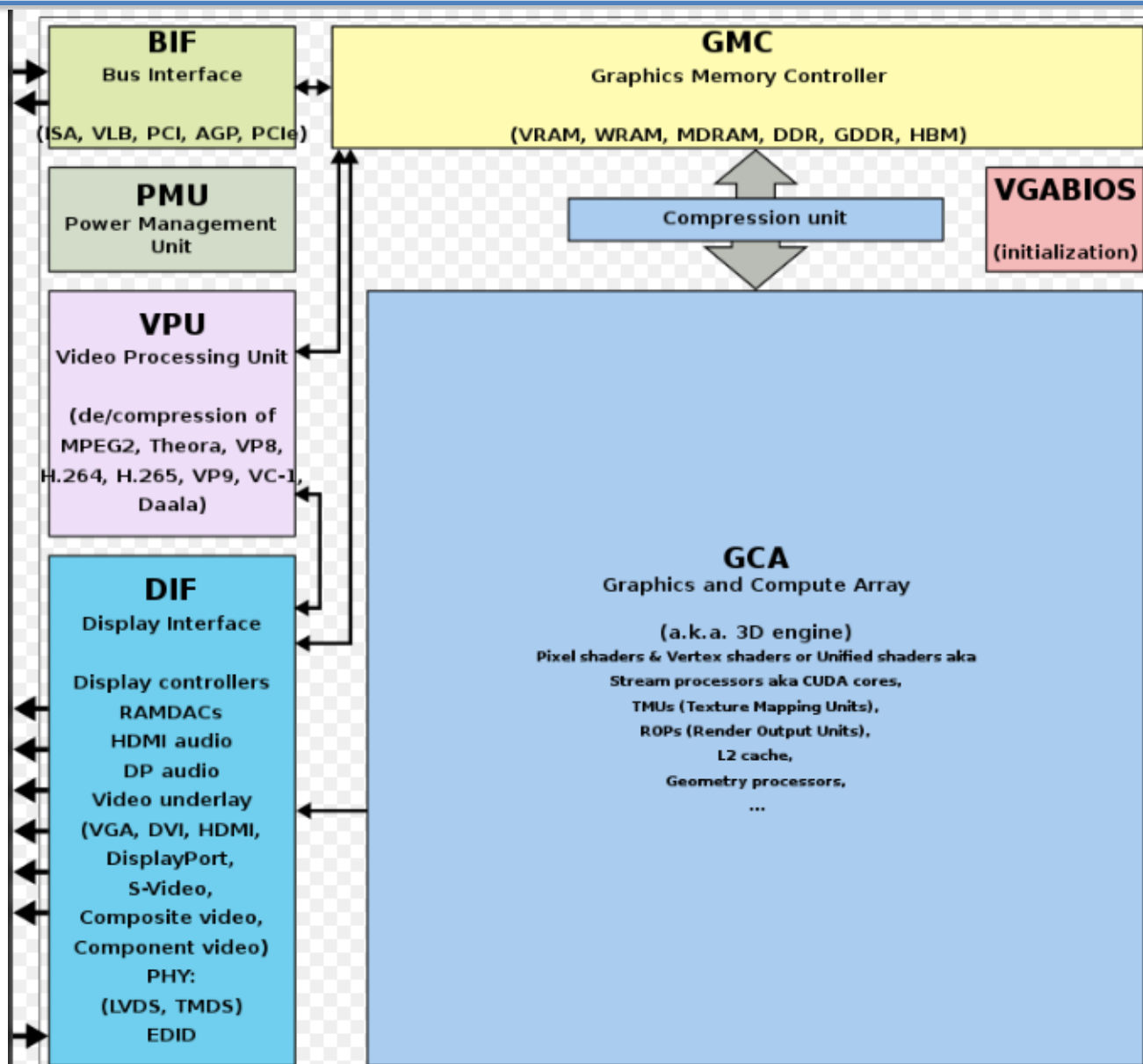
The Mali core grew out of the cores previously produced by Falanx and currently constitute:

Model ↕	Micro- archi- tecture ↕	Type ↕	Launch date ↕	Shader core count ↕	Fab (nm) ↕	Die size (mm <sup>2</sup> ) ↕	Core clock rate (MHz) ↕	L2 cache size ↕
Mali-55/110 <a href="#">↗</a>	?	Fixed function pipeline <sup>[5]</sup>	2005 <a href="#">↗</a> <small>[permanent dead link]</small>	1	?	?	?	N/A
Mali-200 <a href="#">↗</a>	Utgard <sup>[6]</sup>	Programmable pipeline <sup>[7]</sup>	2007 <sup>[8]</sup>	1	?	?	?	N/A
Mali-300 <a href="#">↗</a>			?	1	40 28	?	500	8 KiB
Mali-400 MP <a href="#">↗</a>			2008	1–4	40 28	?	200–600	8-256 KiB
Mali-450 MP <a href="#">↗</a>			2012	1–8	40 28	?	300–750	8-512 KiB
Mali-470 MP <a href="#">↗</a>			2015	1–4	40 28	?	250–650	8–256 KiB
Mali-T604 <a href="#">↗</a> <sup>[9]</sup>	Midgard		?	1–4	32 28	?	533	

# Mali GPU Timeline

Mali-G71 <a href="#">🔗</a>	Bifrost 2 <sup>nd</sup> gen	Unified shader model + Unified memory + scalar, clause-based ISA	Q2 2016	1–32	16 14 10	?	546-1037	128–2048 KiB
Mali-G52 <a href="#">🔗</a>			Q1 2018	1-4 (2 or 3 EU per core)	7 16	?	850	
Mali-G72 <a href="#">🔗</a>			Q2 2017	1–32	16 12 10	1.36 mm <sup>2</sup> per shader core at 10 nm <sup>[29]</sup>	572-800	128–2048 KiB
Mali-G76 <a href="#">🔗</a>			Bifrost 3 <sup>rd</sup> gen	Q2 2018	4-20	12 8 7	?	600-800
Mali-G57 <a href="#">🔗</a>	Valhall 1 <sup>st</sup> gen	Superscalar engine + Unified memory + simplified scalar ISA	Q2 2019	1-6	7	?	?	64–512 KiB
Mali-G77 <a href="#">🔗</a>			Q2 2019	7-16	7	?	850	512–4096 KiB
Model	Micro-architecture	Type	Launch date	Shader core count	Fab (nm)	Die size (mm <sup>2</sup> )	Core clock rate (MHz)	Max L2 cache size

# GPU Architecture



# Phones

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## Phones

\*see slide set on “SoC’s” for phone chips



# Old Palm Pilot Phone



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# 1<sup>st</sup> iPhone

## iPhone

**ANNOUNCED:** Jan. 9, 2007

**RELEASED:** June 29, 2007

**KEY FEATURES:**

3.5-inch diagonal screen;  
320 x 480 pixels at 163 ppi;  
2-megapixel camera

**PRICE:** 4GB model, \$499;  
8GB version, \$599 (with  
a two-year contract)

